

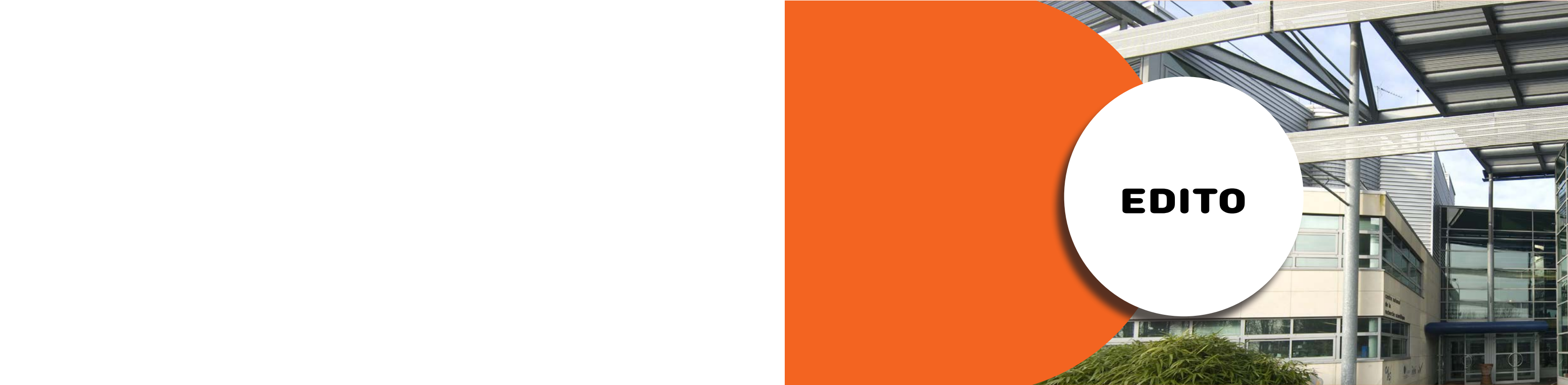


iemn

Institute of Electronics, Microelectronics
and Nanotechnology

UMR CNRS 8520

**Institute of
Electronics,
Microelectronics
and Nanotechnology**



EDITO

IEMN stands for Institute of Electronics, Microelectronics and Nanotechnology. The laboratory, located in the Hauts-de-France region, was created in 1992 to gather, in a unique research structure, disciplines contributing to the progress of electronics, physics, acoustics and their applications. Hence, such an organization was likely to facilitate interdisciplinary research on a wide spectrum of activities ranging from theoretical physics to telecommunication.

Thirty years later after its creation, with the institutional and financial support of five institutions (Lille University, CNRS, JUNIA/ISEN, Centrale Lille Institute and Polytechnic University Hauts-de-France), IEMN has become a major research centre in Micro and Nanotechnology in France, gathering 450 people, including 170 permanent [teacher]-researchers, 90 engineers and technicians, and 140 PhD students.

Today, the core of the institute's activities is centered on micro and nanotechnologies and their applications in the fields of ultra-high data rate communications, technologies for health, energy, transport, internet of things (IoT) and neuromorphic hardware technologies. In order to work on these topics, IEMN researchers have at their disposal exceptional experimental and technical facilities. A large part of the IEMN's research activities are carried out on two platforms, first, the Micro Nanofabrication platform (CMNF) dedicated to the technological fabrication of the next generation of micro-nano-electronic devices and, second, the Multiphysics Characterization platform (PCMP) dedicated to the characterization of materials, devices and systems. As a member of the RENATECH+ network, IEMN has cutting-edge equipment at the highest European level operated by a highly qualified technical staff within the CMNF and PCMP platforms. This facility has been recently supported by the NANOFUTUR Equipex+ program. IEMN is also a member of the GANEXT and STOREX Labex programs, and is a partner of the RS2E network and Graphene European flagships.

IEMN is organized into five scientific departments gathering the 22 research groups of the lab. Since 2020, the governance of the laboratory is assured by a director (Thierry Mélin, CNRS) and two deputy directors (Christophe Delerue, CNRS and Jean-François Robillard, CNRS) assisted by the administration and three councils (namely the Laboratory Council, the Scientific Council and the Technology Council.)

IEMN has numerous national and international collaborations with academic and industrial partners. Middle term joint programs have been established with industrial partners (common laboratories with STMicroelectronics, HCS Pharma and Horiba, Industrial Chair with MC2 Technologies, common IEMN/LEOST cluster). Since 2015, seven start-ups have been created with the support of IEMN by researchers who aim at transferring technological skills capitalized in the framework of research projects to the society in order to improve the daily life by addressing societal challenges.

IEMN is located in several places in Villeneuve d'Ascq, Lille and Valenciennes. The so-called central laboratory in Villeneuve d'Ascq is the largest building gathering the main technological facilities and the institute administration. The other units located on campuses in Lille and Valenciennes are also devoted to research and host numerous equipments allowing a link between the education and research.



Thierry MÉLIN
Director



Christophe DELERUE
Scientific Director



Jean-François ROBILLARD
Director of Technology

The laboratory



Facilities

Micro and NanoFabrication Center (CMNF)

- Deposition and epitaxy unit
- Lithography unit
- Etching unit
- Characterisation unit
- Bio/microfluidic unit
- Packaging unit

Multi-Physics Characterization Platform (PCMP)

- PCP : Scanning Probe Microscopy
- CHOP : Microwave, Optical and Photonic Characterization
- SIGMACOM : Communicating Systems Characterization & Prototyping
- C2EM : Electromagnetic Characterization and Compatibility & Prototyping

The laboratory

The Institute for Electronics, Microelectronics and Nanotechnology has been created in 1992 with the support of three regional partners: The University of Lille (ULille); the University of Valenciennes and Hainaut Cambr sis (UVHC); YNCR A ISEN and CNRS (National Center for Scientific Research), a government-funded research organization, under the administrative authority of France's Ministry of Research and Higher Education. The main objective was to gather, in a unique research structure, disciplines contributing to the progress of electronics, acoustics and their applications. Hence, such an organization was likely to facilitate interdisciplinary research on a wide spectrum of activities ranging from theoretical physics to telecommunication. Twenty-five years later, IEMN has increased in scope, doubled its staff, its budget is four times higher than at the beginning and we can claim that original objectives are fulfilled.

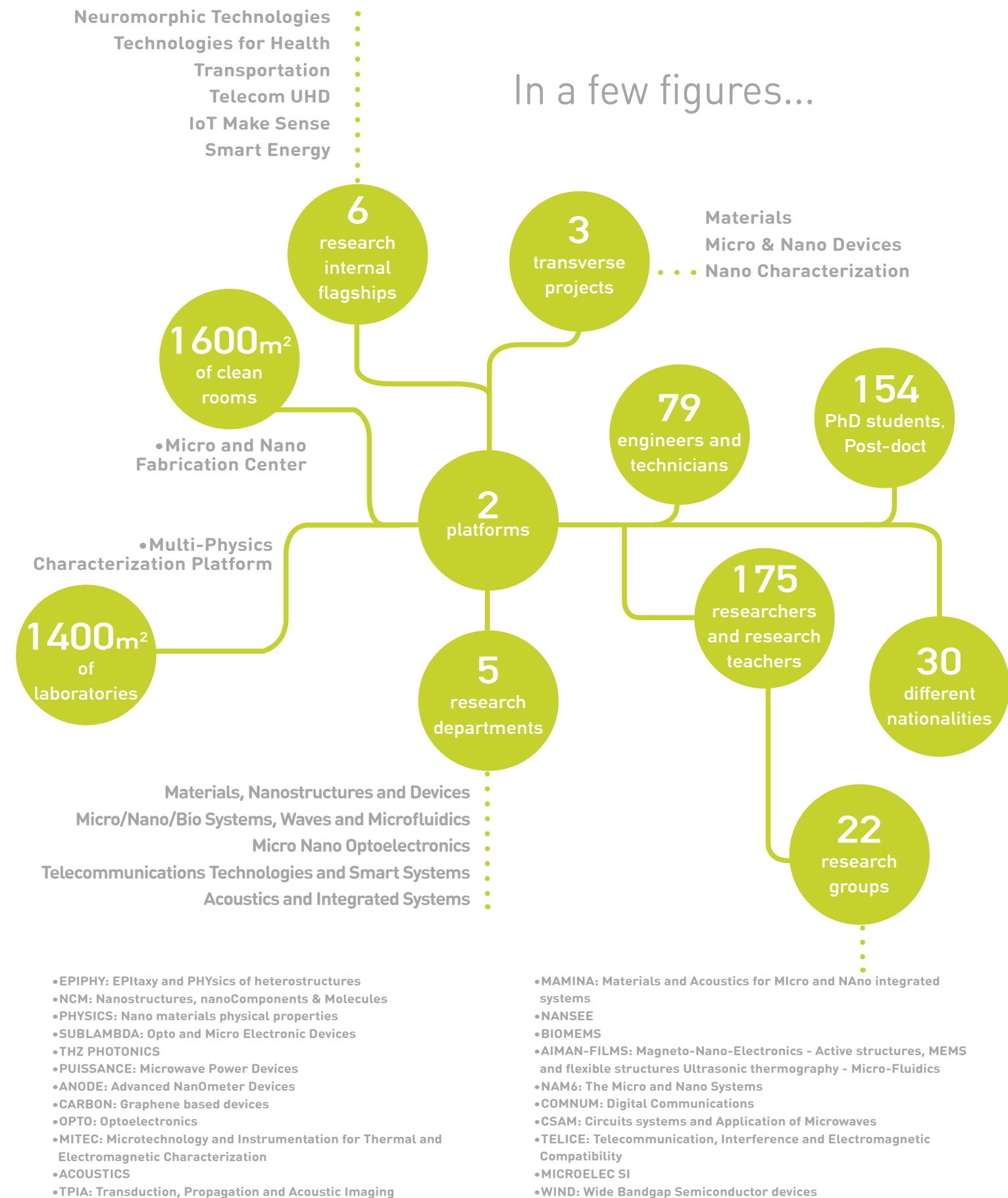
Today, nearly 450 people work together in a scientific field ranging from information and communication technologies to micro and nano technologies. The scientific policy of the laboratory is determined within research groups and five research departments promote emerging activities. Middle term joint programs with industrial partners or other national institutions and long-term research initiatives stimulate the resourcing of our research projects. Thanks to the constant financial support of the Hauts de France Regional Council combined with those of our trustees, IEMN

features exceptional technical facilities. As a member of the Basic Technological Research Network (BTR RENATECH) with four other CNRS laboratories involved in micro and nano fabrication, IEMN offers to the scientific community a technical platform ranking among the best in Europe. IEMN is strongly involved in IRCICA, the Institute for Advanced Communication, where IEMN research groups work together with researchers from software and physics background.

In 2015, IEMN has been asked to work with the Laboratoire d'Electrotechnique et d'Electronique de Puissance (L2EP) on a project of integration. After a few meetings at the board of direction scale and an introduction made by L2EP to IEMN, a task force has been settled in order to identify existing common studies. Scientific committees of both laboratories have been committed to establish a joint scientific project. The outcome was presented and it has been decided to pursue the process during the next period. A joint text has been written and it presented in the project section of this report.

IEMN is located in several buildings in Villeneuve d'Ascq, Lille and Valenciennes. The so-called central laboratory is the largest building and it regroups all the main technological facilities and the institute administration. The other units located on the ULille, UVHC campus and in Lille YNCR A ISEN building are also devoted to research and host various equipments allowing us to make a link between the education at master and engineer levels and research.

In a few figures...





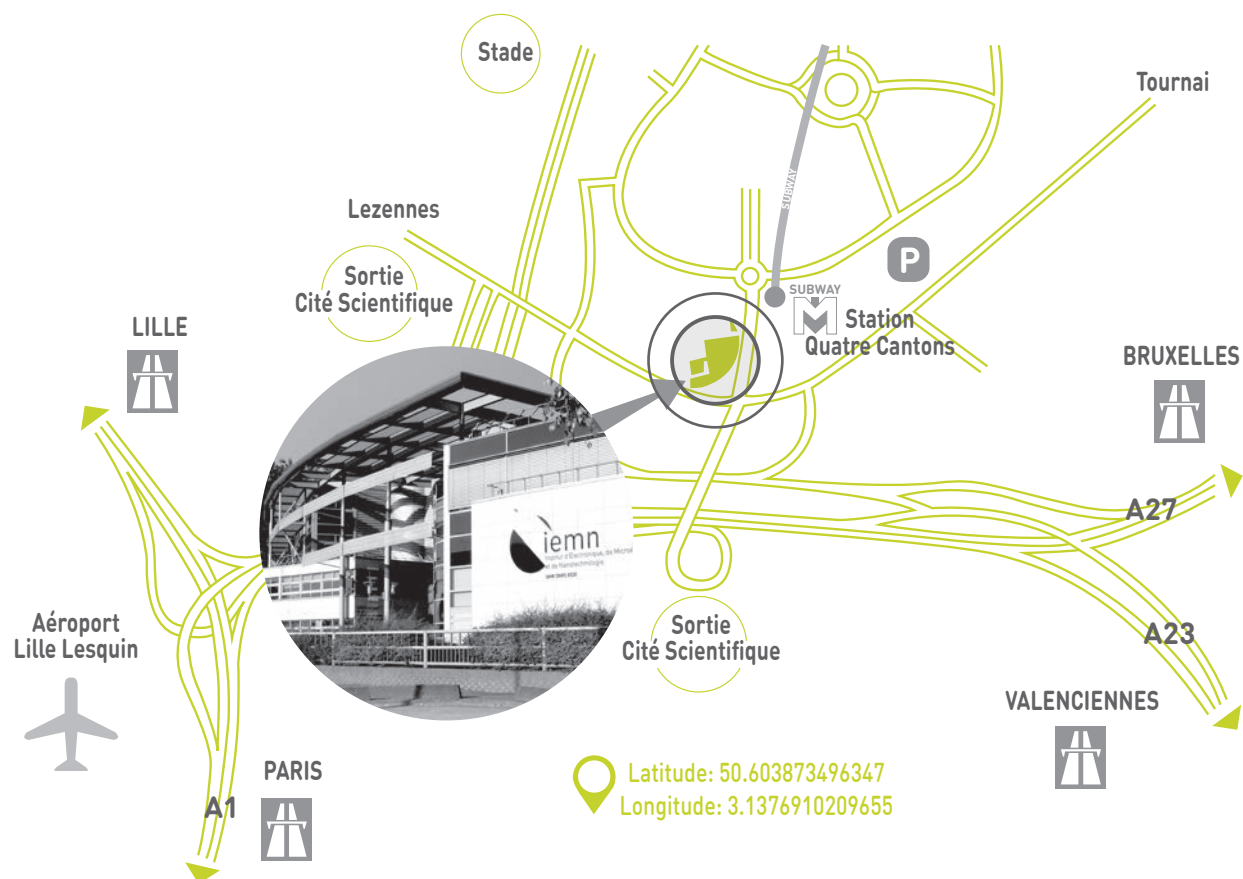
IEMN

Cité Scientifique

Avenue Henri Poincaré - CS 60069

59652 Villeneuve d'Ascq Cedex, France

Tel +33 (0)3 20 19 79 79



By train

- From the "Lille Flandres" SNCF station
Take the metro line 1 → direction 4 Cantons and get off at the station "4 Cantons".
- From the "Lille Europe" SNCF station
Take the metro line 2 → direction St Philibert, change at Lille Flandres station.
Then take line 1 → direction 4 Cantons and get off at "4 Cantons" station.
- At the exit of the "4 Cantons" metro station → turn left and walk up Avenue Poincaré for about 150m. You are now at the IEMN.



By plane

- Lille-Lesquin airport is linked to the centre of Lille by shuttle bus (indicative journey time: 20 minutes).
- The shuttle bus stop in the airport is located in front of the arrivals hall.
 - In Lille, it is located in rue Corbusier, Centre Eurallile.



By car

- Coming from Lille, Paris, Valenciennes or Brussels → take the direction Gent and exit at Cité Scientifique. You are on the Lille1 campus.
- Coming from Gand → take the direction of Paris and exit at Cité Scientifique.



The Technology Council

(chaired by the Deputy Director, Head of the Technology)

17 members

It has an advisory role and gives its opinion on the investments to be made, the technological orientations, the functioning and the animation of the platforms in general. Its mission is to define the future technological orientations of the laboratory which will condition the investment policy of the laboratory.



Deputy Director
Technological Direction
Jean-François ROBILLARD



The Laboratory Council

(chaired by the Director)

The laboratory council is consulted on all the major orientations concerning the scientific life, the functioning, the administration, the management of human resources and the internal regulation of the laboratory.



Director
Thierry MÉLIN



The Scientific Council

(chaired by the Deputy Scientific Director)

16 members

It is consulted on any question related to the scientific policy of the laboratory. It suggests actions of scientific animation, ensures an active scientific and technological watch, proposes strategic scientific orientations, and contributes to the scientific communication of the laboratory.



Deputy Director
Scientific Direction
Christophe DELERUE



Head of Central Micro and Nano -
Fabrication Center (CMNF)
François VAURETTE



Coordinator Multi - Physics
Characterization Platform (PCMP)
Sylvie GODEY



Management
Administrative
and Financial
Frédéric LEFEBVRE



Director of
Education Relations
Sylvain BOLLAERT



Nanostructures and
Components Department
Ludovic DESPLANQUE



Micro/nano/biosystems, waves and
microfluidics department
Nicolas TIERCELIN



Micro, Nano and
Optoelectronics Department
Mohammed ZAKNOUNE



Telecommunications technologies
and intelligent systems
Iyad DAYOUB



Acoustics and
integrated systems
Jérôme VASSEUR



Facilities

CMNF
Micro and
NanoFabrication
Center

PCMP
Multi-Physics
Characterization
Platform



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and Nanotechnology

UMR CNRS 8520

Micro and Nano Fabrication Center

CMNF Centrale de Micro Nano Fabrication

IEMN stands for Institute of Electronics, Microelectronics and Nanotechnology, a laboratory created in 1992 by five institutions: Lille University, Polytechnic University hauts-de-france, JUNIA/ISEN, Ecole Centrale Lille and CNRS. IEMN's research is performed based on a strong connection between its technical (Micro Nanofabrication and Multi Physics PlatForm PCMP) where cutting-edge equipments are operated by a highly qualified technical staff.

The scientific policy of the Institute is declined in five research Departments:

- Materials, Nanostructures and Devices
- Micro/Nano/Biosystems, Waves and Microfluidics
- Micro, Nano and Optoelectronics
- Telecommunications Technologies and Smart Systems
- Acoustics and Integrated Systems

Materials, Nanostructures and Devices

EPIPHY: EPItaxy and PHYsics of heterostructures
NCM: Nanostructures, nanoComponents & Molecules
PHYSICS: Nano materials physical properties
SUBLAMBDA: Metamaterials and metasurfaces for wave control

Micro, Nano and Optoelectronics

THZ Photonics
PUISSANCE: Microwave Power Devices
ANODE: Advanced Nanometer DEvices
CARBON: Graphene based devices
OPTOelectronics
BioMEMS

Micro / Nano / Biosystems, Waves and Microfluidics

AIMAN-FILMS: Magneto-Nano-Electronics - Active structures, MEMS and flexible structures Ultrasonic thermography - Micro-Fluidics

NAM6: The Micro and Nano Systems

Telecommunications Technologies and Smart Systems

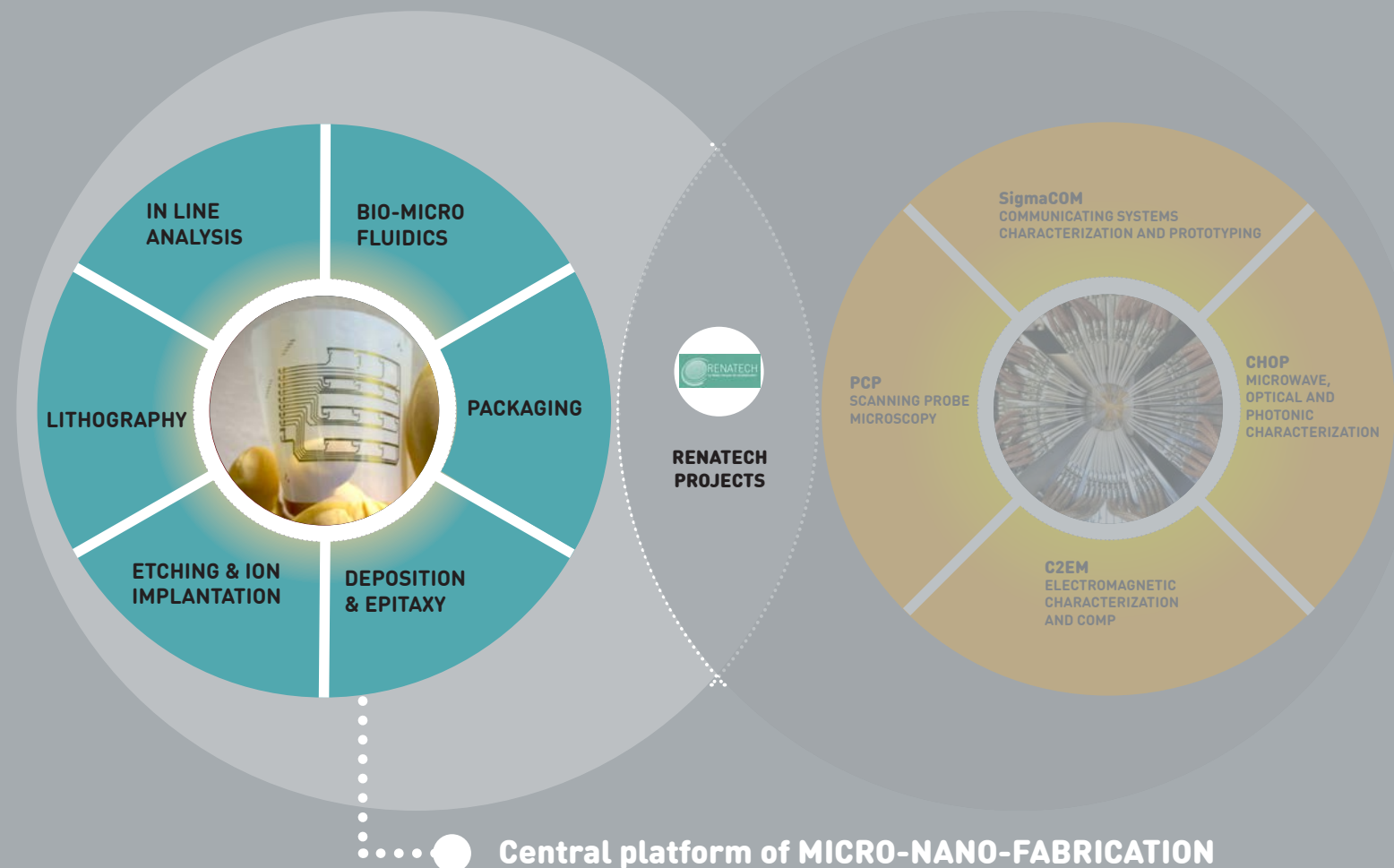
COMNUM: Digital Communications
CSAM: Circuits systems and Application of Microwaves
TELICE: Telecommunication, Interference and Electromagnetic Compatibility

Acoustics and Integrated Systems

Acoutics
TPIA: Transduction, Propagation and Acoustic Imaging
MAMINA: Materials and Acoustics for Micro and NAno integrated systems
MICROELEC SI

At the forefront of education and technological research, and owing to numerous dynamic international collaborations, IEMN hosts PhD and graduate students coming from 30 different countries. Nearly 500 people work in IEMN fields of research, mainly Information Communication Technology and Nanotechnology. IEMN's devices can be found in Electronics, Energy, Biotechnologies, Sensors and Instrumentation applications. Moreover, as evidenced by numerous patents plus spin-off's creations, IEMN demonstrates its efficiency in promoting and facilitating technology transfer of innovations emanating from its research groups.

Central platform of MICRO-NANO-FABRICATION



IEMN's micro and nanofabrication facility is a 1600 square meter ISO6 certified cleanroom, 250 m² of packaging and 100 m² (L2) for Biology. Organised into six technological units: deposition and epitaxy, lithography, etching, integration, bio-microfluidics, in line analysis and one unit of maintenance, the facility is equipped with a full line of cutting edge technological tools supporting device fabrication.

Primarily conceived as an electronics-based research facility, IEMN's clean room is now renowned as a multidisciplinary facility allowing state of the art device and advanced system fabrication in many research fields ranging from photonics to bioMEMS or acoustics. 30 high skilled engineers and technicians work full time to support the research activities and collaborative projects aiming at exploring uses of micro and nanofabrication. The IEMN micro and nanofabrication facility steadily aims to be at the best international research level in micro and nanotechnology to efficiently support academic institutions and companies that require the use of its large clean-room infrastructures. Thus, IEMN is part of RENATECH, the french national network of large technological facilities, that is an integrated partnership of 5 CNRS laboratories in the field of micro nanotechnologies. RENATECH facilities are opened to both academic and industrial partnerships. In this context, IEMN hosts innovative projects in the best possible conditions by sharing and providing the most advanced know-how in the micro and nanotechnology fields through an access to high technology equipment, staff expertise as well as required training support.



I DEPOSITION & EPITAXY Unit	
• Molecular Beam Epitaxy	I. 1-2
• Organic Chemistry	I. 3-4
• Chemical Vapor Deposition	I. 5-8
• Physical Vapor Deposition	I. 9-10
• Alternative Deposition & Heat Treatment	I. 11-12
II LITHOGRAPHY Unit	II. 1-6
III ETCHING & ION IMPLANTATION Unit	
• Plasma	III. 1-2
• Chemical	III. 3-4
• Ion beam	III. 5-6
IV IN LINE ANALYSIS Unit	IV. 1-6
V PACKAGING Unit	V. 1-10
VI BIO-MICRO FLUIDICS Unit	
• Soft Lithography	VI. 1-2
• Bio Micro Fluidic	VI. 3-7

DEPOSITION & EPITAXY

unit

MOLECULAR
BEAM
EPITAXY

Materials engineering process refers to fabrication or modification of materials. The aim is to obtain materials with specific structure, properties and performances depending on the application.
1 Full Time Employee



Deposition Manager : Isabelle Roch
★ Permanent staff : Chiara Crivello • Marc Dewitte
• David Guérin • Carlos Moncasi Luque
Non permanent staff : Marie Philippe
Epitaxy Manager : Christophe Coinon
Non Permanent staff : Paul Moustiez



MOLECULAR BEAM EPITAXY

• **Christophe Coinon**

Molecular beam epitaxy (MBE) is a technique to growth crystalline overlayers and heterostructures on a crystalline substrate using atomic or molecular beams. These beams are produced by heating high purity solid source materials or by cracking very pure gases under ultra high vacuum, that then condensate on the substrate.

- Up to 3 inch wafer
- Around 200 epitaxial growths per year

Epitaxial growth of TMDC

• MBE VINCI Technologies reactor

- Effusion cells : Ga, In, Se
- Valved cracker : Se
- Linear UHV E-Beam source : Ta, W, Mo, Hf, Nb, Zr
- Up to 3 inch substrates
- RHEED up to 15 KV

Epitaxial growth of Graphene and BN

• MBE RIBER Compact 21

- Carbon, boron & silicon solid sources
- Borazine B₃N₃H₆ gas source
- N₂ valved RF plasma source
- Sample holder heating T ≤ 1500°C
- In-situ characterisation by RHEED
- Coupled under UHV with a surface analysis chamber fitted with LEED and Auger spectroscopy

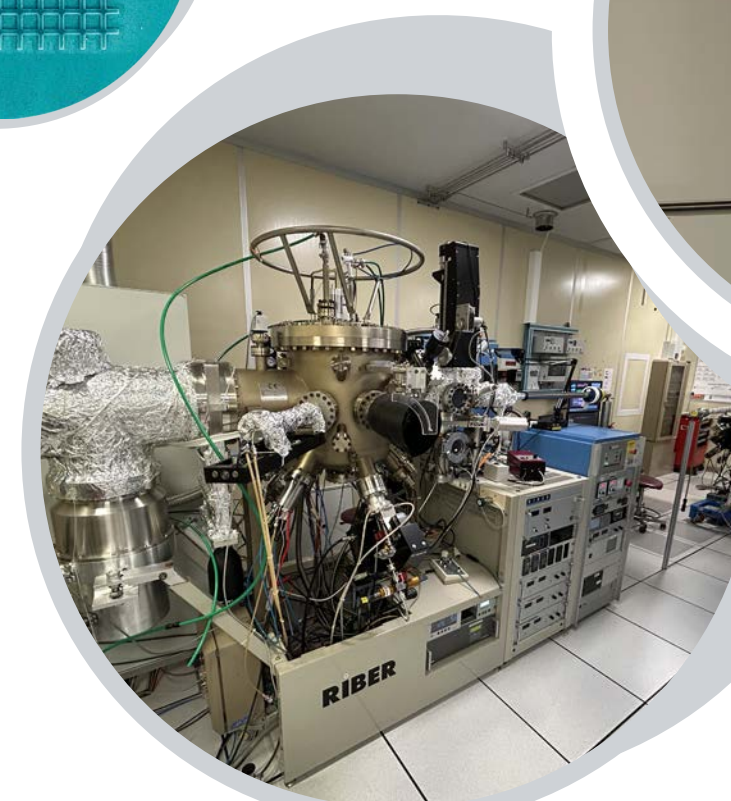
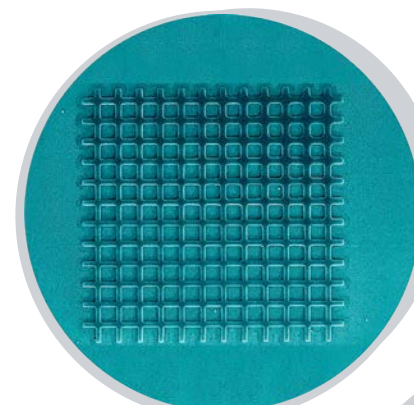
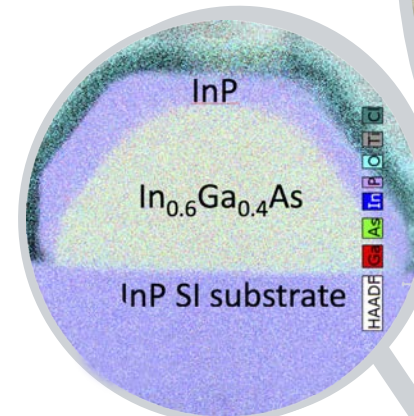
• Epitaxial growth of III-V semiconductors

• RIBER COMPACT 21DZ

- Effusion cells : Ga, Al, In, Si, Be
- Gas injectors : CBr₄
- Valved crackers : As, Sb, P
- Growth on 2 and 3 inch substrates
- RHEED up to 15 KV
- Temperature measurement by band edge thermometry (Bandi T)
- Real-Time Curvature Measurement (EZ-Curve)

• RIBER COMPACT 21T

- Effusion cells : Ga, Al, In, Si, Be, Fe
- RF Plasma source : H
- Valved crackers : As, Sb
- Growth on 2 and 3 inch substrates
- RHEED up to 35 KV





CHEMICAL SYNTHESIS & SURFACE FUNCTIONALIZATION

Manager: David Guérin

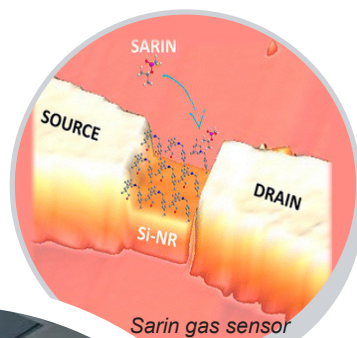
This laboratory is dedicated to chemical synthesis of molecules or materials designed for electronics or nanobiotechnologies. The main activity of the lab concerns the surface functionalization by molecules or by organic thin films. Self Assembled Monolayer technique (SAM) is used to provide specific physico-chemical properties to various surfaces, such as optical or electronical properties, wettability, encapsulation or specific chemical reactivity. Synthesis and grafting of nanomaterials on different substrates are also performed.

Synthesis under inert atmosphere

- Nitrogen glove box
- Schlenkware
- Vacuum / nitrogen manifold

Purification of solvents and organics

- Kugelrohr ovens
- Flash Chromatography
- Distillation
- Rotavapor
- Centrifuge



ORGANIC PLATFORM

Manager: David Guérin

Associated with the laboratory of organic chemistry, the organic platform is dedicated to the preparation of molecular and organic devices. Two connected glove-boxes (M-Braun model, O_2 and H_2O level < 1 ppm) permit to deposit on a substrate various organic materials (self assembled monolayers by surface chemistry or polymers by spin coating) then other organics or metals can be evaporated on-line (by joule effect at 10^{-7} mbar) without any contact with atmosphere.



Vacuum / nitrogen manifold



In addition of usual organic chemistry glassware, the lab is equipped with specific apparatuses for manipulation under inert atmosphere (schlenkware, vacuum/ N_2 manifolds, glove box). Solvents, chemicals or nanoparticles can be purified by various equipments (distillation apparatus, Kugelrohr oven, rotavapor, flash chromatography, centrifuge).



Rotavapor



Kugelrohr oven



Flash chromatography

DEPOSITION & EPITAXY

unit
CHEMICAL
VAPOR
DEPOSITION



Deposition Manager : Isabelle Roch
Epitaxy Manager : Christophe Coinon

CVD is a range of techniques where a substrate is exposed to gaseous sources which react with its surface to deposit or to grow thin films of high purity, density and uniformity.



ATOMIC LAYER DEPOSITION



Manager: Chiara Crivello

2nd Managers: Marie Philippe & Isabelle Roch

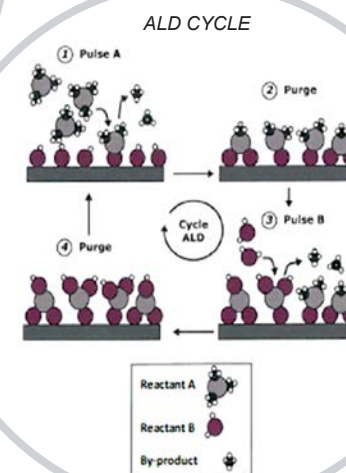
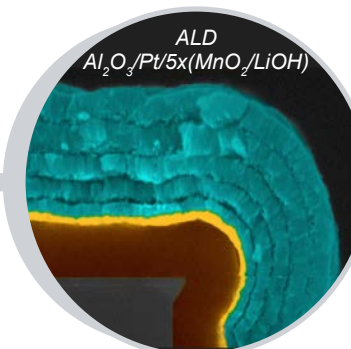
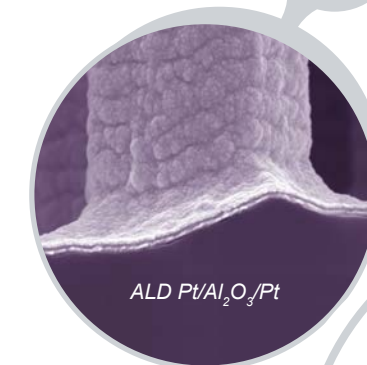
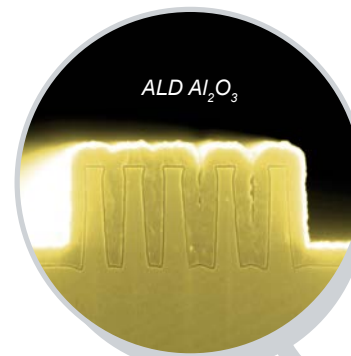
Atomic Layer Deposition (ALD) is an advanced thin film coating method which is used to fabricate ultrathin, highly uniform and conformal material layers.

- Up to 8 inch wafer
- Available materials: Al_2O_3 , NiO, Ta_2O_5 , TaN, Pt, Ag, LiOH, MnO_2 , Li_2MnO_3 , SiO_2 , Li_3PO_4

→ 2 ALD PICOSUN - R200 advanced

Through-porous and HAR samples

- Precursors: 2 or 3 liquid sources, 3 or 4 solid sources, 5 gases for plasma, ozone
- 2 Process chambers
- Mono layer growth control
- 2 glove boxes (N_2 , Ar)
- Process temperature 50-400°C
- 1 ellipsometer in situ (PICO 2)



AP-CVD and LP-CVD



Manager: Marie Philippe

2nd Managers: Carlos Moncasi Luque & Isabelle Roch

APCVD (Atmospheric Pressure Chemical Vapor Deposition) and LPCVD (Low Pressure Chemical Vapor Deposition) refer to chemical and thermal processes used to deposit high purity thin layers with a good uniformity.

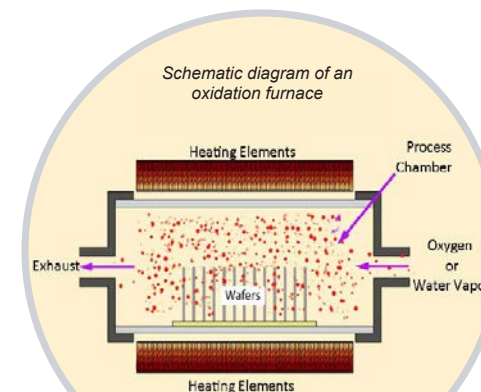
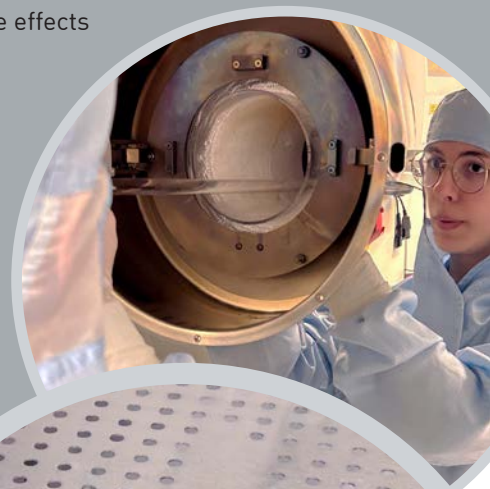
- Up to 4 inch wafer
- 5 process tubes
- Gas: O_2 , H_2 , SiH_4 , PH_3 , BCl_3 , SiH_2Cl_2 , NH_3 , N_2 , Ar

2 APCVD Tempress Furnaces

- 2 APCVD tubes for thermal oxidations of silicon wafers up to 1100°C with O_2 gas (dry oxidation) or H_2O vapor (wet oxidation) at atmospheric pressure.
- Thickness: from 2 nm up to 2 μm
- Applications: insulation, passivation, smoothing of side effects after plasma etching

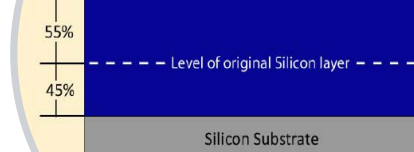
3 dedicated LPCVD tubes (dry pumps)

- Polycrystalline silicon ($\leq 600^\circ\text{C}$) and in-situ phosphorus doped polysilicon (650 to 750°C)
 - thickness up to 2 μm
- Low Temperature Oxide (SiO_2 deposition at 420°C),
 - thickness up to 5 μm
- Low stress (Si_xN_y) or stoichiometric (Si_3N_4) silicon nitride, 800°C
 - thickness up to 1 μm
- Applications → insulation, passivation, p-n junction



APCVD
Silicon dioxide growth into a silicon wafer

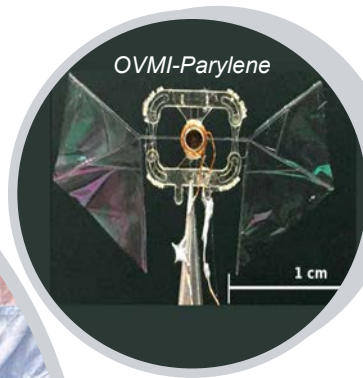
Silicon Dioxide Growth



DEPOSITION & EPITAXY

univ
CHEMICAL
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DEPOSITION

Deposition Manager : Isabelle Roch
Epitaxy Manager : Christophe Coinon



PARYLENE CVD

Manager: David Guérin

Parylene thin film : COMELEC C20S

Parylene is the trade name for chemical vapor deposited poly(p-xylylene) polymer series.

Parylene C, available.

Room temperature conformal depositions on a wide range of materials and shapes.

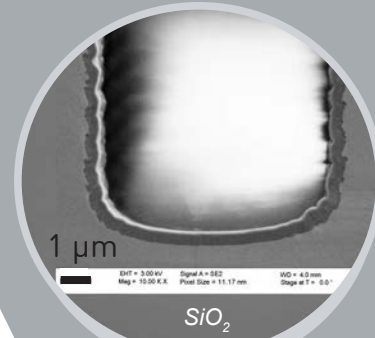
Room temperature deposition (3 steps):

- Vaporisation of the solid dimer
- Pyrolysis of the dimer to yield the monomeric diradical
- Simultaneous adsorption and polymerisation of the monomer on the substrate (at room temperature)

Thickness ranging from 50 nm to 20 μm

Characteristics of Parylene / fields of interests:

- Excellent electrical insulator / dielectric layer
- Biostable/biocompatible
- Highly conformal coating, homogeneous surface
- Very low permeability to gases
- Highly resistant to chemicals
- Device encapsulation/ Surface passivation or functionalization
- Shadow masks/ flexible substrates
- Bonding layers



PLASMA - ENHANCED CVD

Manager: Carlos Moncasi Luque
2nd Managers: Chiara Crivello

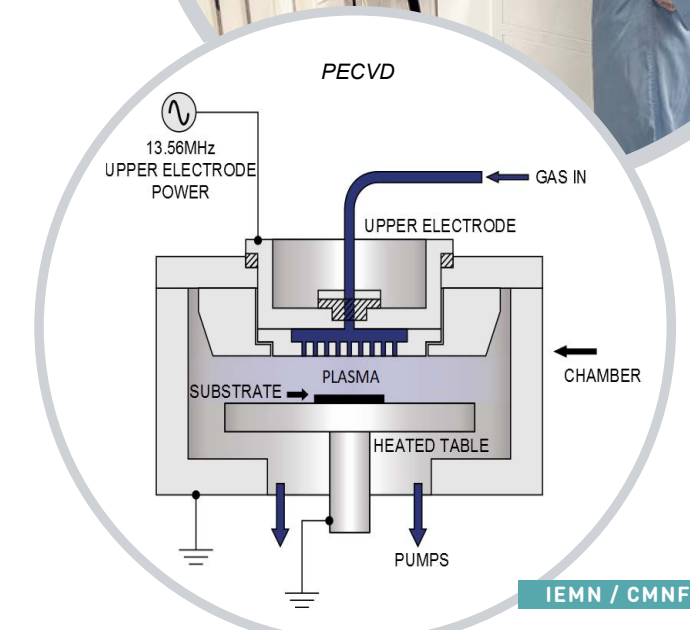
Plasma-Enhanced Chemical Vapor Deposition is a technique that uses a RF plasma to deposit thin films at a milder temperature than other CVD techniques.

KLA Delta 200

- Deposition of silicon oxide (silane or TEOS based), silicon nitride (with or without NH_3), silicon oxynitride and amorphous silicon.
- Film stress tuning with high and low frequency mixing techniques (SiN and TEOS based SiO_2)
- 2 RF sources: HF 13.56 MHz and LF 300-500 kHz
- Gas: SiH_4 , NH_3 , N_2O , N_2 , H_2 , TEOS, C_3F_8 , O_2 , He
- Deposition temperature: 80 to 350°C
- 7 to 470 nm/min
- Deposition rate: 7 to 470 nm/min via filling and high aspect ration deposition with TEOS SiO_2 .

Oxford Plasmalab 80 plus

- Deposition of: silicon oxide, silicon nitride and silicon oxynitride
- Film stress tuning with mix high and low frequency techniques
- 2 RF sources HF 13.56 MHz and LF 50 to 400 kHz
- Gas: SiH_4 5% in N_2 , NH_3 , N_2O , N_2 , He, CF_4 / 20% O_2 and O_2
- Deposition temperature: between 100 to 340°C
- Deposition rate: between 100 to 800 $\text{\AA}/\text{min}$



DEPOSITION & EPITAXY

unit
PHYSICAL
VAPOR
DEPOSITION

Deposition Manager : Isabelle Roch
Epitaxy Manager : Christophe Coinon

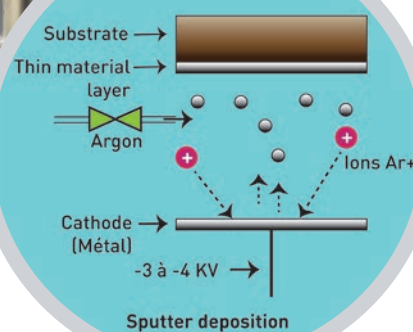
In PVD processes, a solid source is vaporised to generate a gas phase that will condense and form a thin film on a substrate.

More than 3000 depositions per year (Metal, Dielectric material, Magnetic layer)

SPUTTERING SYSTEMS

The sputtering method involves ejecting material from a "target" onto a substrate by energetic ion bombardment:

- Up to 4" wafer
- 6 deposition process chambers



Manager : Isabelle ROCH
2nd Manager: Carlos Moncasi Luque

ALLIANCE CONCEPT CT 200 CLUSTER

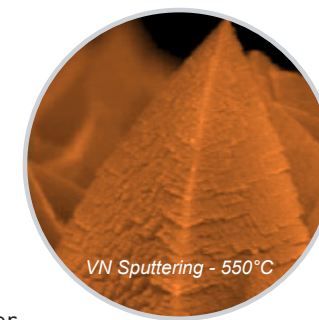
- 14 cathodes, 3 chambers, fully automated sputtering cluster
- **Applications** → single or multi-layers processes, reactive sputtering, co-sputtering
- Realisation of complex structures without vacuum break and cross-contamination of chambers

	Chamber 1 Magnetic Multilayers/Metals (Cu, Au, Pt...)	Chamber 2 - Materials for storage energy (LMNO, WN, VN, LiPON, LFP...)	Chamber 3 - Photovoltaic materials
CHARACTERISTICS	• 6 x 2" magnetron cathodes • Confocal sputtering • 2 pulsed-DC source and 2-RF sources • Cold or heated (400°C) substrate with rotation for uniformity over 4" • Reactive sputtering of nitrides is possible • Gas: Ar, N₂	• 4x 4" (3" also available) cathodes in planar mode • 1 pulsed DC and 1 RF power source • Cold or Heated (800°C) substrate holder • Gas: Ar, N₂, O₂	• 3x 2" magnetron cathodes in confocal mode + 1x 4" magnetron target in planar mode. • 1 pulsed DC, 1 DC and 1 RF source • Heated (400°C) substrate holder • Rotation for uniformity over 4" • Gas: Ar, N₂, N₂/5%H₂

Managers: Carlos Moncasi Luque & Isabelle Roch

ELETTORAVA SPUTTERING

- Automatic cassette load-lock (6 holders)
- 12 targets (3 x 4 confocal 100 mm cathodes)
 - HiPIMS station : ↑ density, ↑ adhesion
 - Pulsed DC station
 - RF station
- Reactive sputtering : Ar, N₂, O₂
- Deposition temperature up to 600 °C
- ICP etching station (Pmax : 1000 W)
- Non-uniformity deposition on 4" wafer < 5%



Manager: Marc DEWITTE

ALLIANCE CONCEPT DP650

- Cold or heated (750°C) substrate holder
- 6 DC and RF cathodes 4"
- Powered with 1 DC pulse, 1DC and 1RF source
- Deposited materials : Au, Ni, Pt, WTi, TiNi, W, Ta, NiCr, NiCu, TiN, TiC, Fe, Al, Mo, Cu, TaN, Ti, Si, SiO₂, ZnO

Manager: Nicolas TIERCELIN

LEYBOLD Z550

- 1 cathode 6" and 4 cathodes 4" RF and DC
- Magnetic layer deposition
- TbFe₂, TbCo₂, TbFeCo, FeCo, Fe, Co, CoPt, FePt, Ta, Cr

EVAPORATION BY ELECTRON BEAM

Manager: Marc Dewitte

2nd Manager: Isabelle Roch

The heat is provided by a focused beam of high energy electrons.

2 PLASSYS MEB 550S

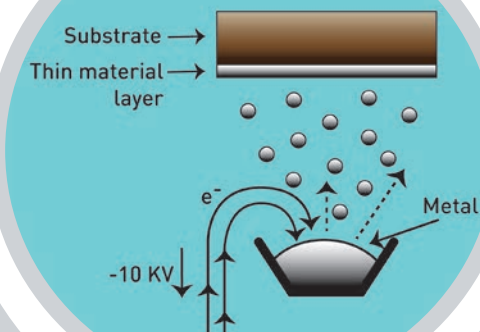
- Load lock with substrate treatment (ion beam source 3cm)
- Capacity : 4 substrate holders 4"
- Materials: Au, Ti, Ge, Al, Pt, Ni, Mo, Cr, Pd, Ag

1 PLASSYS MEB 550SL

- Load lock with O₂ treatment
- Ion beam in chamber
- Capacity : holder 6"
- Materials : Ti, Ni, Cr, Al, Au, Pt, Pd, Ge



e-beam Evaporation

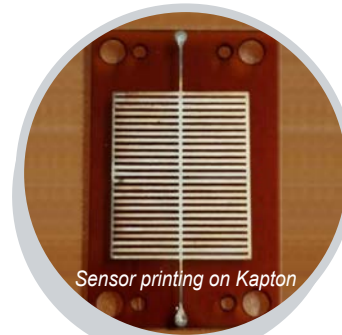
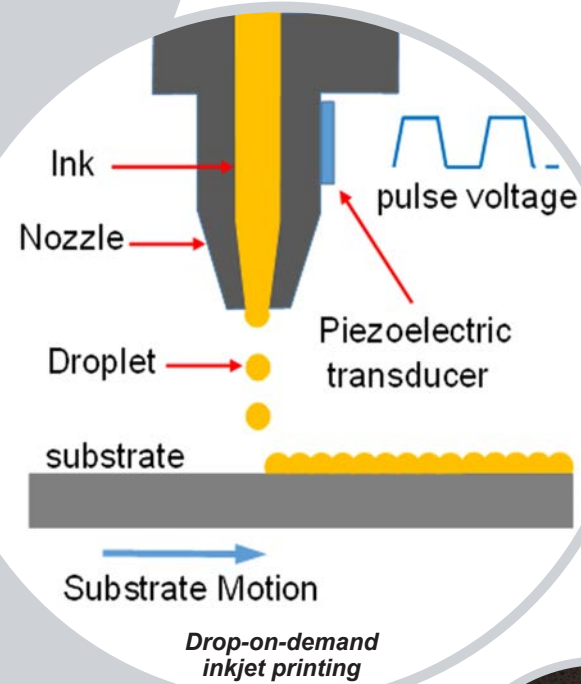


DEPOSITION & EPITAXY

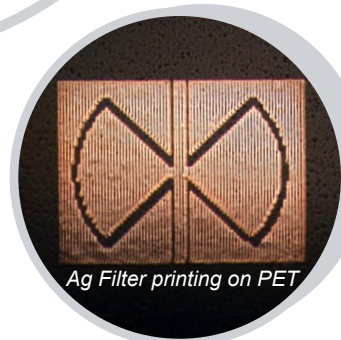
Unit

Alternative
Deposition & Heat
Treatment

Deposition Manager : Isabelle Roch
Epitaxy Manager : Christophe Coinon



Sensor printing on Kapton



Ag Filter printing on PET

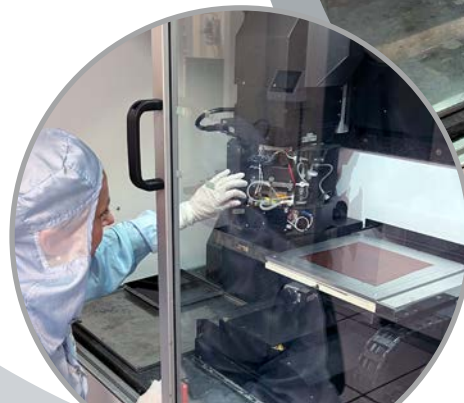
INKJET PRINTING

Manager: Isabelle Roch

Powerfull digital materials deposition systems for printing of functional materials: printing onto rigid and flexible substrates

Ceradrop X-Series Inkjet printer

- 2 Dimatix Printhead (128 Nozzles each)
Diameter of nozzles 35 μm
- 1 Mono nozzle printhead
Diameter of Nozzle 20 μm , 30 μm or 35 μm
- 1 IR Dryer
- Printing with silver nanoparticles ink, biopolymer solutions and carbon ink



HEAT TREATMENT

Manager: Marc Dewitte

2 RTA (rapid thermal annealing)

JIPELEC JETFIRST 200

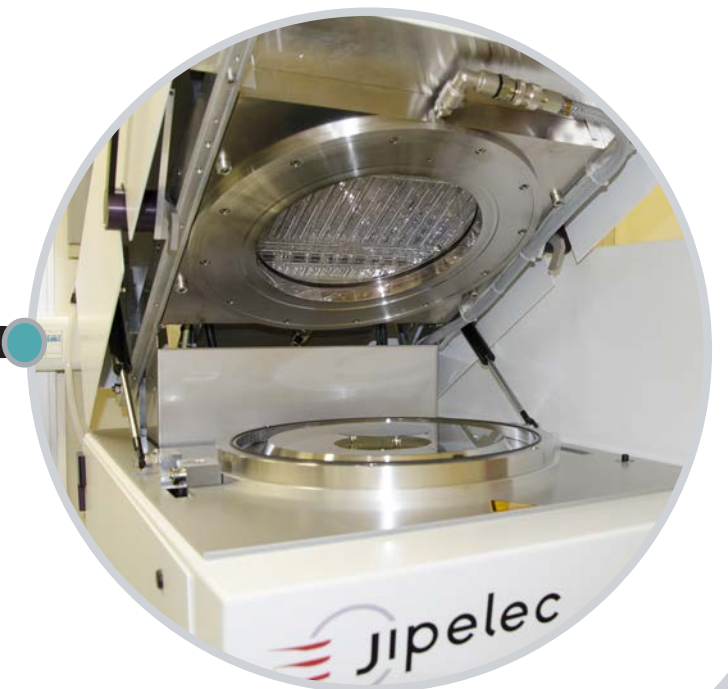
- Range of temperatures : 100°C - up to 1100°C
- Samples to 8"
- Gas process : N_2 - $\text{N}_2/5\%\text{H}_2$ - O_2 - Ar

JIPELEC JETFIRST 100

- Range of temperatures : 100°C - up to 1100°C
- Samples to 4"
- Gas process : Ar, CH_4 , H_2 , N_2

1 Atmospheric Pressure Tubular Annealing Furnace CARBOLITE

- Range of temperatures : from 100°C to 1200°C
- Samples to 3"
- Gas process : N_2 , $\text{N}_2/5\%\text{H}_2$, Ar





Lithography Manager : Yves Deblock
Permanent staff : Christophe Boyaval • Saliha Ouendi • Pascal Tilmant • Anne-Sophie Vaillard
Non Permanent staff : Mélanie Brouillard

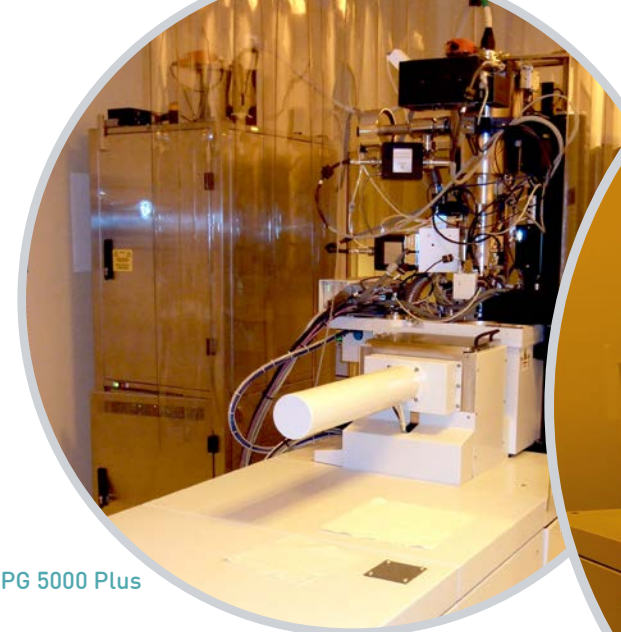
The lithography process enables the fabrication of micro- and nanoscale patterns. It uses radiation, such as UV light or electron beams, to expose light- or electron-sensitive resists. The lithography platform is operated by a team of six full-time engineers.



SPIN-COATING

The lithography process consists of coating the substrate with a thin layer of electron- or light-sensitive resist, typically by spin coating, followed by pattern definition. Patterns can be generated either by direct exposure using an electron or laser beam or by optical lithography, in which light is used to transfer a pattern from a photomask onto a photosensitive resist.

- From 1/4" to 6 inch wafer
- Photomask, 5 x 5, 6 x 6 inches
- More than 30 resists available
- Optical resists: SU8 - 3000, AZ series, S1800 series, SPR series, PMGI, LOR, UV210, ARP5300 series
- E-beam resists: PMMA, PMMA-MAA, CSAR62, MaN 2410, UV210, HSQ



EBPB 5000 Plus



EBPB 5200 Plus

ELECTRON BEAM LITHOGRAPHY

Electron-beam lithography (EBL) is a lithographic technique that uses a focused beam of electrons to define custom patterns in an electron-sensitive resist. Exposure to the electron beam changes the solubility of the resist. The exposed (or unexposed, depending on whether a positive or negative resist is used) regions are then selectively removed during the development process by immersing the sample in an appropriate developer.

2 EBPB electron-beam lithography systems (5000 Plus and 5200 Plus)

- More than 2000 writings per year
- From small sample (4mm x 4mm) up to 8 inch wafer
- E-beam resists: - PMMA, COPO, CSAR62, MaN, UV210, HSQ, ...
 - Optical resists used in e-beam: AznLoF, AZ15nXT, AZ40XT, ...

EBPB 5000 Plus

- High Resolution Gaussian Beam System
- Thermal Field Emission Gun
- 50MHz Pattern Generator
- Minimum address grid 0.08 nm
- Maximum field size : 524 μm (DAC 20 bits)
- Interferometer stage, 0.6 nm positioning accuracy
- Acceleration voltage: 20kV, 50kV or 100kV
- Automatic 10 positions airlock
- Holders for 2" to 4" wafers , 3" to 5" masks and smaller piece parts
- Overlay and stitching better than 30 nm

EBPB 5200 Plus

- High Resolution Gaussian Beam System
- Thermal Field Emission Gun
- 125MHz Pattern Generator
- Minimum address grid 0.08 nm
- Maximum field size : 1040 μm (DAC 20 bits)
- Interferometer stage, 0,15 nm positioning accuracy
- Acceleration voltage: 100kV
- Automatic 10 positions airlock
- Holders for 2" to 4" wafers , 6" masks and smaller piece parts
- Overlay and stitching better than 8 nm

EQUIPMENTS

CHARACTERISTICS

NanoCalc Thin Film Reflectometry System

- The NanoCalc-2000 UV – NIR can be used to measure the film thickness from 10 nm up to 250 μm

6 Gyrset RC8 and RCD8 spin coaters

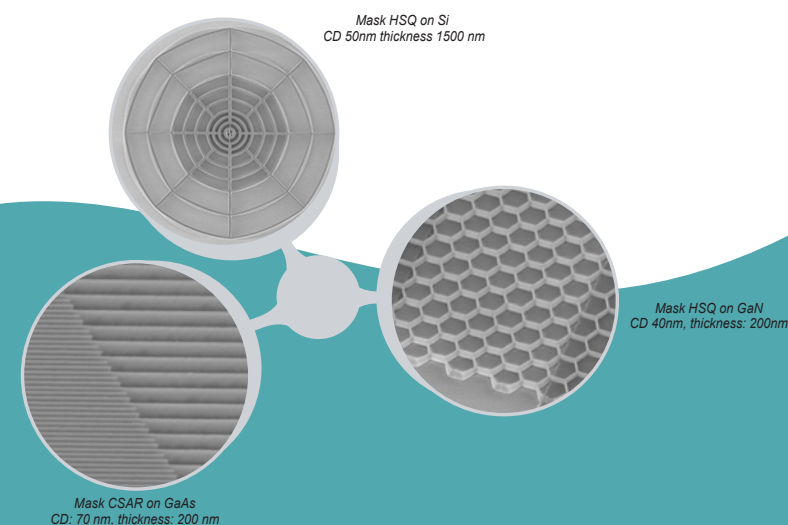
- Wafer size from 10 x 10 mm to 6 inches and optical mask 4, to 6 inches
- System (EBR) edge bead remover for wafers and system auto cleaning with specific solvent

6 Hotplates (Osiris, Obducat)

- Controlled process with nitrogen until 300°C : uniformity 0.1°C
- Programmable with lift pins

1 Sawatec Hotplate

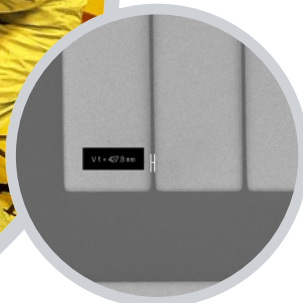
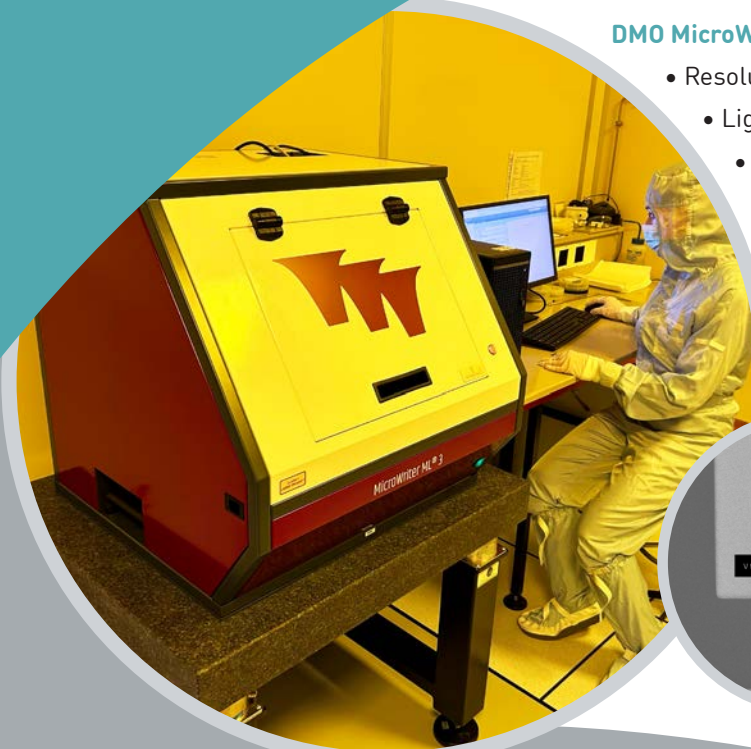
- Controlled process with nitrogen and vacuum until 300°C : uniformity 0.1°C
- Programmable with lift pins
- Controlled ramp up, steps, dwell, and ramp down
- Vapor prime (HMDS)





DMO MicroWriter ML3 PRO

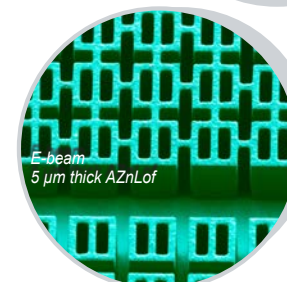
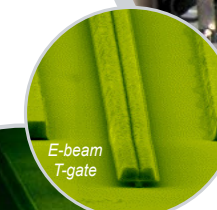
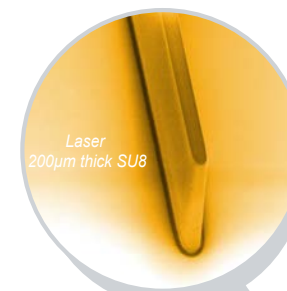
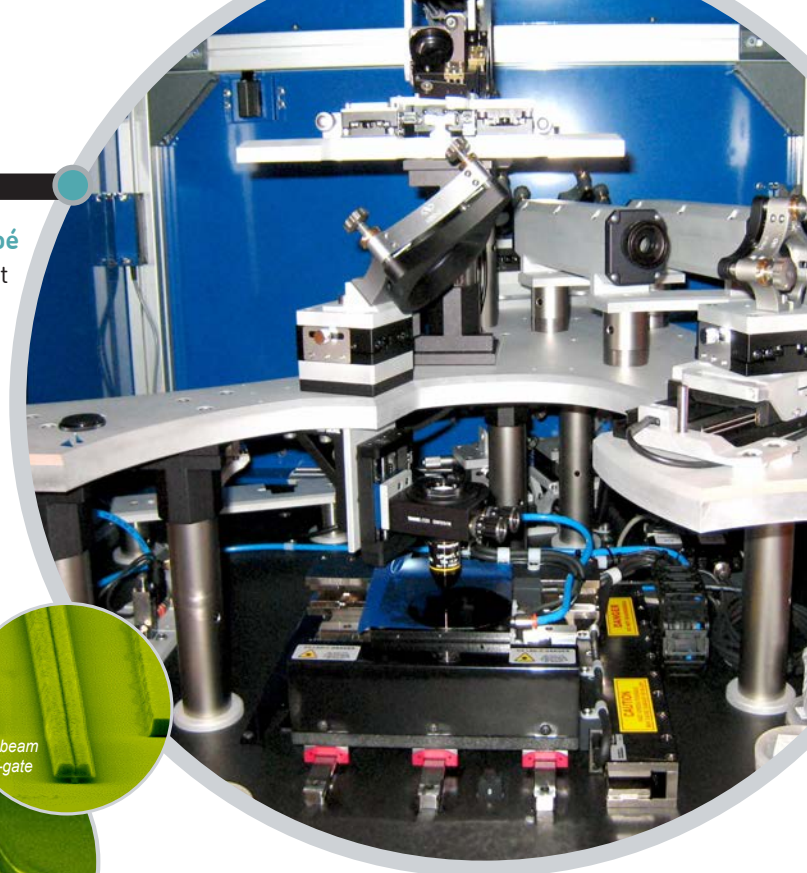
- Resolution: 5, 2, 1, 0,6 and 0.4 μm
- Light source: 385 nm LED
- Substrate size: from 1 cm^2 samples to 200 mm (8-inch) wafers
- Alignment: manual or automatic front-side and back-side alignment
- DLP-based autofocus
- Grayscale lithography with adjustable focus
- Vibration isolation table



LASER LITHO 2D

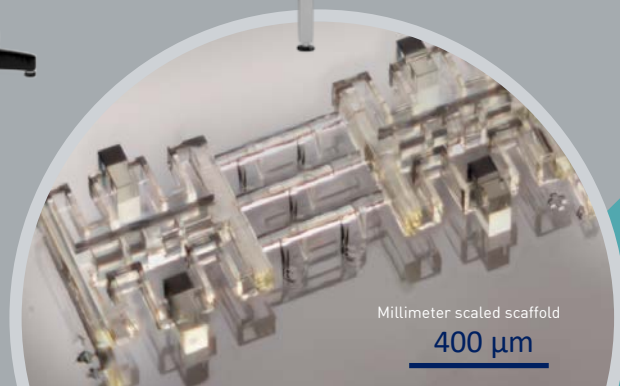
Dilase 650 Kloe

- High Resolution Direct Lithography System for fast Prototyping and Maskless Fabrication
- Laser source 375 nm, 73 mW
 - Wafer writing area 100 x 100 mm
 - Laser spot size: 1 μm and 10 μm
 - Stage travel resolution and repeatability: 100 nm



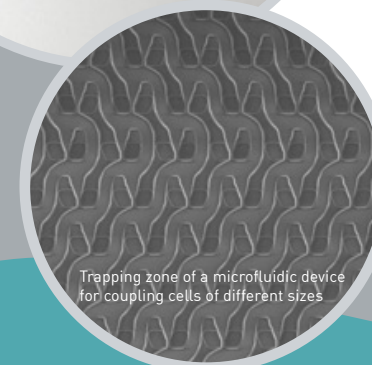
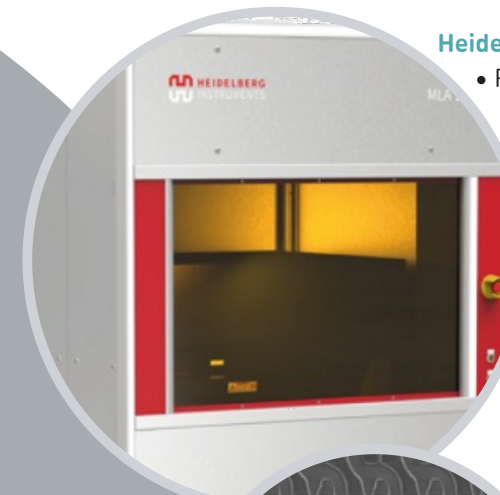
Nanoscribe PP6T2 Plus

- 2PP technology (Two-Photon Polymerization): highly localized absorption within the resist
- 2 optical configuration DiLL configuration and Oil immersion configuration (for low viscosity resist and transparent substrate)
- High-precision 3D piezoelectric stage: 300 x 300 x 300 μm^3 , combined with a mechanical XY stage
- Objectives x63, x25 & x10 (respective xy resolution 0.2 μm , 0.6 μm et 1.2 μm) (respective maximum printable volume <0.1 mm^3 , < 50 mm^3 , < 400 mm^3)



Heidelberg MLA 150

- Resolution: < 0,8 μm (depending on the resist)
- Laser sources: 375 nm (2.8 W) and 405 nm (8 W)
- Writing field: 26 mm x 33 mm
- Substrate size: up to 150 mm (6-inch) wafers and substrates up to 12 mm thick
- Writing speed: up to 200 mm^2/min (≤ 16 min for a 6-inch wafer)
- Alignment: automatic or manual, ± 0.5 μm accuracy; front-side and back-side alignment
- Autofocus: pneumatic
- Patterning modes: vector and raster writing
- Grayscale lithography: 128 gray levels
- Environmental control: laminar flow filtration with temperature stabilization to ± 0.1 $^{\circ}\text{C}$





MASK ALIGNERS

2 Suss MicroTec MA6/BA6 Mask Aligner and Bond Aligner UV 240-365 nm

- Substrate compatibility: from one-quarter of a 2-inch wafer up to full 4-inch wafers; compatible with 4 and 5 inches photomask blanks.
- Exposure modes: proximity, soft contact, hard contact & vacuum contact.
- Alignment performance: top-side alignment (TSA) accuracy down to 0.5 μm and bottom-side alignment (BSA) accuracy down to 1 μm .
- Lithographic resolution: features down to 800 nm in vacuum-contact mode using AZ nLOF 2020 photoresist.

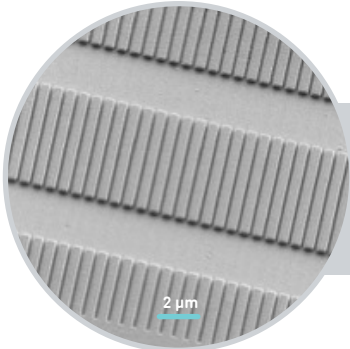


WAFER BONDING

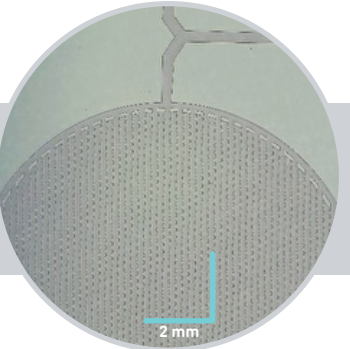
SB8 Gen 2 Suss MicroTec SB6e Wafer Bonder in combination with MA/BA6 Mask Aligner

- Compatible with aligned and non-aligned wafer using,thermo-compression, anodic, fusion, adhesive bonding, and other compatible processes.
- Substrate compatibility: samples smaller than 2 inches up to full 6-inch wafers. Alignment accuracy: aligned bonding down to 3 μm , depending on process conditions.
- Pre-bond surface preparation: integrated H_2/N_2 deoxidation prior to bonding.

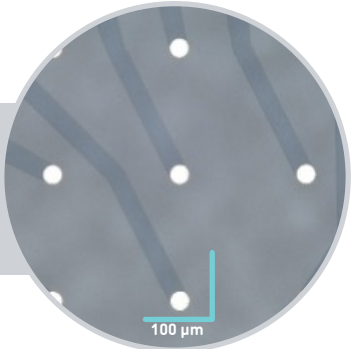
	E-beam Lithography	Maskless Photolithography	Mask Photolithography
Advantages	• Very high resolution (down to the sub-10 nm range) • Maskless process (direct writing from a computer-generated pattern file) • High overlay accuracy and stitching precision between lithography levels (typically better than 30 nm) • Ability to pattern very small samples (down to approximately $4 \times 4 \text{ mm}^2$)	• Maskless process (digital patterning directly from a computer file) • High depth of focus, enabling the exposure of very thick resist layers	• Very short exposure time (typically a few seconds per wafer exposure) • Simple and robust process, suitable for high-throughput fabrication • High wafer-to-wafer repeatability using the same photomask
Disadvantages	• Proximity effect, requiring correction for high-resolution patterns • Charging effects when exposing non-conductive materials • Accurate height measurement and focus control required before exposure • Long exposure time, depending on the pattern density and exposed areae.g., ~50 min for 1 mm^2 exposure in PMMA on GaAs, 1 nA beam current, 100 kV acceleration voltage)	• Limited overlay accuracy between lithography levels (typically 0.5–1 μm) • Exposure time can be long, depending on the pattern complexity and exposed area	• Requires a physical photomask, involving additional fabrication cost and lead time • Limited overlay accuracy between lithography levels (typically 0.5–1 μm)
Typical Applications	• Sub-micrometer and nanometer-scale patterning (features below 1 μm) • High-precision alignment between lithography levels (below 1 μm, typically tens of nanometers) • Fabrication of advanced devices requiring high-resolution structures (nanophotonics, quantum devices, nanoelectronics, etc.)	• Feature sizes above 1 μm • Rapid prototyping without the need for photomask fabrication • Patterning of very thick photoresists requiring a large depth of focus	• Micrometer-scale patterning (typically above 1 μm) • High-volume fabrication of multiple wafers with the same design • Industrial processes requiring high throughput and reproducibility



PMMA gratings & wave guide



Interdigitated electrode



PEDOT: PSS MEA

ETCHING & ION IMPLANTATION

Unit

PLASMA ETCHING

Etching is used in microelectronics to chemically or/and physically remove layers from the surface of a wafer during process. For many etching steps, part of the wafer is protected from the etchant by a «masking» material which resists etching.
4,5 Full Time Employees

DEEP SILICON ETCHING

Bosch process

The Bosch process is two steps process. It enables highly anisotropic deep silicon etching. It uses fluorine based plasma chemistry (SF_6), to etch the silicon combined with a fluorocarbon (C_4F_8) plasma process to provide sidewall passivation and improved selectivity to masking materials. A complete etch process cycles between etch and deposition steps many times to achieve deep, vertical etch profiles.

2 Bosch process based reactors:

• Oxford estrelas plasmapro100 with cryogenic capabilities:

• Dmitri Yarekha

Estrelas is equipped with a **Cryogenic** electrode, that allows to do Si etching at very low temperature (-150°C min. Typically at -120°C / -90°C). No passivation steps or needed at low temperature to obtain anisotropic etching and at the same time it allows to obtain very smooth walls, which is very interesting for optoelectronics applications.

- Etch depth: wafer through
- Selectivity to PR > 250:1
- Selectivity to SiO_2 > 500:1
- Uniformity $\pm 3\%$

• SPTS Rapier

• Marc Faucher

REACTIVE ION ETCHING (RIE)

• Timothy BERTRAND • Tatiana Mbouja Signe

Reactive Ion Etching (RIE) uses chemically reactive plasma and physical sputtering to remove material deposited on wafers.

• 2 systems CCP OXFORD Plasma Pro 80

- Single 600W RF plasma source determines both ion density and ion energy
- Ion energy dependent on the RF power and process pressure
- Negative self-bias forms at the substrate electrode
- Gas : CF_4 , CHF_3 , SF_6 , Ar, O_2 , N_2
- Laser interferometry endpoint detection systems

Etching & Ion Implantation Manager : Dmitri Yarekha
Permanent staff : Timothy Bertrand • Laurent Fugère
• Jean Houpin • David Troadec
Non Permanent staff : Giuseppe Di Gioia • Tatiana Mbouja Signe

INDUCTIVELY COUPLED PLASMA (ICP - RIE)

• Timothy Bertrand • Giuseppe Di Gioia
• Tatiana Mbouja Signe • Dmitri Yarekha

ICP source produces a high density of reactive species. Separate RF generators for ICP and electrode provide separate control over ion energy and ion density often achieving higher etch rate and lower damage. High process flexibility, can also be run in RIE mode for certain low etch rate applications. Materials etched are III-Vs, silicon, silicon oxides, several metals, glass,...

All of our etching chambers are equipped with laser interferometry endpoint detection systems.

• OXFORD Plasmalab System 100 dual chamber cluster ICP 180

Two process chambers

- Gas chamber 1 : CH_4 , H_2 , Cl_2 , O_2 , SF_6 , Ar
- Gas chamber 2 : Cl_2 , BCl_3 , O_2 , SF_6 , Ar
- The system includes wafer clamping and helium cooling, providing temperature control (range 5°C to 60°C)

• SENTECH SI 500 - 2 reactors:

- Gas: CH_4 , H_2 , Cl_2 , O_2 , Ar, Cl_2 , BCl_3 , HBr
- Providing temperature control (range -20°C to 250°C)
- For up to 100 mm wafers

SURFACE CLEANING AND TREATMENT

• Timothy Bertrand • Dmitri Yarekha

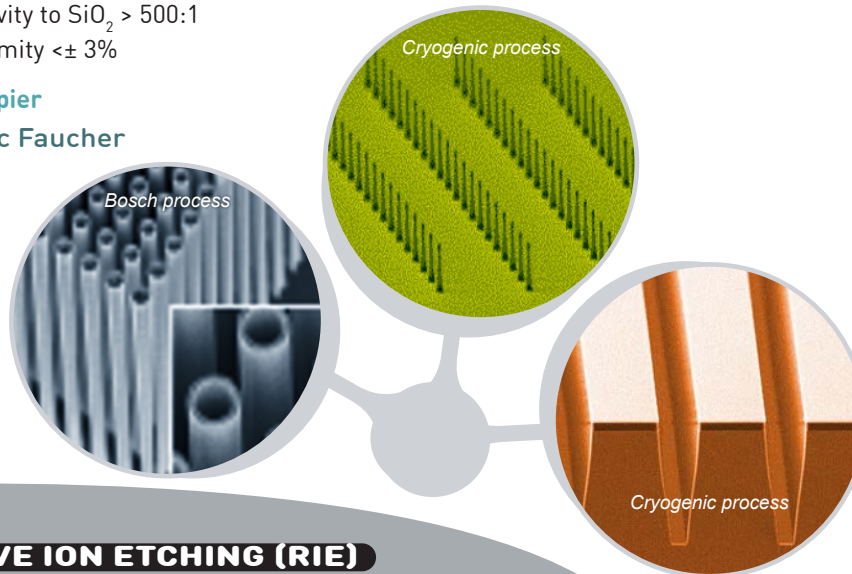
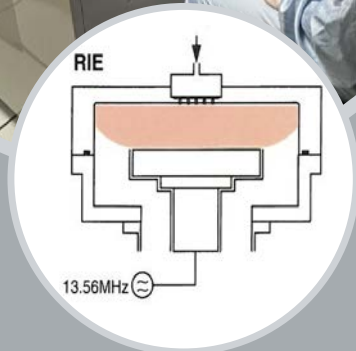
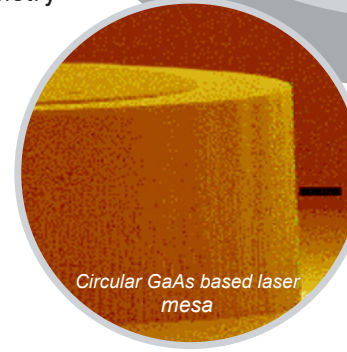
• Plasma system PVA Tepla 300 semi-auto

Microwave plasma stripper
Dry process for photoresist stripping and substrate cleaning
Microwave plasma produces a very high concentration of chemically active species with low ion bombardment energy guaranteeing fast ash rate and a damage-free plasma
Tubular quartz chamber with 1000W microwave generator
Option : Faraday cage to reduce electro static discharge (ESD)
Gas : O_2 , Ar, CF_4

• NAVIGATOR 8

Photo-resist stripping
Residues cleaning & descum
Surface activation
High plasma density ICP source
Gases: O_2 , CF_4 , N_2
Power: 13.56 MHz, 1000 W
Pressure: 50 - 1000 mTorr
Chamber heating: 20 - 250 °C
Chuck heating: 20 - 250 °C

• **UV-ozone Cleaner** : Surface oxidation and cleaning by ozone combined with UV(254 nm and 185 nm)



ETCHING & ION IMPLANTATION

Unit

CHEMICAL ETCHING

Etching & Ion Implantation Manager : Dmitri Yarekha

WET ETCHING

Wet etching is an etching process that uses liquid chemicals to remove materials from a wafer. Chemistry stations:

- Organic, halogeneous, inorganic acids
- Inorganic bases
- Halogeneous and non halogeneous solvents

DRY ETCHING:

- Good Anisotropy
- To achieve small features
- High cost

WET ETCHING COMPARED TO DRY ETCHING

WET ETCHING:

- Low cost, easy to operate
- Good selectivity for most materials
 - Isotropic
- sensitive to changes in temperature

- Supercritical CO₂ dryer TOUSIMIS Automegasamdri®-936-C

Jean Houpin

- Striction-free drying of MEMS and microstructures following wet process
- Standard rinsing solvents : IPA, ethanol, methanol
- Processing up to 5-150mm (6") wafers per cycle, as well as 100, 75 or 50 mm wafers and individual chips.

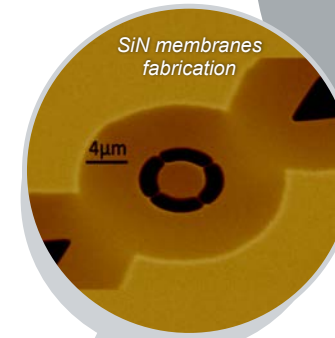
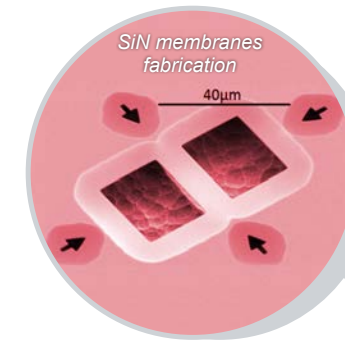
XeF₂ ETCHING SYSTEM

Jean Houpin Dmitri Yarekha

The Xactix® X4 Series is the XeF₂ etch system for releasing Silicon based MEMS devices.

It uses cyclic vapor exposition to isotropically dry etch sacrificial silicon:

- high rate silicon etching system with
- high silicon /silicon oxide selectivity



VAPOUR HF ETCHING SYSTEM

Jean Houpin

The fabrication process of MEMS devices in silicon microtechnologies involves as final step the releasing of the microstructures by an etching of a silicon dioxide sacrificial layer.

The "vapour HF" technique gives access to a releasing process which is an alternative to the one including wet HF etching + CO₂ supercritical drying. Advantages of the "Vapour HF" technique are manifold, and come from the dry and anhydrous conditions the "Vapour HF" machine brings: stiction free releasing, carbon free surfaces, selectivity versus metals and silicon nitride.

The SPTS "uEtch" is a single-wafer system. Wafers from pieces to 8 inch can be loaded in the chamber. Using 5 different recipes calibrated on the machine, we are able to etch TOX with an etch rate of 100 Å/min to 1650 Å/min and a uniformity around 2% on 3 inch.

ETCHING & ION IMPLANTATION

Unit ION BEAM



Etching & Ion Implantation Manager : Dmitri Yarekha

Characterisation process refers to in-line inspection for process control and materials study. A wide range of techniques are available from optical, electrical, physical or mechanical.
3,5 Full Time Employees

FOCUSED ION BEAM

David Troadec

Dual beam system combines a high resolution secondary electron microscope (SEM) and a focus ion beam with gallium metal ion beam source (FIB) for nanoscale machining, patterning, and nanomaterials characterization. Materials can be milled or deposited while observing the evolution of the surface topography with secondary electrons (SEM or FIB).

ZEISS - CROSSBEAM 550L

Electron column (SEM) :

- Electron source : Field effect gun (FEG)
- Accelerated voltage : 20V to 30kV
- Probe Current : 3 pA to 40 nA
- Scanning resolution (SEM) : 0.9nm
- Transmission resolution (STEM) : 0.6nm

Ion column (FIB) :

- Ion source : Gallium liquid metal ion source (LMIS Ga+)
- Accelerated voltage : 500V to 30kV
- Probe Current : 1pA to 100nA
- FIB resolution : 3nm at 30kV

- 120nm at 1kV
- 330nm at 500V

Laser Femtosecond :

- Localisation : Airlock chamber
- Focus diameter : < 15 μm
- Pulse duration : < 350 fs
- Pulse repetition rate : 0.1 – 1000 kHz
- Scan Speed : 0.1 – 9000 mm/s
- Scan Field : 40 x 40 mm

Detectors :

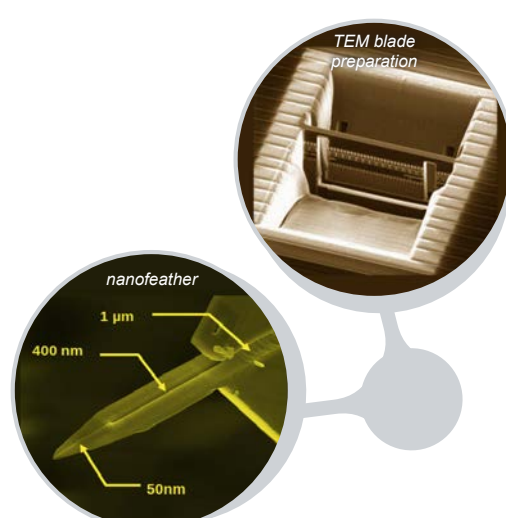
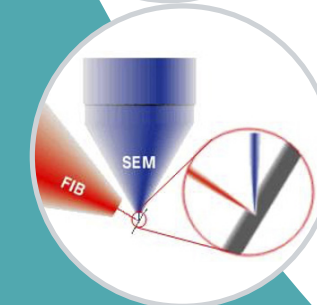
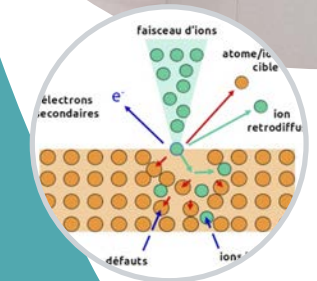
- SE : Secondary electrons
- BSD : Backscattered electrons
- InLens : Secondary and backscattered electrons
- STEM : Transmission electrons
- EDX : Oxford Ultimex 100
- EBSD : Oxford Symmetry

Stage :

- 6-axes motorised super eucentric
- Movements : X = 153 mm
- Y = 153 mm
- Z = 50 mm
- M = 20 mm
- Tilt = -15 to 70°
- Rotation = 360° continuous

Gaz injectors (x2) : Platinum, Carbon, Tungsten, ...

Micromanipulators : Kleindiek



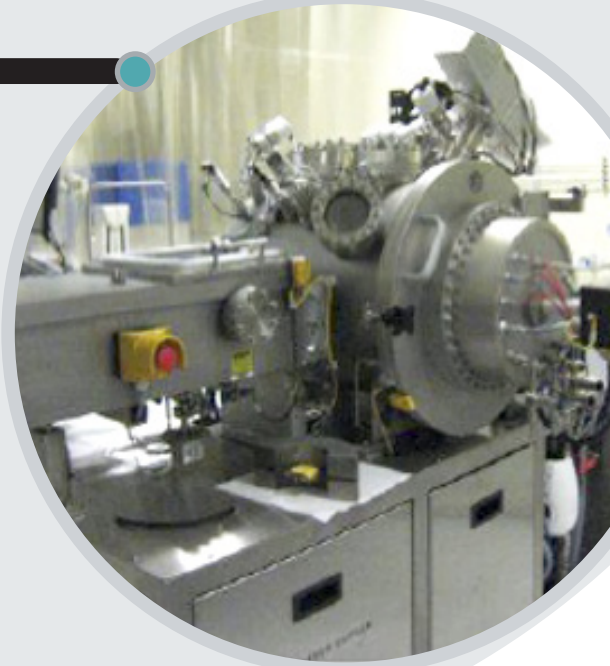
ION BEAM ETCHING (IBE)

Giuseppe Di Gioia Dmitri Yarekha

- High resolution (below 10 nm)
- Universal etchant
- No undercut
- monoenergetic beam - varied to suit experiments
- Field and plasma free - relaxes restrictions
- IBE - Beam of neutral ions (Ar+)
- RIBE - Beam of neutral and reactive ions (Ar+, O+ et O2+)

IonSys 500

Microwave ECR ion beam 220 mm source
- ion energies from 100 – 1000 V
- ion current densities up to 1 mA/cm²
Tilting from 0° to 90°, $\pm 0.1^\circ$
Rotation from 2 to 20 rpm
Cooled substrate holder (-20°C to +50°C), helium backside
Six process gas lines: Ar, N₂, O₂, CH₄, SF₆, H₂
Endpoint detection - SIMS



ION IMPLANTATION

Laurent Fugere Dmitri Yarekha

Ion implantation is a materials engineering process by which ions of a material are accelerated in an electrical field and impacted into a solid. This process is used to change the physical, chemical, or electrical properties of the solid.

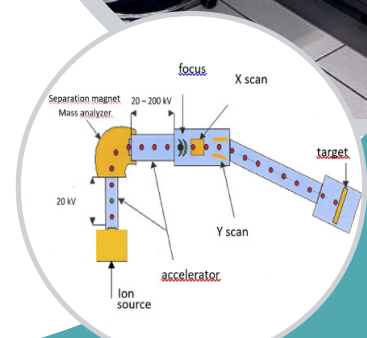
- Production and R&D chambers
- More than 250 implantations per year
- Up to 4 inch wafer
- Principal implanted species: As, P, Si, Ar, N, C, B, F
- More than 30 species can be implanted

Implanter EATON-AXCELIS GA 3204

- Energy : from 5 keV to 150 keV
- Doze : from 1E12 at./cm²
- Sources: Gases, solid
- Twist : 0° to 360°

ANNEALSYS Rapid Thermal Annealing

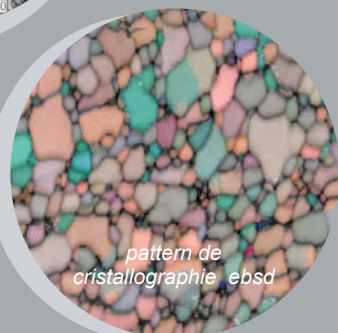
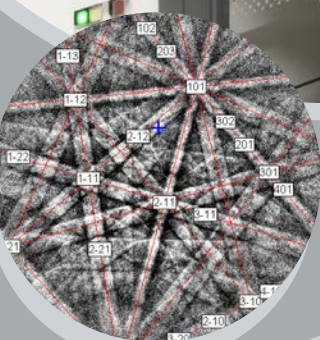
- Temperature range: 100° to 1300°C
- Susceptors : Silicon or Graphite coated with SiC
- Operation : N₂, N₂H₂, High vacuum
- Up to 6 inches



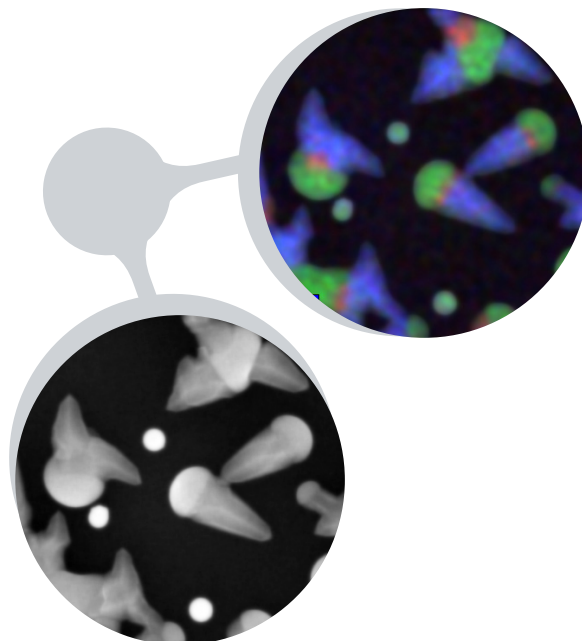


In Line Analysis Manager : Christophe Boyaval
Permanent staff : Flavie Braud • Christophe Coinon
• Yves Deblock • Marc Dewitte • David Guérin

Characterisation process refers to in-line inspection for process control and materials study. A wide range of techniques are available from optical, electrical, physical or mechanical.
3,5 Full Time Employees



pattern de cristallographie ebsd



SEM

Christophe Boyaval

SEM (Scanning Electron Microscope) is a microscope that uses an electron beam to illuminate a specimen and produce a magnified image with a 1000 times higher resolution than optical light microscope.

Equipments

- ZEISS ULTRA 55 / EDS Bruker
- ZEISS SUPRA 55 VP / EBSD Oxford
- Maximum resolution : Close to 1nm @ 15kv
Close to 3 nm @ 1kv
- Source type: Field effect gun
- Detector type: Inlens, Secondary and backscattered electrons
- Analysis: Chemical by EDS and Crystallographic by EBSD
- Wafer size: up to 6 inch
- Low Pressure: 1 to 133 mPa

PHYSICAL CHARACTERISATION

Christophe Coinon

PANalytical X'Pert Pro MRD

TA-DA XRD (Triple and Double-Axis X-Ray Diffraction)

X-ray Diffraction is a tool used for determining the crystalline structure of solids, in which the periodic atomic arrangement causes a beam of X-rays to diffract into many specific directions. The structure is determined by measuring the angle and intensities of these diffraction peaks.

Applications →

- Alloy composition and thickness
- Control of lattice matching of epitaxial layers layers with the substrate
- Interface quality of superlattices
- Thin strained layers
- Relaxation rate, composition and tilt of mismatched layers

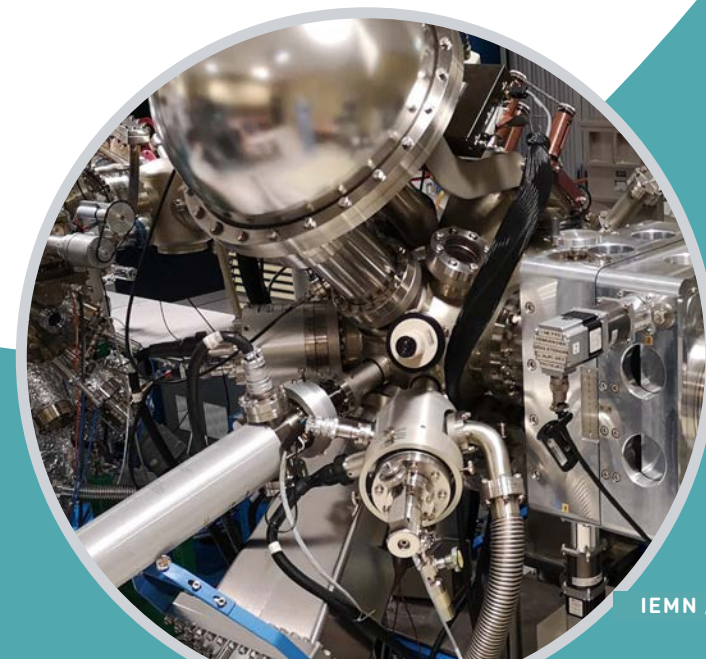
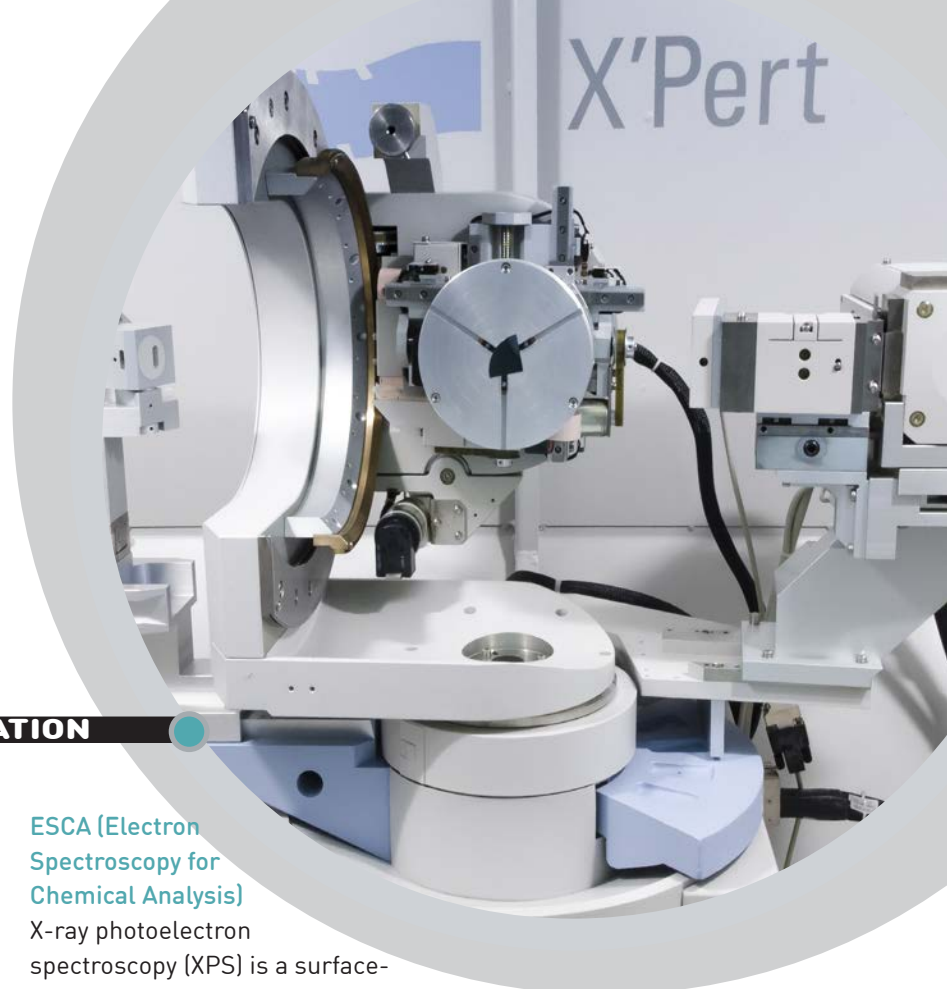
ESCA (Electron Spectroscopy for Chemical Analysis)

X-ray photoelectron spectroscopy (XPS) is a surface-sensitive quantitative spectroscopic technique. Based on the photoelectric effect, it allows determining the elemental composition at the parts per thousand range and the chemical state of the elements present within a material.

- Monochromatized XPS with ultimate resolution: 0.45eV
- UPS: He I and He II excitations
- Low Energy Electron Diffractometer (LEED)

Applications →

- III-V MBE grown surfaces and interfaces
- Graphene
- Organic layers
- Characterization of process steps





OPTICAL

Christophe Coinon, Yves Deblock, David Guérin

• 2 Horiba Jobin Yvon Spectroscopic Ellipsometers:

Based on optical polarisation for investigating the dielectric properties of thin films (complex refractive index, dielectric function). It can be used to characterise thickness, composition, roughness, crystalline nature, layer inhomogeneity (gradient, anisotropy). Single layers or complex multilayers from a few Å to several μm .

Uvisel: 200 nm - 2000 nm, variable angle, monochromator.

AutoSE: 440 nm - 1000 nm, mapping, spot views.

• Reflectometer Idil

The NanoCalc Thin Film Reflectometry System allows to analyze the thickness of optical layers from 10 nm to 250 μm . Observation of single thickness with a resolution of 0.1 nm and single-layer or multilayer films in less than one second and 6" mapping.

• μ -Photoluminescence & Raman Lab RAM HR

PL can be used for band gap measurement, alloys composition and thickness, Interface studies of heterostructures.

Raman can be used for graphene (strain, doping, thickness)

• UV/vis Spectrometer Lambda 365+ (Perkin Elmer)

Absorption spectrum of liquids or thin films from 200 nm to 900 nm

• Tri-range MIR/NIR/FIR Fourier - Transform Infrared Spectrometer Spectrum 3 (FTIR) - Perkin Elmer

Spectral range : from 15000cm^{-1} to 30 cm^{-1}

Different accessories available for bulk materials (solid or liquid) or surface analysis (molecular films, polymer)

• Veemax III accessory (from Pike Technologies) : Variable angle single reflection ATR with Ge crystal or variable angle specular reflection with manual control of the angle of incidence

• Gladi ATR accessory (from Pike Technologies) : ATR with diamond crystal (control of temperature also possible during analysis)

Different techniques : transmission mode, ATR mode, variable angle specular reflexion

ELECTRICAL

Christophe Coinon, Christophe Boyaval, David Guérin

• **Hall Effect:** The Accent HL5500PC is a turn-key, high performance Hall System for the measurement of resistivity, carrier concentration and mobility in semiconductors. Modular in concept, allowing easy upgrade paths, the system is suitable for a wide variety of materials, including silicon and compound semiconductors. It has both low and high resistivity measurement capabilities to 300K or 77K.

• **Probe station:** Two microwave probe stations are available in the IEMN for idv and junction measurement.

• **The semilab WT-2000PVN** system is a non contact platform for samples inspection (silicon, ...) quality control and process monitoring.

It is equipped with a variety of measuring options, including solar cell characterisations. It enables automatic mappings in the following modes:

- μ -PCD for determination of minority carrier lifetime
- LBIC for diffusion length and internal quantum efficiency evaluation on solar cells
- Eddy current for non-contact resistivity measurement

Thin film's Stress measurements



SURFACE TOPOGRAPHY

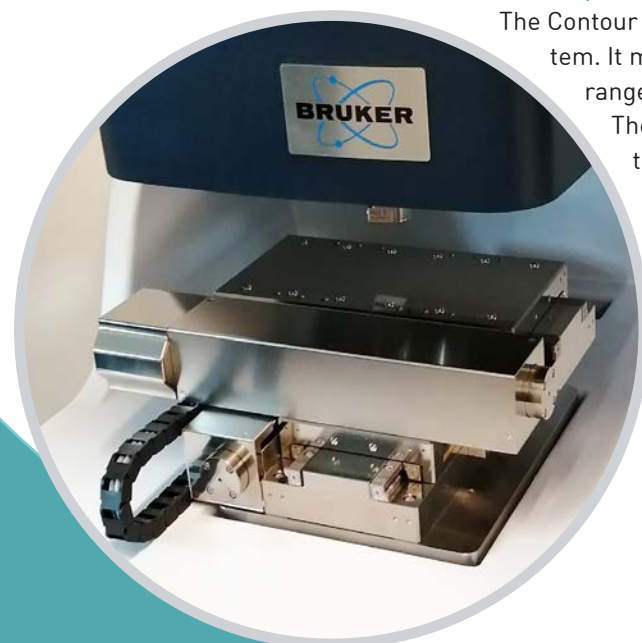
Christophe Boyaval, Flavie Braud

AFM Edge (Bruker).

The AFM Edge is used for measuring very small dimensions such as step heights and roughness on different materials. Roughness around 0.1nm and step heights below 1nm can be measured. Peak Force Tapping™ allows making measurements without damaging surfaces and tips. The motorized table authorizes the positioning of large substrates with a scanning range of 100µm.

Contour GT X Optical profiler (Bruker)

The Contour GT-X is a stand-alone optical surface-profiling system. It measures surface topography with high accuracy in a range from fractions of a nm up to approximately 10mm. The system contains motorized x/y, tip/tilt and z stages to enable automated production monitoring. It is equipped with four interferometric objectives of magnification 2.5x, 10x, 50x and 115x.



3 Mechanical profilometers

They are used for measuring step heights from 10 nm to 1 mm. A stylus on a capacitive cantilever scans the profile of various types of materials (resists, metallic plots and so on...). Scan range up to 6 inches are available.



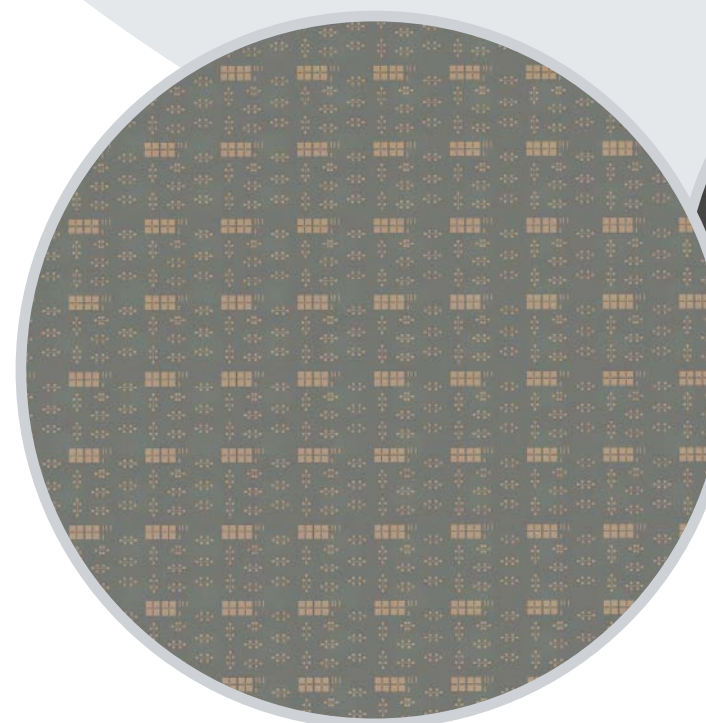
DIGITAL MICROSCOPES

Christophe Boyaval

Two models VHX6000 & VHX7000N (Keyence)

Functions :

- 750 mm image reconstruction
- Height measurement using Z position delta
- Tilt imaging



Back end process refers to the process done outside cleanroom at chip level from wafer backgrinding to packaging.

Packaging Manager : Flavie Braud
Permanent staff :
Marvin Savanxayadeth
Non Permanent staff :
Diana Kafizova

LAPPING, POLISHING

for a slow lapping and a soft polishing

A plate in rotation carries a cloth impregnated of an abrasive micro suspension. The sample, laid out on a head in rotation and translation, is brought to the contact with a controlled pressure.

PM5 (LOGITECH)

Main Characteristics:

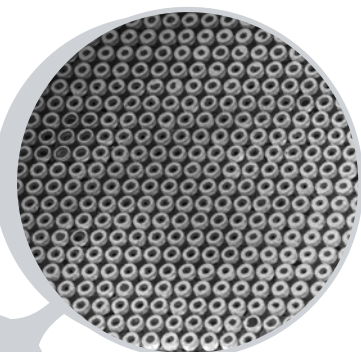
- Materials: III-V Materials (InP, AsGa), Si, Lithium Niobate ...
- Up to 4" wafers and small pieces
- Sample maximum thickness: 2 mm
- Plate speed: 0-40 rpm
- Applied pressure: 0 to 2 kg
- Removed material mesured by a dial gauge - 1 to 5 $\mu\text{m}/\text{min}$
- Thickness resolution : +/- 5 μm
- Roughness of the order of nm

Wafer Substrate Bonding Machine (LOGITECH)

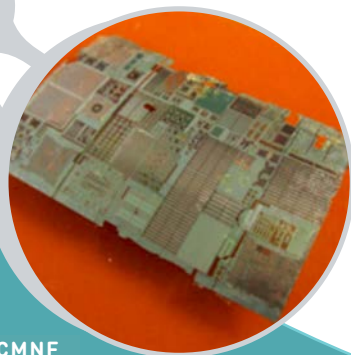
- Up to 4" wafers and small pieces
- Automated process cycle
- Excellent wafer to support disc parallelism
- Process repeatability

Applications →

- Preparing the surface prior to fabrication,
- Thinning the device after fabrication,
- Providing defect free face polishing on substrate.



Ni pillars thinning and planarization

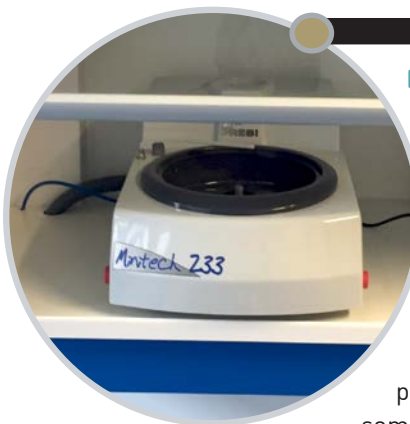


Silicon components reported on flexible substrate after grinding and chemical etching

POLISHING

MINITECH 233 (PRESI)

The MINITECH Polishing machine is robust, powerful and reliable, it allows an easy use and simple maintenance. The machine provides a constant rotation of the plate, whatever the force applied, giving the possibility to polish large sized samples. MINITECH range is equipped with plates $\varnothing$ 200mm.



CMP

E 460 (ALPSITEC)

CMP: for a soft and precise polishing and planarisation process

Chemical mechanical planarization is a process of smoothing and planing surfaces with the combination of chemical and mechanical forces, in order to prepare them for the following steps.

The CMP tool consists of a rotating platen, covered by a pad. The wafer is mounted upside down in carrier. The platen and the carrier are rotating.

Pressure is applied by down force on the carrier.

A slurry is supplied from above on the platen.

Main characteristics:

- Authorized substrates: from 2 to 4 inches
- Substrate rotation speed: 5-130 rpm
- Plate rotation speed: 5-120 rpm
- Applied pressure: 0-950 mdaN/cm²
- 10 steps per recipe
- 2 slurries possible during the process
- Materiels: Si, poly Si, SiO₂, metals (Cu, W...)
- Maximum removed thickness: 20 μm

Applications →

- Interlevels dielectrics ILDs
- Shallow trench isolation STI technology
- Damascene process
- Planarisation



GRINDER

MPS 2 R300 (G&N)

For a fast and aggressive mechanical thinning of substrates

A rotation abrasive wheel removes the material on a sample itself in rotation.

Main characteristics:

- Substrate: 3"
- 4 substrates max
- Substrate rotation speed: 0-30 rpm
- Head max rotation speed: 2600 rpm
- Height precision: 3 μm
- Grinding speed: 1-30 μm
- Materials: Silicon SiC glass

Ultra pure deionized water allows cooling during the process.





LASER ABLATION

Laser micromachining is emerging as a key technology for structuring, ablating, scribing, cutting, drilling a wide range of materials as diverse as semiconductor crystals, metals and plastics. Ablation selectivity between materials can be achieved with a proper selection of wavelength, laser shot repetition rate and beam velocity. Two laser micromachining equipments are available, operating in the nanosecond and femtosecond pulse regimes, respectively.

Oxford Laser Equipment #1, Amplitude Systems Tangerine

- Multi-wavelength femtosecond (300fs) diode-pumped (DPSS) lasers source (UV 343,GR 515,IR 1030 nm)
- Average power up to 20 W @ 200 kHz and pulse energy up to 100 μ Joule in IR
- Repetition rate up to 2 MHz
- galvanometer deflection with extended field of 50x50mm²
- sample stage up to 300x300 mm² with linear accuracy +/- 0.5 μ m, repeatability +/- 0.2 μ m
- Trepan head
- Position synchronized output (PSO)

Micro and nanostructuring of metal to create black metal with femtosecond laser system

Microstructure

Nanostructure

XTOOL F2 Ultra UV

Engraving without significant heat buildup thanks to the UV laser ("cold laser"), minimizing burns and warping. Compatible with almost all materials: glass, crystal, acrylic, engineering plastics, metal, wood, leather, ceramic, rubber, silicone, etc.

- 5 W UV Laser – 355 nm
- Engraving speed up to 15,000 mm/s
- Work area: 200 x 200 mm
- 3D internal engraving in glass: 70 x 70 mm
- Ultra-fine engraving precision suitable for high-definition markings and micro-details.
- Maximum part height: 150 mm
- Maximum diameter for rotary engraving: 150 mm
- USB, Wi-Fi, and IP network connectivity.

P3S Gravure Co₂

- Technology: 55 W CO₂ laser cutting and engraving
- Work area: 600 x 305 mm
- Maximum speed: up to 600 mm/s
- Cutting capacity: up to 18 mm of wood and 20 mm of acrylic in a single pass
- Maximum workpiece height: up to 215 mm (with riser base)
- Accuracy: 0.01 mm resolution with LiDAR autofocus and dual positioning cameras
- Materials: wood, acrylic, leather, cardboard, fabric, glass, ceramic, bamboo, slate (metal engraving with optional IR module)

μ -PCB for mmW applications (laser femto system)

DICING SAW DAD 3240

Diamond saw for substrates dicing, components individualisation

The substrate to be diced is positioned on a flexible adhesive film and fixed on the chuck. After alignment between the cutting ways on the substrate and the blade, the substrate moves at a selected speed under the blade. The blade is cooled by water jet and its rotation speed is controlled. Dicing can be made in manual or automatic ways.

Main characteristics:

- Rotation speed of the blade: 6,000 - 60,000 rpm
- Chuck displacement speed: 0.1 - 600 mm/s
- Substrates size: up to 8 inches max
- Materials: III-V materials, silicon, glass, ceramics, SiC saphir
- Optical alignment of the blade

Dicing & Patterning

Pillars carried out by DISCO dicing saw

SEM picture of a cutting line

AlN micromachining : Blind and pass-through via (nanosecond laser system)



WIRE BONDING

JFP WB-100 wire bonder & JFP -200

Wire Bonding: Realisation of electric connections between the component and its support

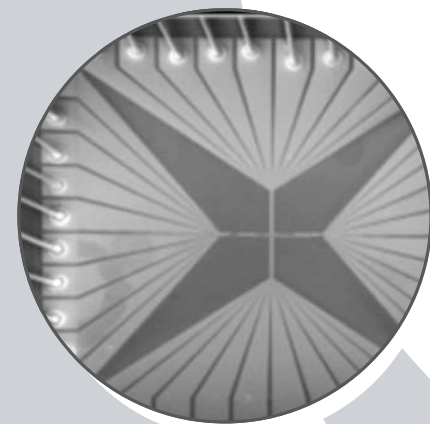
Wire bonding is a method to make interconnections between a semiconductor device and its packaging during semiconductor device fabrication. A conductor wire is positioned using a specific tool (ball or wedge) to the top of the metal pad of the component contact. A welding is created by the application of force and ultrasounds. An heating effect can be added according to the nature of wire.

Main characteristics:

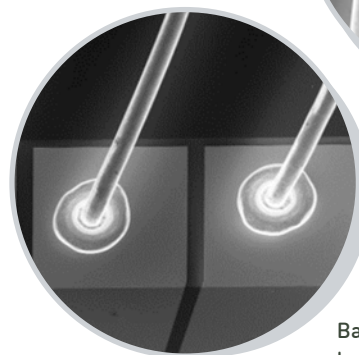
- Wire types: Au
- Wire diameters: 17 μm , 25 μm
- Principle: ultrasonic and thermosonic

Technical characteristics of the WB100:

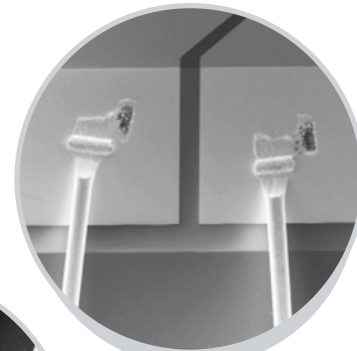
- Ball, bending
- Bond force: 15 - 100 cNm
- Bond time: 15 - 5000 ms
- Motorized Z travel: 20 mm
- Throat depth: 165 mm
- Fitted with a heated work holder, a motorized wire spool



Micro-solder in ball mode on a crossbar device 100nm



Ball bonding (left) and wedge bonding on Si (right), 180 x 180 μm pads



WAFER SCRIBER/BREAKER

Wafer Scriber/Breaker: Realisation of a seed in a preferred crystallographic direction to force the cleavage

The scriber is a machine designed scribing & breaking of delicate die, such III-V materials & silicon chip. It keeps the finished die clean and damage-free.

After positioning the substrate on the Mylar film, it aligns the diamond tip on the cutting or along the desired axis lines. Then, it strongly supports the diamond peak on the surface by dragging the substrate to create a fracture line.

Main characteristics:

- Diamond peak
- Substrate up to 4 inches
- Materials type: Si, AsGa, InP
- Resolution of position: 1 μm
- Vision system allowing a programmable or manual alignment
- Break mode: operator control or automatic
- Scribing length programmable and scribing repeatable
- Robust, vibration free, requiring minimal training to operate



JFP Model 100

PICK AND PLACE

JFP Model PP6-6:

The Flip Chip Die Bonder model PP6 is designed for accurate placement of delicate devices on substrate. It achieves high accuracy placement using high magnification optical device.

The machine provides for single collet vacuum pick and place of die from wafer pack, wafer, Gel-Pak or bulk die media and features adjustable and repeatable subsonic scrub. The placement accuracy is < 3 μm , upon configuration.

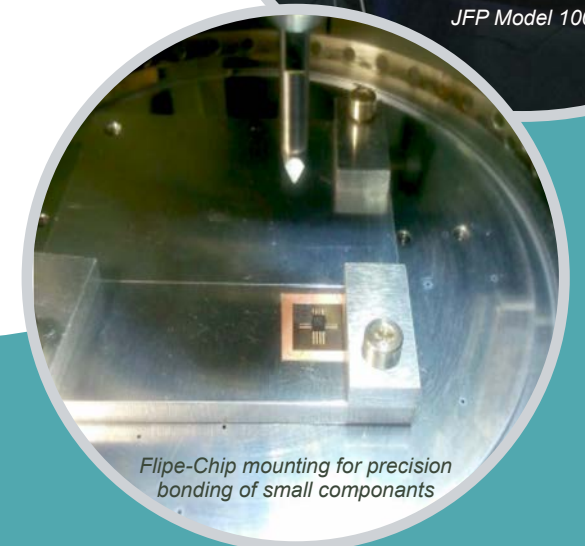
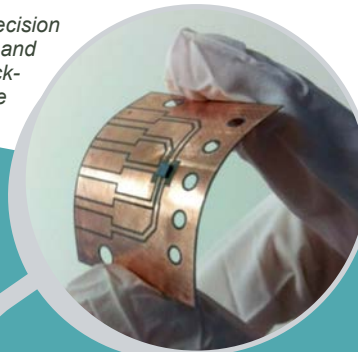
Small and large devices can be placed with flipped vision.

A robust, and reliable mechanical concept, designed to be external vibration free.



JFP Model 100

High precision positioning and connecting by pick-and-place



Flipse-Chip mounting for precision bonding of small components



3D PRINTER

Christophe BOYAVAL

The dual-extruder MakerBot's Replicator 2X 3D printer produces good-quality objects.

MakerBot Replicator 2X

- Two extruders
- ABS, PETT, HIPS (dissolvable) filaments
- 100 µm layer resolution
- SD card / USB
- User-friendly software
- LCD navigation screen
- Various print modes
- Heated platform (110°C – 120°C)

FormLabs

- Technology: SLA (LFS) 3D printing
- Print volume: 145 × 145 × 185 mm
- Layer thickness: 25 to 300 µm
- Laser spot size: 85 µm (405 nm laser)
- Accuracy: Excellent dimensional accuracy & surface quality
- Materials: Over 30 engineering, dental & biocompatible resins
- Connectivity: Wi-Fi, Ethernet, USB

Bambu Lab X1E - 3D Filaire

- Technology: FDM / CoreXY 3D printing
- Print volume: 256 × 256 × 256 mm
- Maximum speed: up to 500 mm/s
- Maximum acceleration: 20,000 mm/s²
- Maximum nozzle temperature: 320 °C
- Active heated chamber: up to 60 °C
- Accuracy: automatic calibration, vibration compensation, and AI-assisted quality control
- Materials: PLA, PETG, ABS, ASA, TPU, PC, PA, PVA, as well as carbon- and glass-fiber-reinforced composites (PA-CF, PC-CF, PPS-CF, etc.)

devices by
3D printing

MACHINING STATION

CNC milling machine, DATRON NEO

Development of fluidics (devices) or mechanical compounds (molds) in polymer or hard materials

The DATRON neo is a CNC milling machine which enables the ultra-fast and efficient machining of different materials.

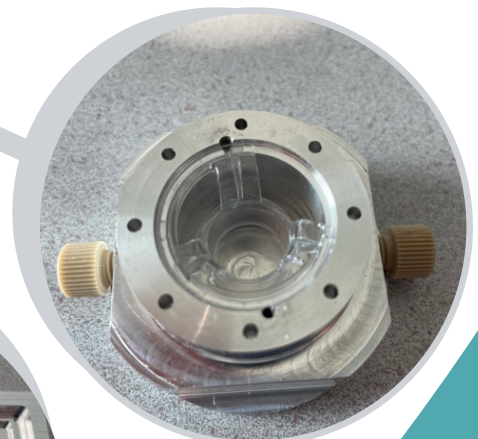
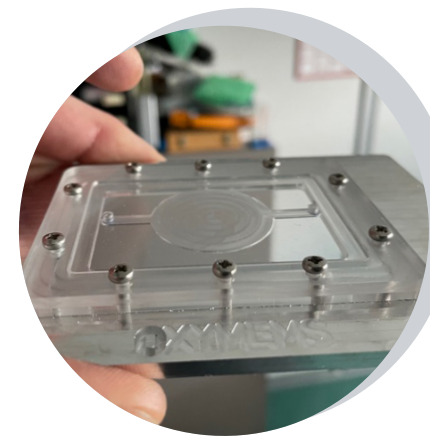
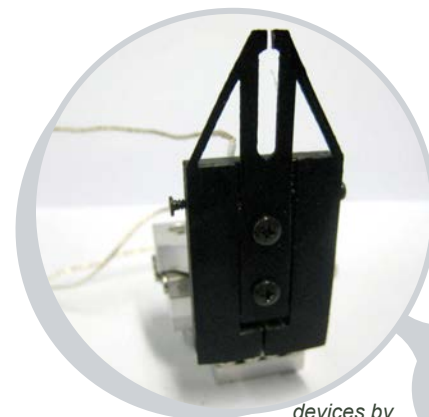
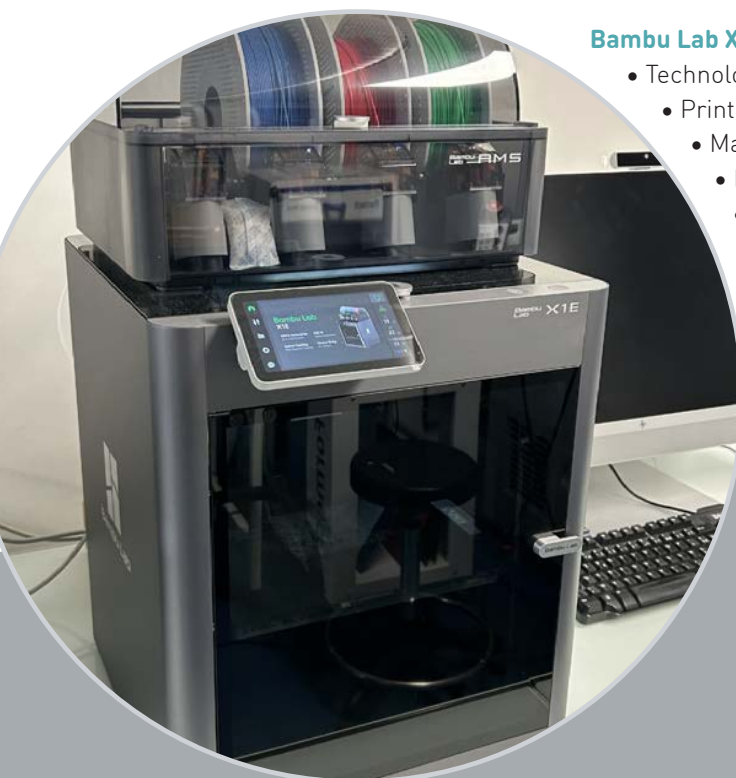
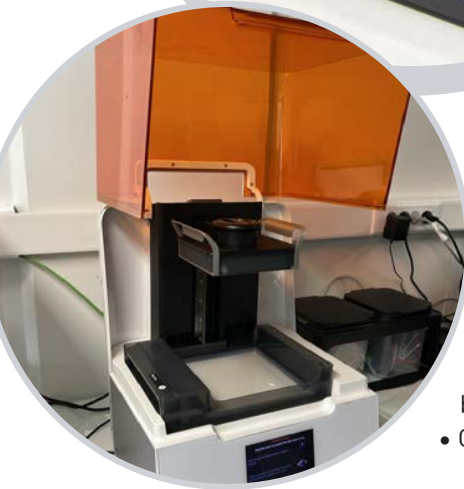
Whether for 3, 3 + 2 or 5 simultaneous, high precision or economical machining.

Compatible materials:

- Composites
- Aluminum
- Light alloys
- Wood
- Plastics
- Carbon fiber reinforced plastic
- Stainless steel
- Green ceramics

Machine capabilities:

- Milling
- Drilling
- 3D engraving



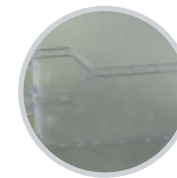
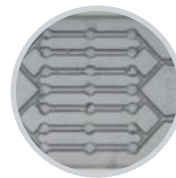
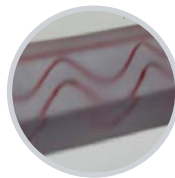


The Soft-lithography resource enables the development and characterization of microfluidic devices.
1 Full time employee

F3B



The Form 3B+ 3D printer from Formlabs is a 3D printer using the Low Force Stereolithography (LFS) technology, allowing to increase both print quality and dimensional accuracy with fine and precise details. The wide range of resins (biocompatible, translucent, clear, black, rigid, elastic) and the XY resolution of 25 μm (with layer thickness from 25 to 300 μm depending on the material used) offer many possibilities to design microfluidic chips with custom-made geometries and at low cost.



SPIN-PROCESSOR LAURELL WS-650-23 B

The Laurell WS-650-23 B spin coater system will accommodate up to $\varnothing 150\text{mm}$ wafers and $5\text{''} \times 5\text{''}$ [$127\text{mm} \times 127\text{mm}$] substrates, and features a maximum rotational speed of 12,000 RPM (based on a $\varnothing 100\text{mm}$ silicon wafer).

The WS-650 series is typically employed for Solvent, Base or Acid-based processing:

- Coating • Rinsing-Drying • Cleaning



THINKY MIXER ARV 310

The association of the vacuum function with the rotary and revolutionary movements allows the complete deaeration of almost all fluids.

The memory mode allows the user to reproduce the optimal conditions of their own mixes for high repeatability



Technical Description:

- Vacuum function : optimal bubble-free dispersion
 - Deaerated mixture of highly viscous materials
- Guaranteed without flow, sedimentation or foam during the operation
 - Modifiable RPM for mixtures of all types
 - Viscosity regulator

XUROGRAPHIC STATION

- Cricut explore Air 2
- For the cutting of thin film of polymer
- Laminating machine

CHARACTERIZATION AND MEASUREMENT STATION

- KRUSS goniometer
- Measurement of wettability and contact angles for surface characterization (hydrophobic, hydrophilic, super-hydrophilic...)
- Stereoscopic microscope
- For the assembly of devices and post-manufacturing control

PLASMA STATION

- PICO N2 and O2
- For surface treatment : cleaning and activation

PDMS STATION

- Thinky Mixer for the mixing and degassing of polymer
- Precision scale
- Oven
- Spincoater • Dessicator
- Heating plate
- Plasma torch for substrate activation

MACHINATING STATION

- CNC Milling machine, DATREON NEO
- Development of fluidics (devices) or mechanical compounds (molds) in polymer or hard materials
- Formlabs 3B+, Stereolithographic printer (SLA)

SOFT-LITHOGRAPHY RESSOURCES

USE OF DEVICES IN THE BIO-MICROFLUIDICS LABORATORY



PLASMA CLEANER : O2 AND AR PLASMA STATION

- Cleaning of surfaces (before bonding, soldering or gluing)
- Activation of surfaces (before printing, varnishing or gluing)
- Etching of surfaces (microstructuring of silicon or etching of PTFE)
- Coating of surfaces - plasmapolymerization (deposition of hydrophobic hydrophilic layers)



PLASMA TORCH ElectroTechnicProducts MODEL BD 20V

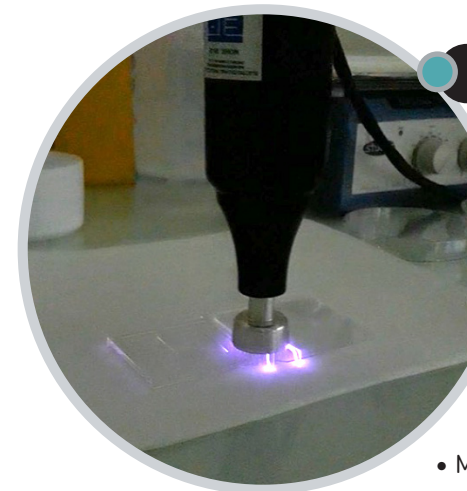
The Corona equipment enables a quick and easy treatment surface, and can be used to bond PDMS with glass or PDMS with PDMS very quickly (a few minutes).

Indeed the Corona tool will change the surface properties in much the same way as a traditional plasma cleaner treatment.

The corona produces a high voltage and high frequencies sparks at the tip of an electrode to ionize the air.

Main Characteristics:

- Device adapted for Soft-lithography applications
- Manual PDMS bonding
- Quick and easy PDMS bonding
- Create quickly strong link between PDMS with glass and PDMS with PDMS



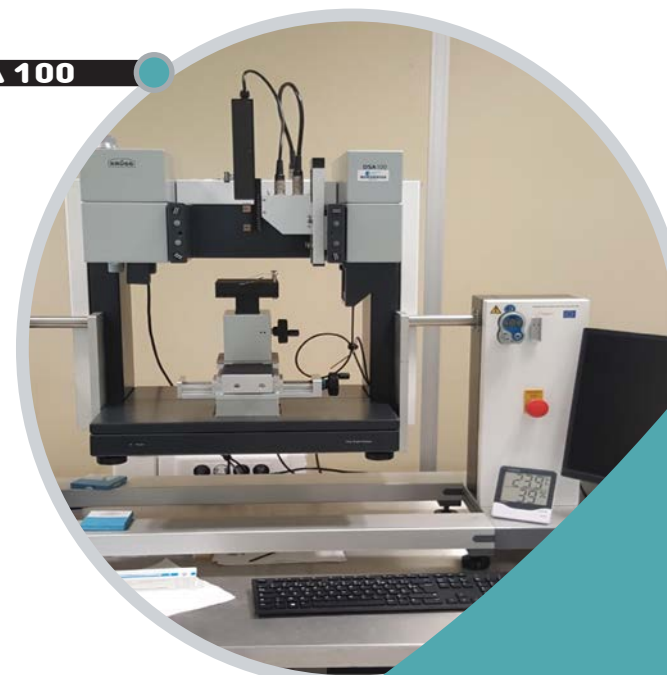
KRUSS GONIOMETER DSA 100

Measurement of wettability and contact angles for surface characterization (hydrophobic, hydrophilic, super-hydrophobic ...)

For wettability and wall angles measurements, surfaces characterization (hydrophilic, hydrophobic...) and analyzing wetting and coating processes. The Drop Shape Analyzer DSA100 is a system solution for tasks in the analysis of **wetting** and **adhesion** on solid surfaces.

Comprehensive analysis of solids and liquids

The DSA100 measures the surface tension of liquids using the **Pendant Drop** method. The results can be used to analyze the relationship between the wetting of the solid and the liquid properties.



BIO - MICRO FLUIDICS

Unit

BIO/MICRO FLUIDICS



Bio Micro Fluidic Manager : Aude Sivery

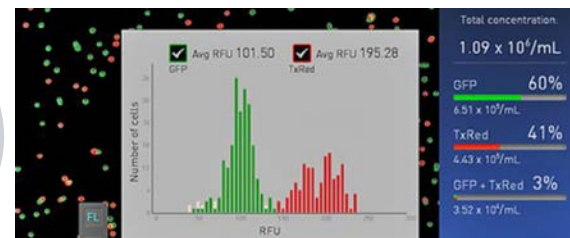
The Biomicrofluidic resource includes all the equipment necessary for cell culture, microscopy and microfluidics experiments.
1 Full time employee

CELLULAR BIOLOGY

Our L2 BioMicrofluidic laboratory is a biological lab dedicated to the confined experimentation of biologic agents classified in group 2 (French regulation, 16/07/2007) and of genetically modified organisms (GMOs) to be confined in a level 2 laboratory (HCB manual, 30/11/2014).

The biological laboratory contains all equipments required for cellular biology :

- **Three** biological safety cabinets
- **Two CO2 incubator** for common cell lines
- **Small CO2 incubators** dedicated to microfluidic experiments
- **Automated cell counter**
- **Autoclave** : for the sterilization of solids and liquid trashes as well as microdevices



3D BioInk PRINTER

3D bioprinting is the utilization of 3D printing like techniques to combine cells, growth factors, and biomaterials to fabricate biomedical parts that maximally imitate natural tissue characteristics.

The 3D BioX from CellInk utilizes the layer-by-layer method to deposit bioinks to create tissue-like structures that are later used for biological research.

Features

- Temperature Controlled Printbed (4 C to 60 C)
- Compatible with standard petri dishes, multi wellplates, and custom inserts
- Compatible with a **wide range of bioinks in CellInk library**
- Clean chamber technology with UV-C germicidal lamps and HEPA H14 dual-filter system
- Exchangeable Photocuring Modules : 365 nm and 405 nm



www.3dnatives.com



SYRINGES PUMPS NEMESYS

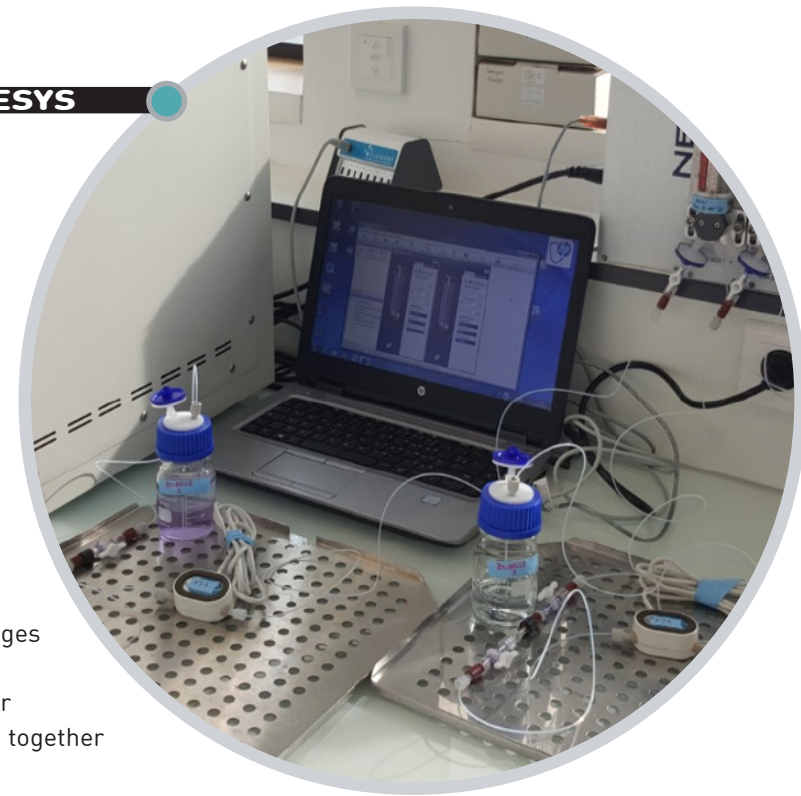
Nemesys medium pressure pumps are used for the precise injection of liquids into systems operating at higher pressure levels or with viscous liquids.

The NeMESYS syringe pumps allow emptying and filling syringes by the relative linear movement of a syringe-and a piston holder.

The NeMESYS syringe pump serves for precise and pulsation-free dosing of fluids in the range of nanoliters per second up to milliliters per second.

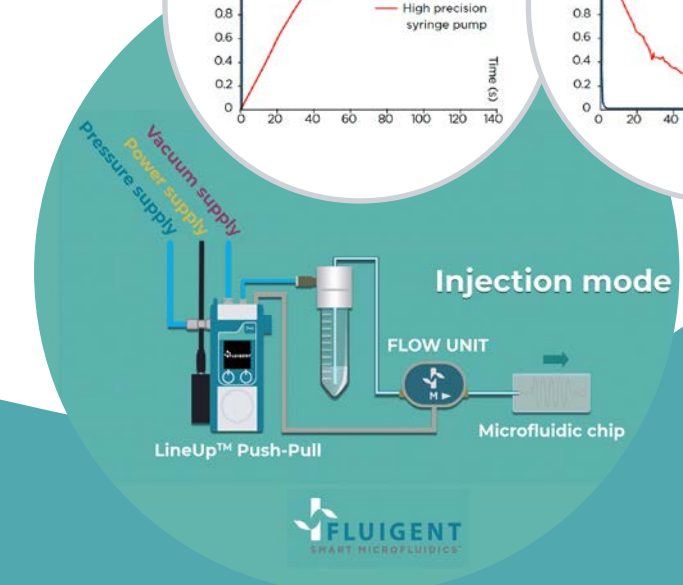
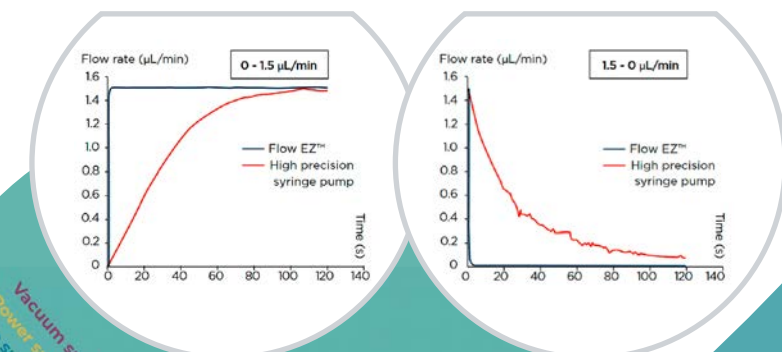
Benefits:

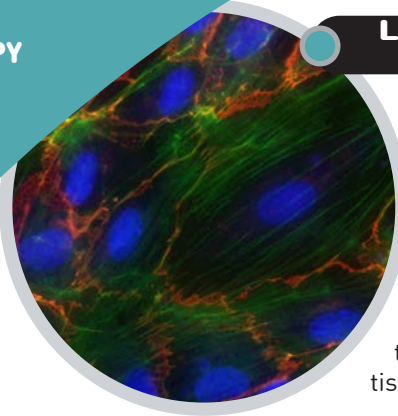
- Support of high-pressure valves for the creation of continuous fluid streams
- Glass syringes or four sizes of stainless steel syringes are available
- Accurate dosing for pressure levels of up to 200 bar
- Modular system: multiple modules can be plugged together



PRESSURE AND VACUUM CONTROLLER : LINEUP PUSH-PULL FLUIGENT

The **LineUp™ Push-Pull** is a standalone controller with the ability to deliver **finely regulated pressure** or a **vacuum** through a single outlet over the range of **-800 to +1000 mbar**. It can be used **without a PC** or controlled with **Fluigent Software Solutions** to benefit from **control in real-time**, protocol **automation**, graphic displays and **custom integration**. Combined with a **FLOW UNIT** it allows for **direct control of flow rate**.



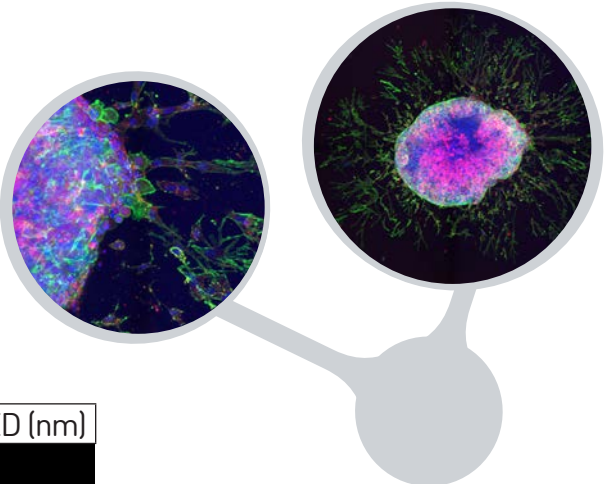


LEICA DMI8 MICROSCOPE ENVIRONMENTAL

- This microscope makes it possible to make acquisitions in phase contrast and epi-fluorescence
 - It is equipped with a motorized X, Y and Z stage
 - The Adaptive Focus Control (AFC) allows long-term acquisitions without focus drift over time
 - The temperature and CO2-controlled environmental enclosure allows real-time imaging of devices possibly coupled to microfluidics. The large chamber incubation system is used for the stabilization of temperature and humidity which is designed for pre-heating cell and tissue cultures

HUVEC cells. Hoechst staining for the nucleus (blue). Alexa fluor 546 staining for VE-cadherin (red) and Alexa fluor 488 staining for actin staining (green). 100X immersion oil objective

Spheroid inside a 3D perfusion microfluidic device from Ibidi. Co-culture of HUVEC and MCF7 cells. MCF7-mcherry cells appear in red, Actin filament in green and cells nucleus in blue



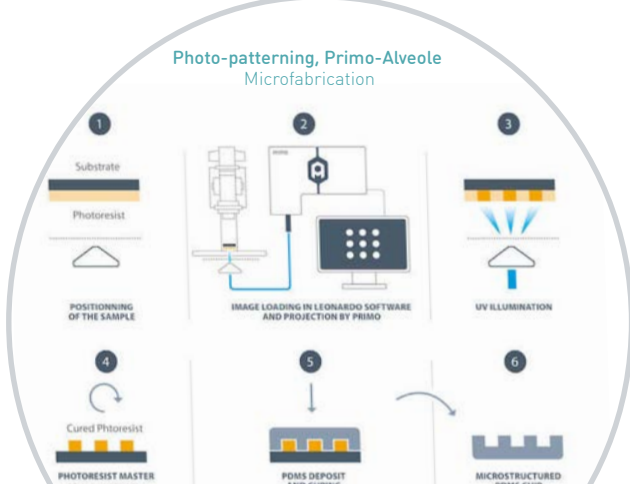
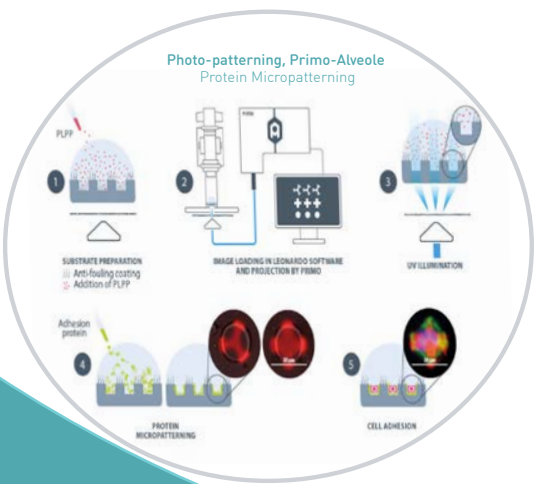
Filter Cubes	Excitation (nm)	Emission (nm)	Associated LED (nm)
DAPI	325-375	435-485	365
FITC	460-500	512-542	460,470,490,500
Rhodamine	541-551	565-605	550
Y5	590-650	662-738	595,635

PHOTO-PATTERNING, PRIMO-ALVEOLE

www.alveolab.com

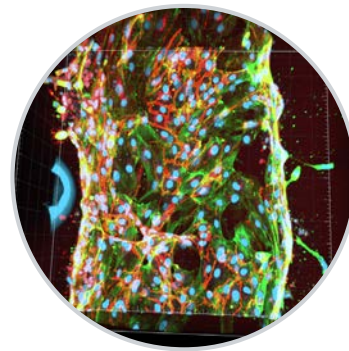
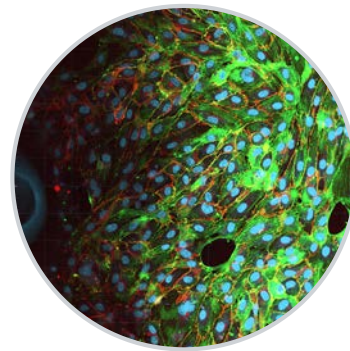
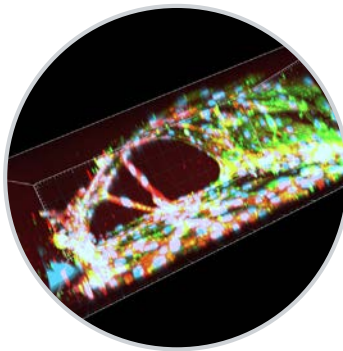
The PRIMO maskless photopatterning system (DMD based) can engineer custom in vitro cell microenvironments through three techniques: micropatterning, hydrogel structuration and microfabrication.

- **Micropatterning:** Allows to precisely control cell adhesion to mimic in vivo phenotypes, isolate them or place them in reproducible conditions for standardized assays.
- **Microfabrication:** PRIMO maskless DMD-based photopatterning system can perform greyscale photolithography on greyscale resists to create complex 3D molds such as ramps, curving wells or microfluidic chips for organ-on-a-chip applications.
- **Hydrogels:** As a photopatterning system, PRIMO can also polymerize and photo-scission most commonly used hydrogels for applications such as 3D cell culture or permeable hydrogel membranes polymerization within microfluidic chips.
- **Fields of application:** The system allows to better study the behavior and development of living cells in a broad range of applications, such as: cytoskeleton dynamics, cell adhesion force measurement, cell confinement, cell migration, tissue engineering, spheroids.

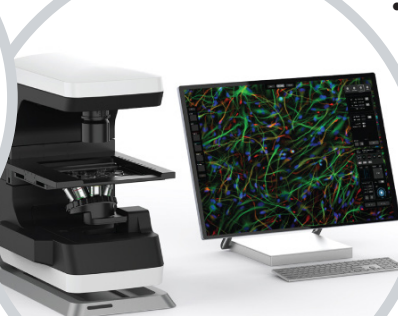


ANDO CONFOCAL BENCHTOP MIROSCOPE BC43

- Laser confocal microscope
- Widefield fluorescence microscopy, Transmitted light microscopy, Confocal and Super-resolution imaging
- Image monolayer and 3D cell cultures
- Follow cell dynamics : intercellular behaviour, migration and division
- Introductory **Imaris** Quantify package: Visualise 2D/3D/4D images, Create high-resolution snapshots and multi-dimensional movies
- **Objective lens** : Dry 2X, 10X, 20X, 40X, 60X and 60X oil immersion
- **Lasers** : 405nm, 488 nm, 561 nm, 638 nm
- **Filters** : DAPI (445/20 nm), FITC (529/24 nm), Rhod (595/31 nm), Far-Red (708/75 nm)



UP-RIGHT/FAMILY AUTOMATED



Revolution Automated Microscope

- Revolution Upright & Inverted Capability
- Multi-Dimensional Imaging: Time-Lapse, Multi-Point, Mosaic, Multi-Channel, Z-Stack
- Motorized Epi-Fluorescence: 5 Channels (DAPI, FITC, TRITC, CY5, TxRED)
- Objectives Lens : 1.25 X, 4X, 10X, 20X, 40X, 60X and 60X immersion oil
- Microscope Environmental Incubator Enclosure : Includes Controller for Temperature for live-cell viability. Ambient to 40°C with Stage Top humidity chamber, includes CO2 Mixer

- **Live Cell Imaging**
View and capture live samples with automated time-lapse microscopy.
- **Image Stitching**
Capture and stitch to form largeFOV high resolution images.

- **Stage Top Incubator**
Ensures optimal conditions for maintaining specimen viability.
- **Z-Stack**
Acquire and stack images at multiple focal planes.

- **Multi-Channel**
Capture and overlay multiple wavelengths in Fluorescence.
- **Auto Focus**
Automatically find and track best Z-plane(s) for focus.

- **Multi-Point**
Set multiple acquisition points to view and revisit over time.
- **Hyperscan**
High-speed image stitching



Nous remercions nos soutiens

IMPLEN NANOPHOTOMETER NP80

UV/Vis spectrophotometer for NanoVolume and cuvette applications.
Quantify DNA, RNA, proteins.

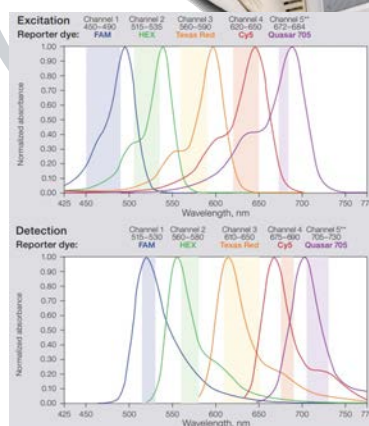
- Starting with 0.3 µl of sample
- 3.5 – 6.0 seconds per reading
- Scan range 200 – 900 nm
- Detection range (nanovolume):
 - dsDNA: 1 ng/µl to 16,500 ng/µl (N50: 5 ng/µl to 7,500 ng/µl)
 - BSA: 0.03 mg/ml to 478 mg/ml (N50: 0.15 mg/ml to 217 mg/ml)
- Photometric range (cuvette) : 0 - 2.6 A



CFX OPUS REAL TIME PCR SYSTEM

Quantitative PCR system

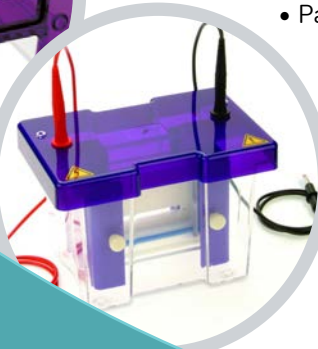
- 96 well plate
- Temperature range, 4–100 °C
 - Accuracy ±0.2 °C of programmed target at 90°C
 - Uniformity, ±0.3 °C well-to-well after 10 sec of arrival at target
- Optical Detection
 - Range of excitation/emission wavelengths 450–684 nm / 510–730 nm
 - Scan time : 12 s for all channels, 3 sec FAM/Sybr only
- Thermal gradient
 - Operational range, 30–100 °C
 - Programmable span, 1–24 °C



ELECTROPHORESIS STATION

Systems suitable for nucleic acids and protein electrophoresis

- Programs: multistep (up to 9 steps) methods and timed runs with a choice of constant voltage, current, or power output :
 - 0–500 V, fully adjustable in 1 V steps
 - 0.01–2.5 A, fully adjustable in 0.001 A steps
 - 1–500 W, fully adjustable in 1 W steps
- Timer control : 1 min–99 hr 59 min
- Pause/resume function
- 4 pair recessed banana jacks floating in parallel
- User optional run completion after an AC power failure
- Constant voltage, constant current, or constant power operation with automatic Crossover
- Stackable case with adjustable viewing angle via flip down legs



CPER IMITECH • CPER TECSANTE • CPER WAVETECH

EQUIPEX NANOFUTUR • PEPR ELECTRONIQUE



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Site litho : <https://litho.priv.iemn.fr/bddlitho/bdd.php>
(uniquement accessible au LCI)

Comité Editorial : François Vaurette

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e.C^om



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Institute of Electronics, Microelectronics
and Nanotechnology

UMR CNRS 8520

Multi-Physics Characterization Platform

PCMP Plateforme de Caractérisation Multi-Physique

IEMN stands for Institute of Electronics, Microelectronics and Nanotechnology, a laboratory created in 1992 as a joint research unit of 5 institutions: Lille University, CNRS, Polytechnic University Hauts-de-France, JUNIA/ ISEN, Ecole Centrale Lille. The Institute's scientific policy is based on flagship application projects of societal interest (Transport, Energy, Health, Internet of Objects, Neuromorphic Technologies, UHD Telecommunication) and three transverse scientific and technological axes (Materials, Devices, Nano-Characterization).

IEMN's research is performed based on a strong connection between its 22 research groups and its technological (Micro Nanofabrication and Multi Physics Characterization) platforms in which cutting-edge equipment are operated by a highly qualified technical staff.

The scientific policy of the Institute is declined in five research Departments:

- Materials, Nanostructures and Devices
- Micro/Nano/Biosystems, Waves and Microfluidics
- Micro, Nano and Optoelectronics
- Telecommunications Technologies and Smart Systems
- Acoustics and Integrated Systems•

470 people work at IEMN, in research groups, platforms, and administrative services. At the forefront of education and technological research, and owing to numerous dynamic international collaborations, IEMN hosts PhD and graduate students coming from 30 different countries. IEMN designs, manufactures and characterizes devices and systems for Electronics, Photonics, Energy Storage and Harvesting, Bio-micro-technologies, Sensors, Integrated Systems and Instrumentation. Moreover, as evidenced by numerous patents plus spin-off's creations, IEMN demonstrates its effectiveness in promoting and facilitating technology transfer of innovations emanating from its research groups.

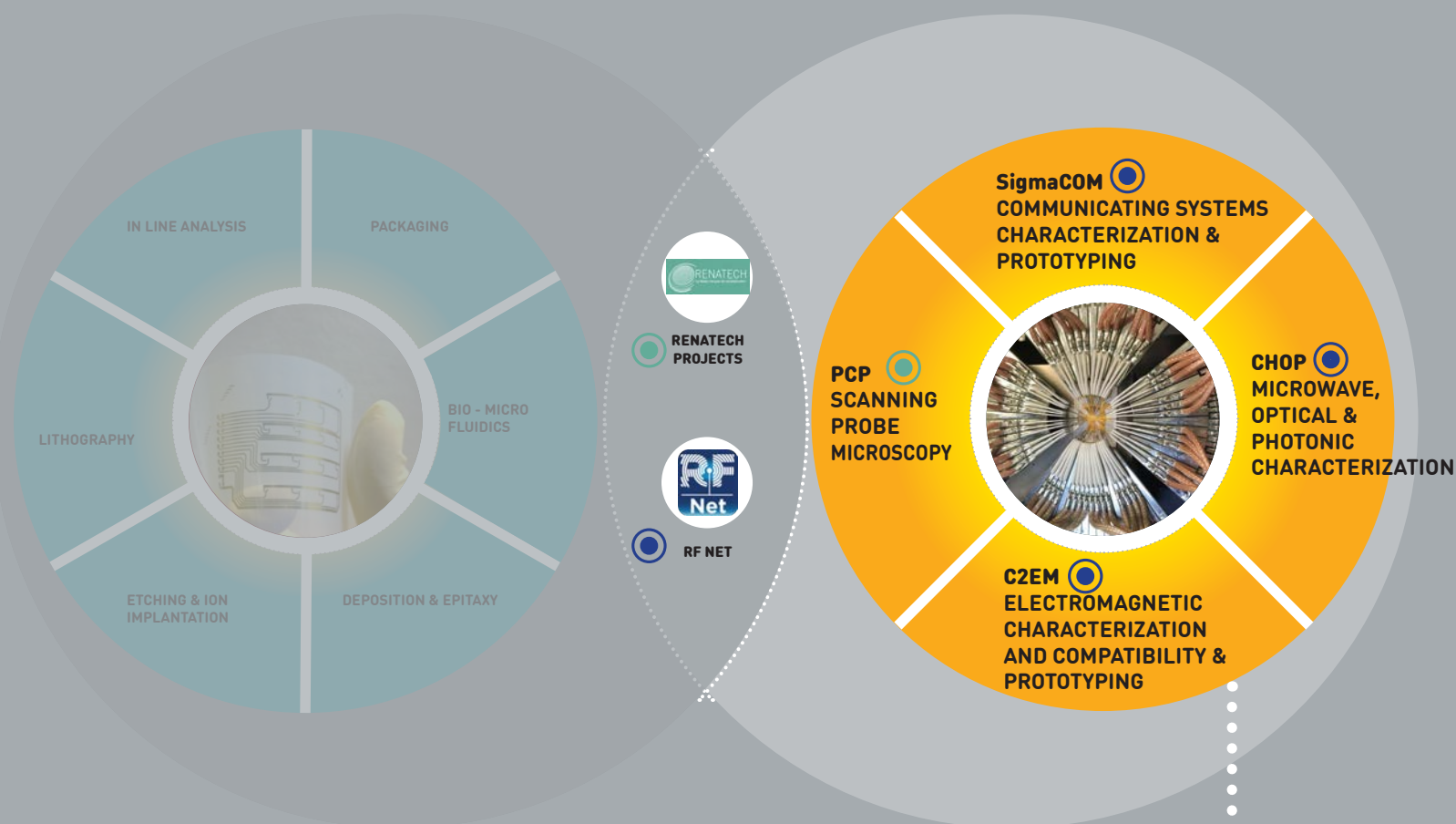
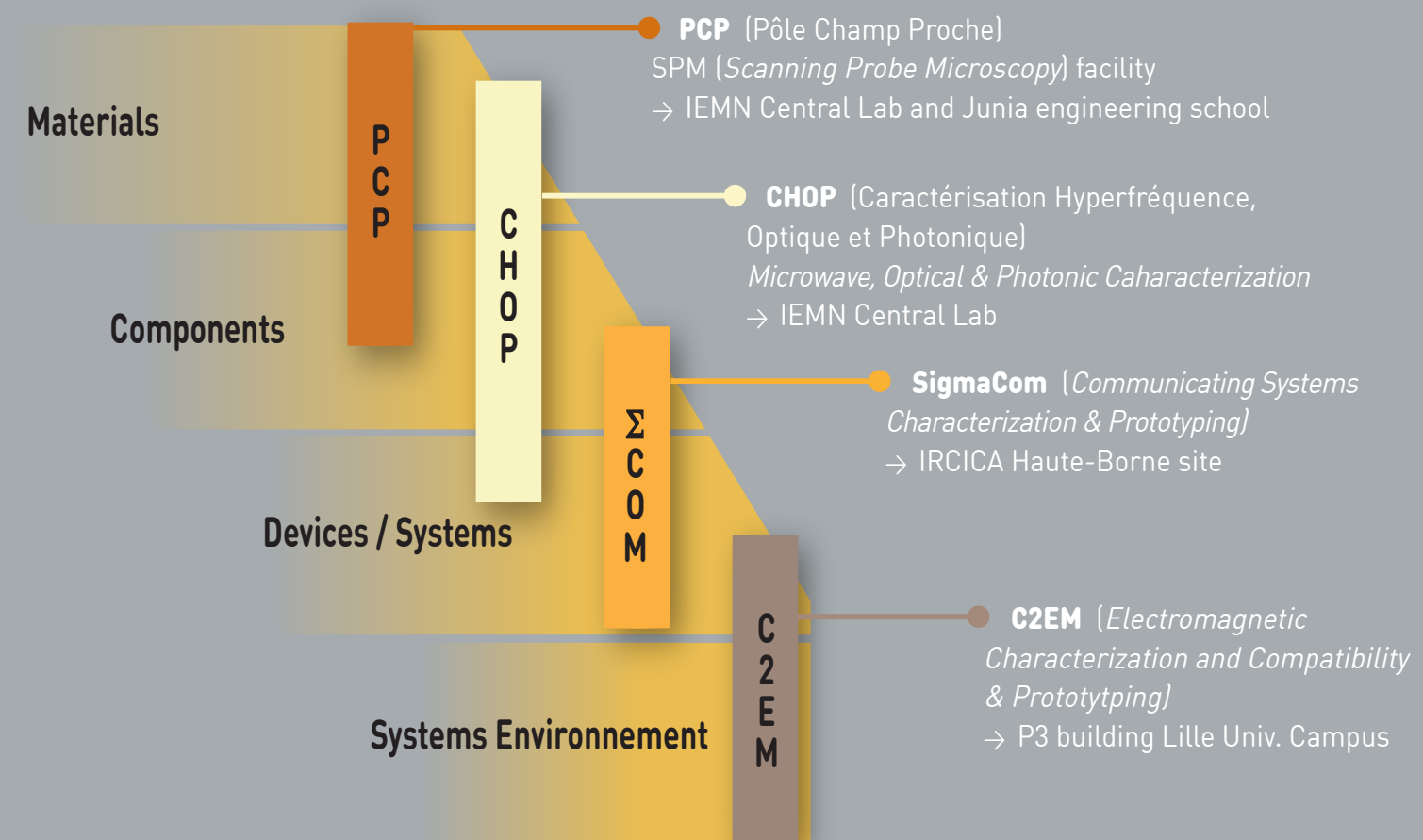
The Multi-Physics Characterization Platform

The Multi-Physics Characterization Platform is the instrumental facility of IEMN dedicated to characterization of materials, devices and electronic systems, from materials at the nanoscale to electronic systems in their environment. It gathers 4 services localized on Lille University campus «Cité Scientifique», Haute-Borne site and Junia engineering school (Lille center town).

In addition to characterization, PCMP's activities also include instrumental development and prototyping (design, production and testing) in the SigmaCom and C2EM services.

The PCMP services belong to the Renatech (PCP) and Rf-NET (CHOP - SigmaCom -C2EM) networks: we work both with national and international partners from academia or industry.

→ **Access to the PCMP Platform is regulated.**
Please contact the head of each PCMP Service to request access.



MULTI-PHYSICS CHARACTERIZATION PLATFORM

I	PCP	
	Scanning Probe Microscopy	
	• Air domain	I. 1-4
	• UHV domain	I. 5-8
II	CHOP	
	Microwave, Optical and Photonic Characterization	
	• Nanocharacterization	II. 1-2
	• DC-Low Frequency	II. 3-4
	• Hyper-Frequency	II. 5-8
	• Millimetric & THz	II. 9-12
	• Noise measurement	II. 13-14
	• Power Measurement	II. 15-18
III	SIGMACOM	
	Communicating Systems Characterization & Protoyping	
	• Analog and digital communication systems	III. 1-8
	• Optical communication systems	III. 9-12
	• Prototyping	III. 13-16
IV	C2EM	
	Electromagnetic Characterization and Compatibility & Prototyping	
	• EMC chambers and cells	IV. 1-2
	• EM site characterization	IV. 3-4
	• Massive Multiple Input Multiple Output System Acquisition	IV. 5-6
	• Prototyping	III. 13-16



pcmp-contact@iemn.fr



PCP

The Scanning Probe Microscopy service named **"Pole Champ Proche"** supplies premium tools, to observe and manipulate atoms, molecules or nanoscale objects on the micro to subnanometer scale, making these instruments essentials to Nanoscience and Nanotechnology. The PCP facility is organised into 2 domains depending on the measurement environment:

- AIR domain for microscopes operating in air ambient, liquid or controlled gas atmosphere
- UHV domain for microscopes operating under Ultra High Vacuum

With 8 instruments and 400m² of area in a ISO8-certified environment localized on the ground floor of IEMN, the facility hosts about 30 expert users. Part of the instruments are on free access and can be booked online. One day training for beginners is provided in request. The team is composed of 3 permanent engineers providing internal, external academic and industrial services in the framework of the RENATECH national network. Their mission concern also the development of new instruments and experimental techniques in collaboration with users, Start-up and SPM companies.

Head of PCP
M. Berthe



- **Air domain SPM's**
ICON
DIMENSION
MULTIMODE
BIOSCOPE
LASER VIBRAMETER

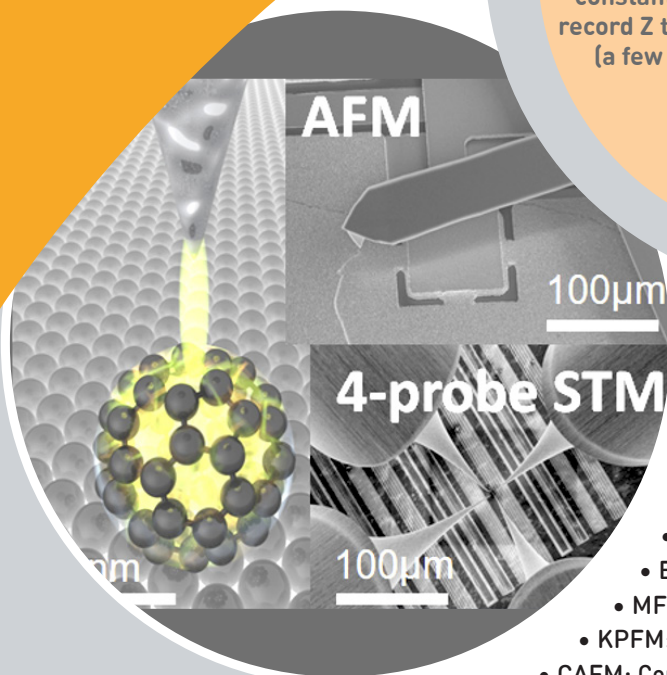
I. 1-4

- **UHV domain SPM's**
VTAFM
JT-SPM
LT-STM
NANOPROBE

I. 5-8

pcp-contact@iemn.fr

The Scanning Probe Microscope is a recent technique (Nobel prize in Physics 1986) where a probe (tip) interacts with the surface of the sample at a very short distance (nanometer scale). This interaction is kept constant while moving the tip, allowing to record Z topography maps at the nano-scale (a few nm to 100µm) depending on the microscope model.



The probe interacts in contact (C) or non-contact (NC) mode and can work in static or dynamic mode. Various physical characteristics of the surface can be addressed through different modes of measurement:

- STM: Scanning Tunneling Microscopy (NC),
- LDOS: Local Density of Electronic States (NC)
- AFM: Atomic Force Microscopy (C, NC), Force Spectroscopy (C)
- EFM: Electrostatic Force Microscopy (NC)
- MFM: Magnetic Force Microscopy (NC)
- KPFM: Kelvin Probe Force Microscopy (NC)
- CAFM: Conductive Atomic Force Microscopy (C)
- PFM: Piezoelectric Force Microscopy (C)
- SCM: Scanning Capacitance Microscopy (C)
- SThM: Scanning Thermal Microscopy (C)

→ APPLICATION EXAMPLES

- Topographic monitoring of technological processes and material growth: Molecular beam epitaxy, etching, film deposition, lithography
- Local characterization in contact mode of the physical properties of materials: Electrical conductivity by CAFM or thermal conductivity by SThM, piezoelectric response by PFM, adhesion forces and mechanical properties by force spectroscopy
- Local characterization in non-contact mode of the physical properties of the surface: Measurement of electrostatic and magnetic forces (EFM, MFM), measurement of charges, measurement of surface potential (KPFM), local density of states (STM/STS)

→ ADVANTAGES & LIMITATIONS

- 3D nanometric topography measurement, sub nanometric roughness measurement
- Simultaneous local physical imaging and characterization
- Tip Convolution
- Low scan speed

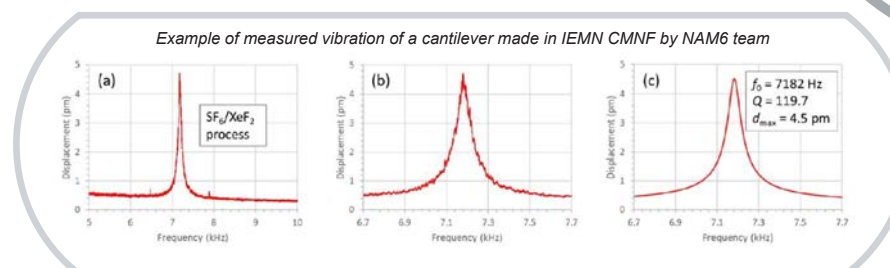
LASER VIBROMETER MSA 500

Maxime Berthe Marc Faucher

Visualizing surface deformations, knowing the speed, frequency and distance of displacement of a vibrating element, are essential information for MicroElectroMechanical Systems (MEMS). This equipment is based on Doppler effect. Thanks to a laser and an interferometer it is possible to know how an element vibrates. It is possible to map vibrations modes of a device.

→ ADVANTAGES & LIMITATIONS

- Max displacement +/- 75nm, frequency 0 up to 24MHz



Experimental and modeled resonance curves of a microcantilever fabricated the mixed SF_6/XeF_2 process. (a) 5-10 kHz frequency sweep, (b) zoom over 1kHz, and (c) modeled resonant frequency curve. The inset to (b) shows a microcantilever fabricated using this process.

DRIVE AFMs NANOSURF

Louis Thomas

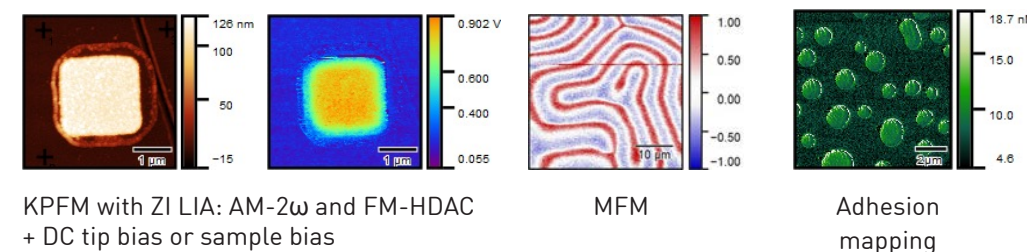
- Tip Scanning Atomic Force Microscope
- 100 x 100 µm² (x,y) 20 µm z
- Contact, Resonant Intermittent Contact, non-Resonant Intermittent Contact

→ Photothermal Excitation

- Environments: gas or liquid
- Electro-chemical Cell + Biologic SP300 Bipotentiostat var. T up to 200°C, Mag. Field (110 mT o-p, 780 mT i-p) ZI LIA 50 MHz

• Full integration into Mbraun Glovebox

Argon atmosphere (O_2 , H_2O < 0.1 ppm), Noise: < 80 pm RMS with gas circulation



KPFM with ZI LIA: AM-2ω and FM-HDAC + DC tip bias or sample bias

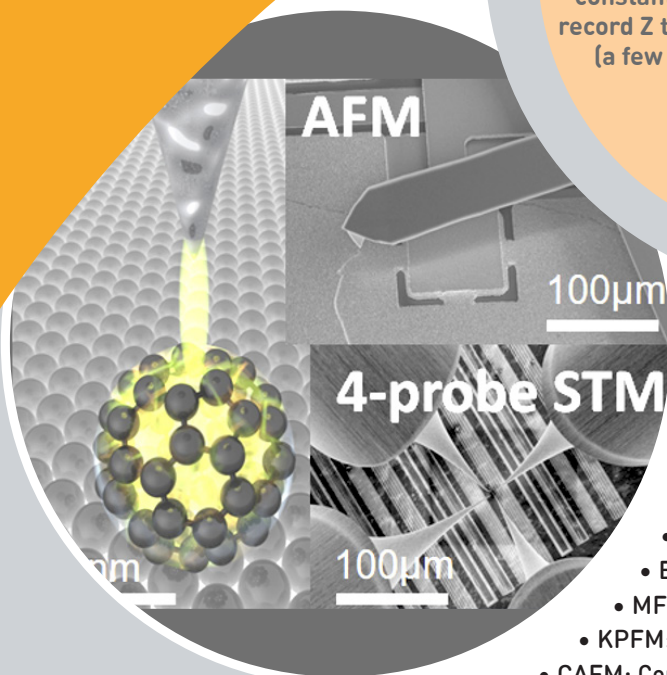
MFM

Adhesion mapping

Available modes: Contact, Tapping, Wavemode, C-AFM, SSRM, KPFM, MFM, F-D, EC-AFM
Work in progress: PFM, SThM, AFM-SECM

Ambient conditions or under controlled atmosphere

The Scanning Probe Microscope is a recent technique (Nobel prize in Physics 1986) where a probe (tip) interacts with the surface of the sample at a very short distance (nanometer scale). This interaction is kept constant while moving the tip, allowing to record Z topography maps at the nano-scale (a few nm to 100µm) depending on the microscope model.



The probe interacts in contact (C) or non-contact (NC) mode and can work in static or dynamic mode. Various physical characteristics of the surface can be addressed through different modes of measurement:

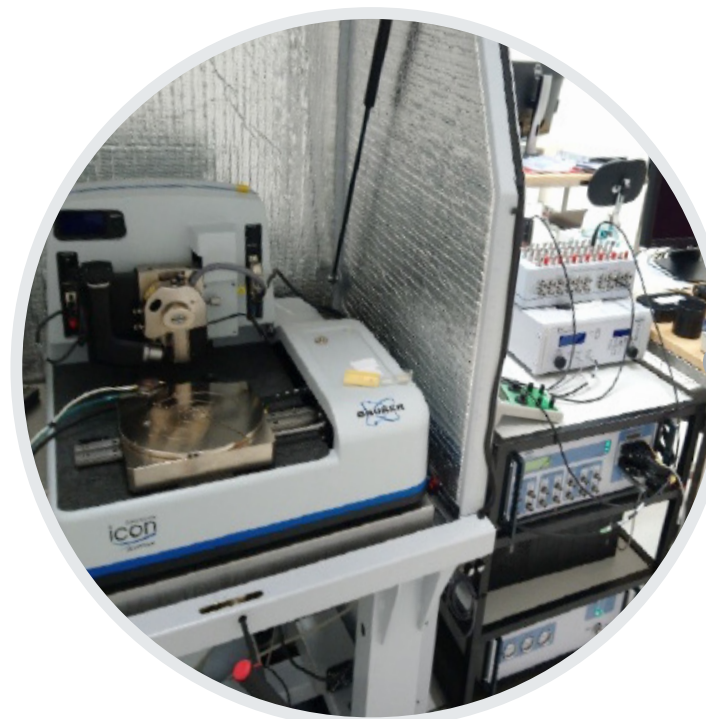
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- SThM: Scanning Thermal Microscopy (C)

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→ ADVANTAGES & LIMITATIONS

- 3D nanometric topography measurement, sub nanometric roughness measurement
- Simultaneous local physical imaging and characterization
- Tip Convolution
- Low scan speed



ICON

👤 Louis Thomas

- **Sample dimension** : 5mm square to 20cm diameter
- **Scan range** : 10nm to 100µm (X and Y linearization feedback: closed loop) - Max. Z range: 10µm
- **Resolution** : Lateral: nanometric - Vertical 30pm
- **Working Mode** : AFM Tapping, AFM Peakforce, EFM, KPFM, CAFM, PeakForce TUNA, PFM, SThM, Force spectroscopy
- **Environnement** : Ambient air, Nitrogen gas
- **Temperature** : -25°C to 250°C

→ APPLICATIONS

- PeakForce
- Thermal chuck for small sample

→ ADVANTAGES & LIMITATIONS

- Large sample, large coarse displacement of the chuck (2µm resolution)
- Acoustic and vibrational Noise sensitive

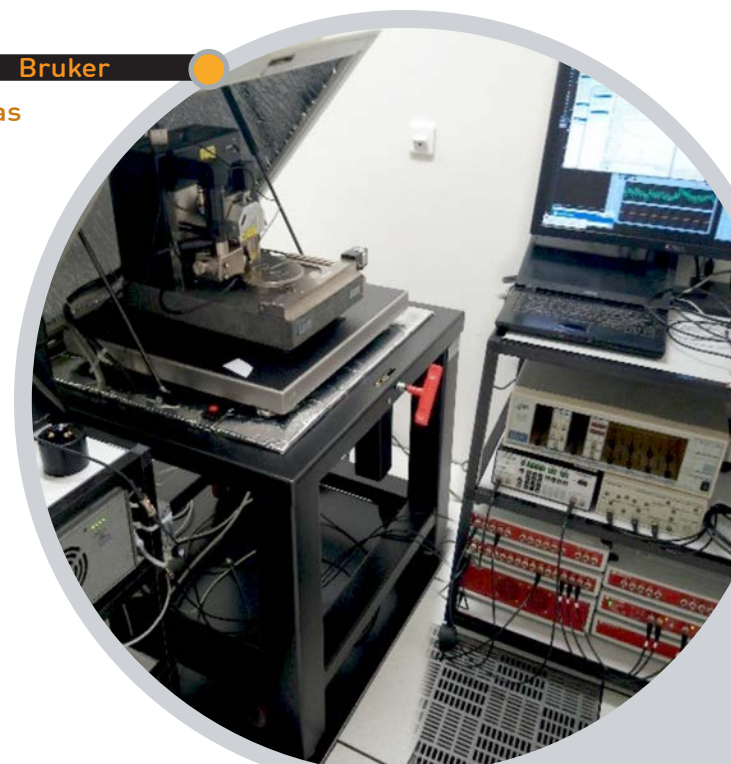
DIMENSION Bruker

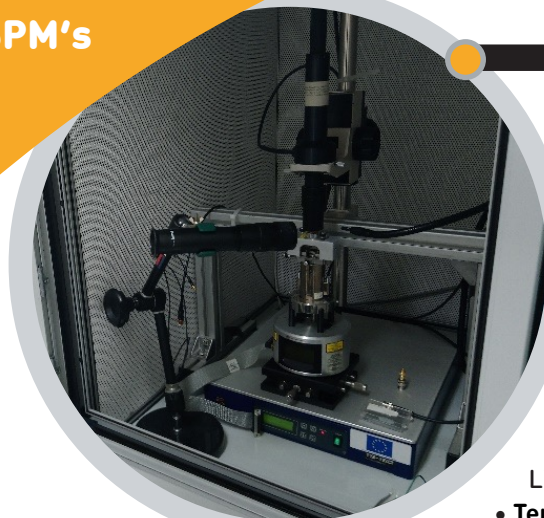
👤 Louis Thomas

- **Sample dimension** : 5mm square to 20cm diameter
- **Scan range** : 10nm to 100µm - Max. Z range: 6µm
- **Resolution** : Lateral: nanometric - Vertical 50pm
- **Working Mode** : AFM Tapping, EFM, KPFM, CAFM, PFM, SThM, Force spectroscopy, SCM
- **Environnement** : Ambient air, Nitrogen gas
- **Temperature** : Ambient

→ ADVANTAGES & LIMITATIONS

- Large sample, large coarse displacement of the chuck (2µm resolution)
- Acoustic and vibrational Noise sensitive





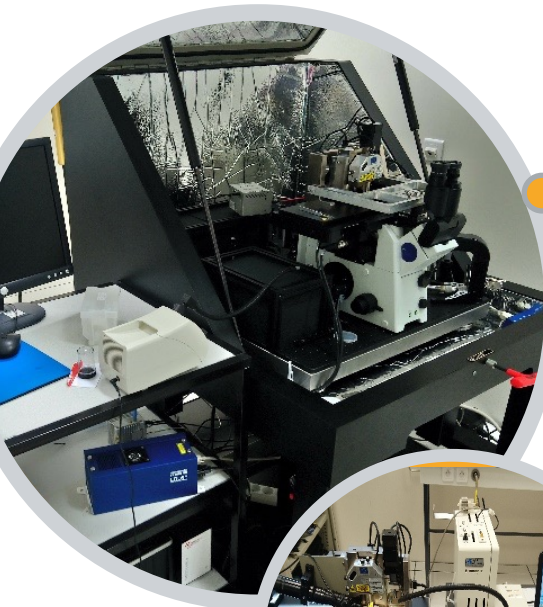
MULTIMODE Bruker

Louis Thomas

- **Sample dimension** : 5mm square to 15mm diameter
- **Scan range** : 10nm to 10 or 100µm (two scanners available) - Max. Z range: 2 or 5µm
- **Resolution** : Lateral: nanometric - Vertical 30pm
- **Working Mode** : AFM Tapping, EFM, KPFM, CAFM, PFM, Force spectroscopy
- **Environnement** : Ambient air, Nitrogen gas and Liquid
- **Temperature** : Ambient

→ ADVANTAGES & LIMITATIONS

- Low noise imaging
- Small sample
- Limited coarse displacement



BIOSCOPE Bruker

Louis Thomas

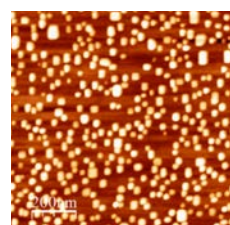
- **Sample dimension** : 5mm square to 5cm diameter
- **Scan range** : 10nm to 100µm - Max. Z range: 6µm
- **Resolution** : Lateral: nanometric - Vertical 80pm
- **Working Mode** : AFM Tapping
- **Environnement** : Ambient air and liquid
- **Temperature** : Ambient

→ APPLICATIONS

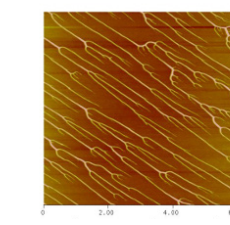
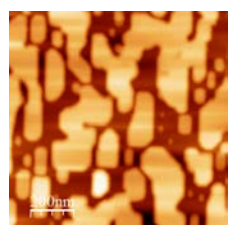
- In situ electrochemical growth monitoring

→ ADVANTAGES & LIMITATIONS

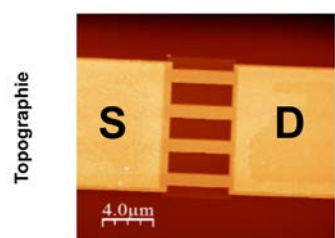
- Tip Enhanced Raman Spectroscopy (TERS) tip optical bench
- Acoustic and vibrational Noise sensitive



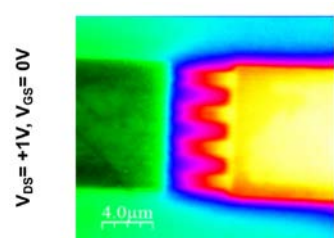
2D-3D growth GaSb/GaAs (AFM)



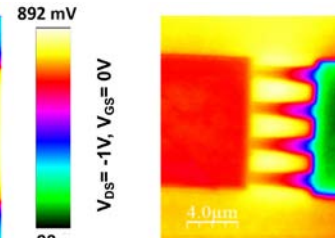
Collagen on silicon surface



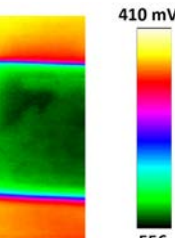
Topographie



$V_{DS} = +1V, V_{GS} = 0V$

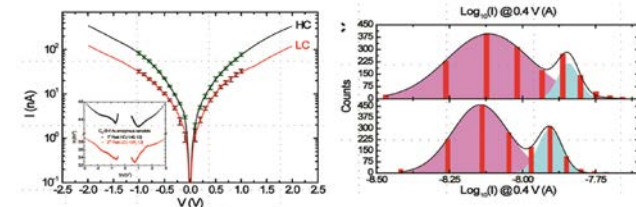
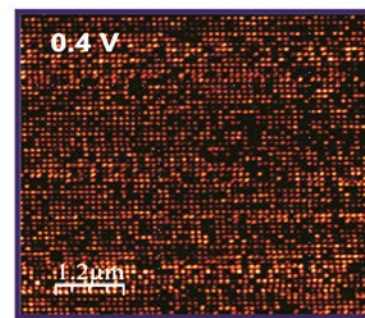
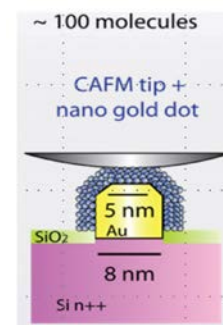


892 mV
 $V_{DS} = -1V, V_{GS} = 0V$

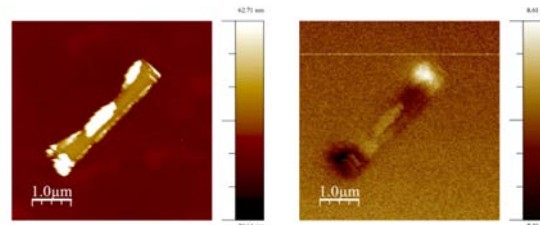


410 mV
-556

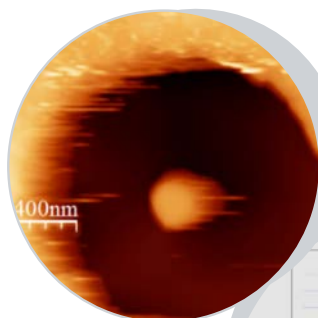
Gas sensing transistor polarization (KPFM)



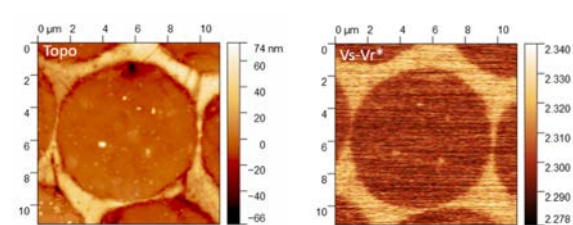
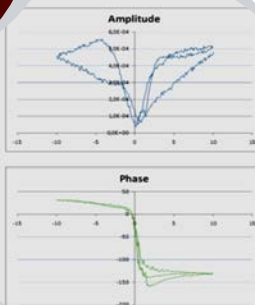
Conducting AFM statistics from a large array of sub-10 nm molecular junctions



Topo and MFM image of ferromagnetic domain wall position in multiferroic heterostructures



Topo and PFM cycle
Of a 60nm PZT dot
(1pm displacement sensitivity)



Topography and thermal conductivity of carbon fiber in epoxy matrix (AFM-STHM)

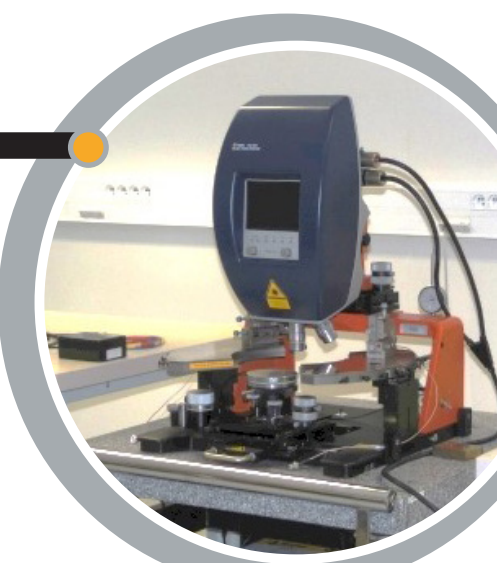
LASER VIBROMETER MSA 500

Maxime Berthe Marc Faucher

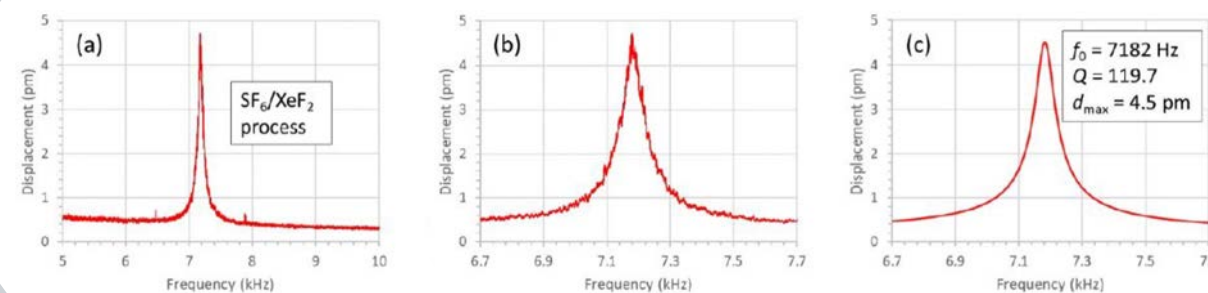
Visualizing surface deformations, knowing the speed, frequency and distance of displacement of a vibrating element, are essential information for MicroElectroMechanical Systems (MEMS). This equipment is based on Doppler effect. Thanks to a laser and an interferometer it is possible to know how an elements vibrates. It is possible to map vibrations modes of a device.

→ ADVANTAGES & LIMITATIONS

- Max displacement +/- 75nm, frequency 0 up to 24MHz

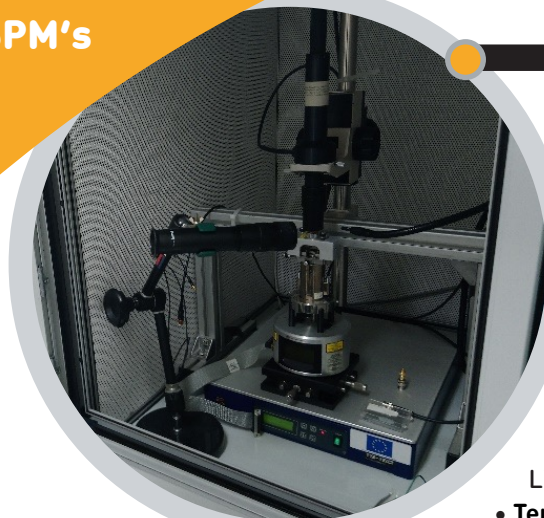


Example of measured vibration of a cantilever made in IEMN CMNF by NAM6 team



Experimental and modelled resonance curves of a microcantilever fabricated the mixed SF_6/XeF_2 process.
(a) 5-10 kHz frequency sweep, (b) zoom over 1kHz, and (c) modelled resonant frequency curve.

The inset to (b) shows a microcantilever fabricated using this process.



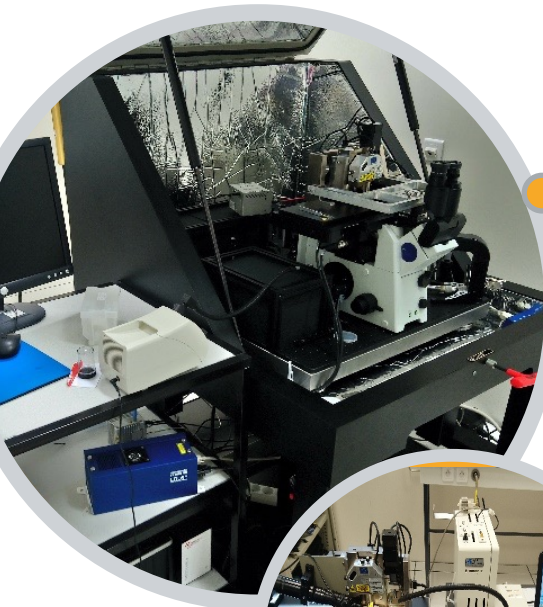
MULTIMODE Bruker

Louis Thomas

- **Sample dimension** : 5mm square to 15mm diameter
- **Scan range** : 10nm to 10 or 100µm (two scanners available) - Max. Z range: 2 or 5µm
- **Resolution** : Lateral: nanometric - Vertical 30pm
- **Working Mode** : AFM Tapping, EFM, KPFM, CAFM, PFM, Force spectroscopy
- **Environnement** : Ambient air, Nitrogen gas and Liquid
- **Temperature** : Ambient

→ ADVANTAGES & LIMITATIONS

- Low noise imaging
- Small sample
- Limited coarse displacement



BIOSCOPE Bruker

Louis Thomas

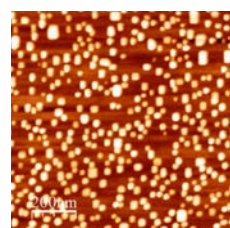
- **Sample dimension** : 5mm square to 5cm diameter
- **Scan range** : 10nm to 100µm - Max. Z range: 6µm
- **Resolution** : Lateral: nanometric - Vertical 80pm
- **Working Mode** : AFM Tapping
- **Environnement** : Ambient air and liquid
- **Temperature** : Ambient

→ APPLICATIONS

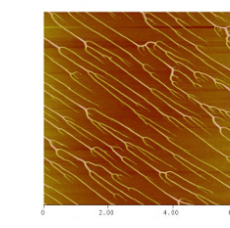
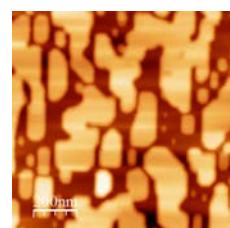
- In situ electrochemical growth monitoring

→ ADVANTAGES & LIMITATIONS

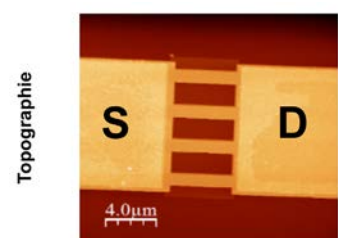
- Tip Enhanced Raman Spectroscopy (TERS) tip optical bench
- Acoustic and vibrational Noise sensitive



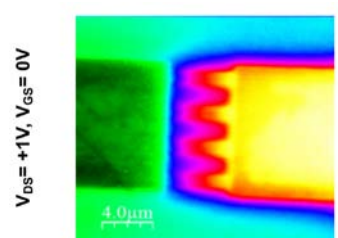
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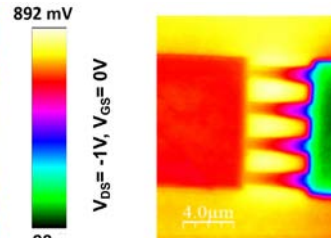
Collagen on silicon surface



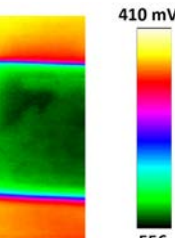
Topographie



$V_{DS} = +1V, V_{GS} = 0V$

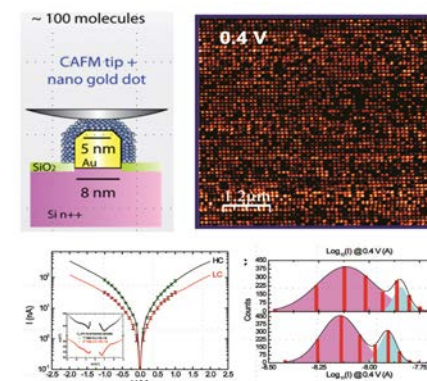


$V_{DS} = -1V, V_{GS} = 0V$

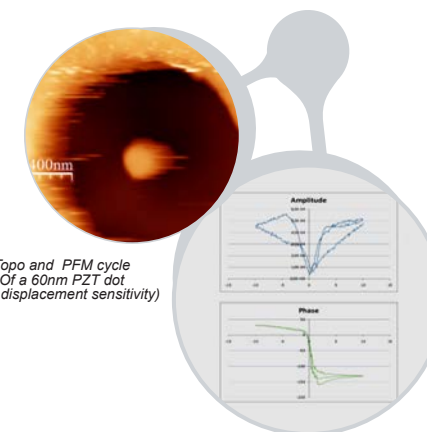


892 mV
410 mV
-556

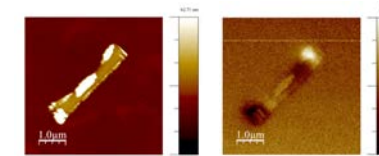
Gas sensing transistor polarization (KPFM)



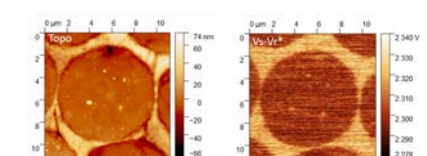
Conducting AFM statistics from a large array of sub-10 nm molecular junctions



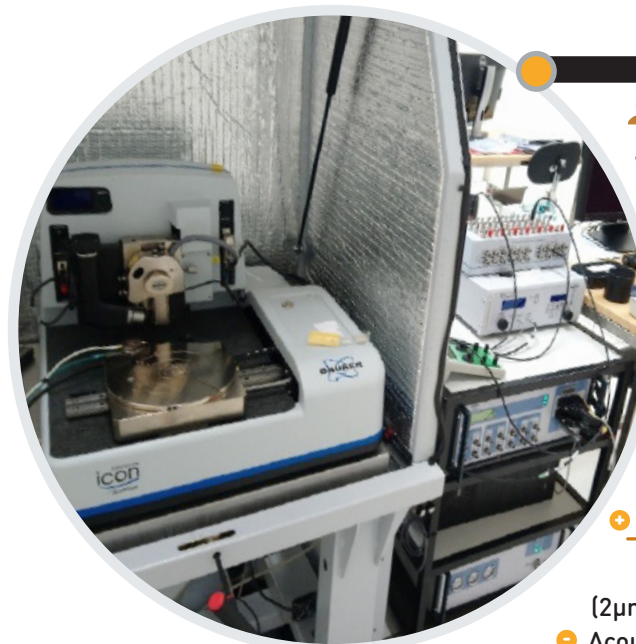
Topo and PFM cycle of a 60nm PZT dot (1pm displacement sensitivity)



Topo and MFM image of ferromagnetic domain wall position in multiferroic heterostructures



Topography and thermal conductivity of carbon fiber in epoxy matrix (AFM-STHM)



ICON

Louis Thomas

- **Sample dimension** : 5mm square to 20cm diameter
- **Scan range** : 10nm to 100µm (X and Y linearization feedback: closed loop) - Max. Z range: 10µm
- **Resolution** : Lateral: nanometric - Vertical 30pm
- **Working Mode** : AFM Tapping, AFM Peakforce, EFM, KPFM, CAFM, PeakForce TUNA, PFM, SThM, Force spectroscopy
- **Environnement** : Ambient air, Nitrogen gas
- **Temperature** : -25°C to 250°C

→ APPLICATIONS

- PeakForce
- Thermal chuck for small sample

→ ADVANTAGES & LIMITATIONS

- Large sample, large coarse displacement of the chuck (2µm resolution)
- Acoustic and vibrational Noise sensitive

DIMENSION Bruker

Louis Thomas

- **Sample dimension** : 5mm square to 20cm diameter
- **Scan range** : 10nm to 100µm - Max. Z range: 6µm
- **Resolution** : Lateral: nanometric - Vertical 50pm
- **Working Mode** : AFM Tapping, EFM, KPFM, CAFM, PFM, SThM, Force spectroscopy, SCM
- **Environnement** : Ambient air, Nitrogen gas
- **Temperature** : Ambient

→ ADVANTAGES & LIMITATIONS

- Large sample, large coarse displacement of the chuck (2µm resolution)
- Acoustic and vibrational Noise sensitive





VTA FM Omicron

Maxime BERTHE

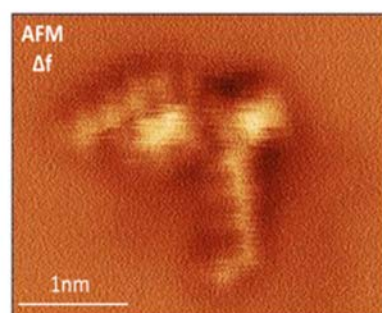
- **Sample dimension** : 4x6mm to 10mm square
- **Scan range** : 10 μ m - Max. Z range: 2 μ m
- **Resolution** : Lateral: nanometric - Vertical 30pm
- **Working Mode** : AFM, EFM, KPFM, CAFM, PFM, STM
- **Environnement** : Ultra High Vacuum
- **Temperature** : 50K to 1000K

→ APPLICATIONS

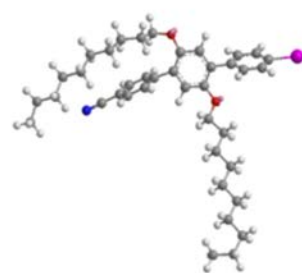
- Laser beam deflection (allow contact modes)
- Preparation chamber for sample and Tip
- Sample heater
- Mass spectrometer
- Ion gun
- 3 metal evaporator

→ ADVANTAGES & LIMITATIONS

- Variable temperature operation
- Small sample



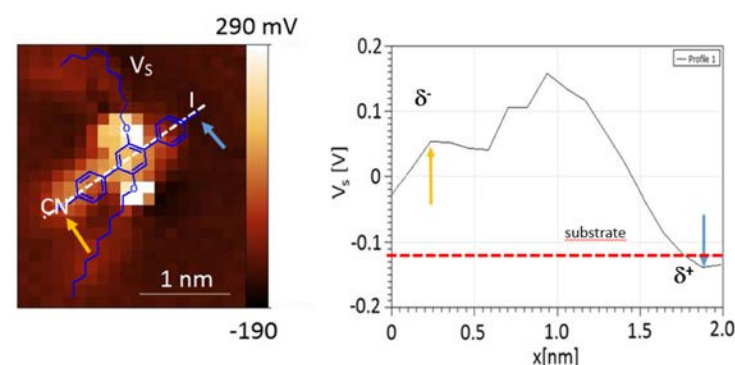
Δf image $V_s=0$ mV



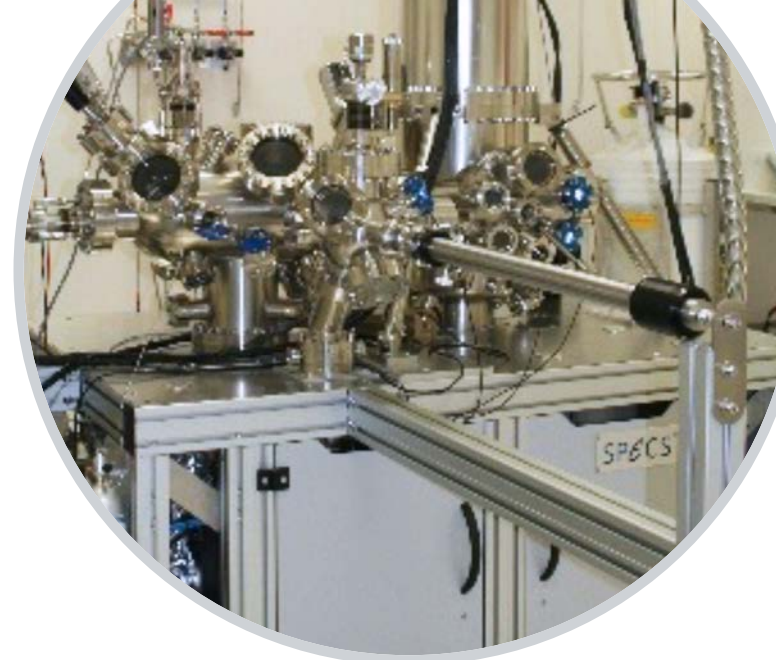
Model corresponding to nc-AFM image

Sub-molecular resolution

KPFM Spectroscopy



Identification of CN et I terminaison groups



JT-SPM SPECS

Sylvie Godey

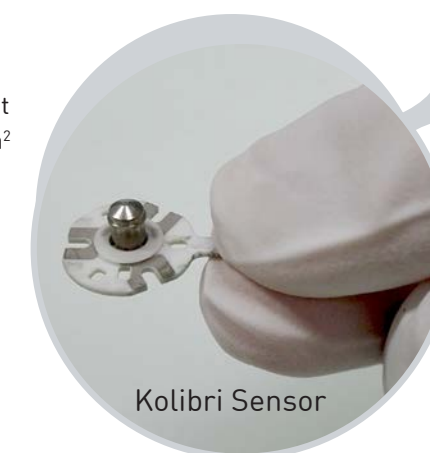
- Low temperature Scanning Probe Microscope, 1.2 K minimum (Joule-Thomson stage)
- STM/AFM modes, nc-AFM, KPFM
- Length Extension Resonator (Kolibri sensor): $f_0=1$ MHz $K=540$ kN/m $Q\approx 100000$ at 4K, - Nanonis controller
- XY Scan Range 300K/4K : $\sim 22\mu$ m/ $\sim 4\mu$ m, Z Scan Range 300K/4K : $\sim 2.3\mu$ m/ $\sim 0.42\mu$ m
- 3T maximum magnetic field perpendicular to sample surface
- Ar sputter gun for surface preparation, LEED-AES
- KENTAX evaporator, CO functionalisation

→ APPLICATIONS

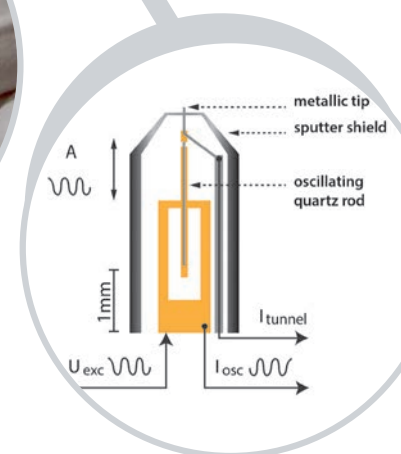
- Structure and electrostatic properties of surfaces, adatoms, unique molecules or molecular assemblies, nanostructures, nano-objects
- Surface potential determination, single charge transfer detection

→ ADVANTAGES & LIMITATIONS

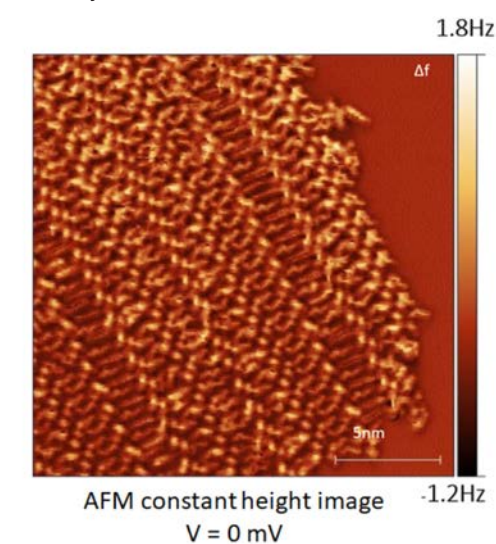
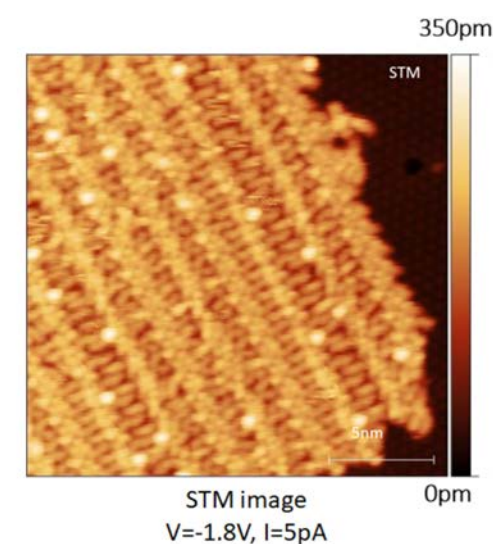
- AFM and STM simultaneous modes
- Submolecular resolution, tip functionalization
- constant height measurements
- need for a minimum density of objects of interest (of the order of one per 0.01 μ m²) on about 1mm²



Kolibri Sensor



Self-assembled monolayers on Si:B



**LT-STM Omicron**

Maxime Berthe

- Surface imaging of conducting or semiconducting surfaces down to the atomic scale.
- Electrical testing on surfaces or nanostructures with atomic precision and ultra-low drift rate (<10pm/h).
- All modes of operation compatible with low temperature down to 4K.

→ **APPLICATIONS**

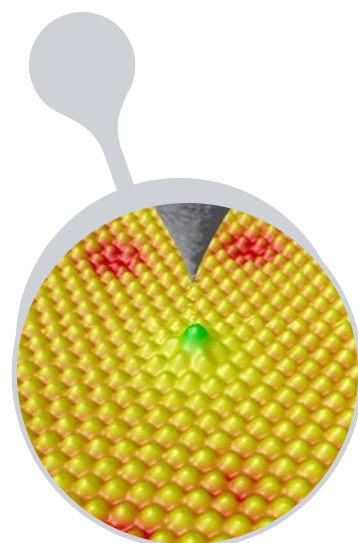
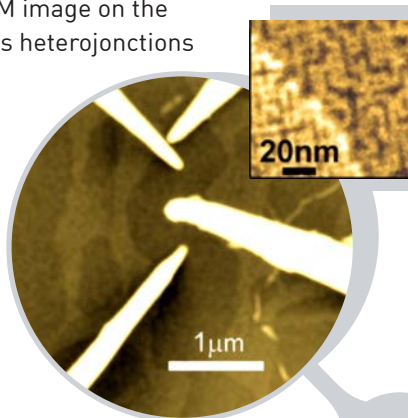
- Investigation of defects at the atomic scale in semiconductors and nanostructures by Scanning Tunneling microscopy (STM). Complementarity with TEM.
- Electronic properties of surfaces and nanostructures at the atomic scale by Scanning Tunneling Spectroscopy (STS). Complementarity with MBE, multiple-probe-STM, tunneling-induced light-emission spectroscopy.

→ **ADVANTAGES & LIMITATIONS**

- Extreme resolution (better than 100pm)
- Electronic measurements (local electronic density of states)
- Limited aspect ratio : only flat surfaces
- Only conducting and semiconducting samples

SEM Image of a four-point-probe measurement on a single domain of colloidal nanocrystals heterojunctions.

Inset : zoomed SEM image on the colloidal nanocrystals heterojunctions



3D representation of the reconstructed B-Si(111)-√3×√3 R 30°

NANOPROBE Omicron

Maxime Berthe

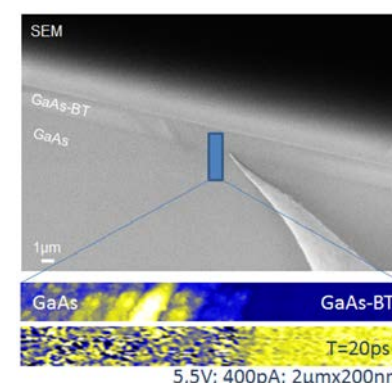
- Scanning Tunneling Microscopy (STM)
- Scanning Electron Microscopy (SEM)
- Nanoscale localization and manipulation
- Multiple-scale (100nm to 1mm) electronic transport measurements
- « fs-Laser-combined-multiple-probe-STM » for time-resolved (<1ps) nanoscale measurements .

→ **APPLICATIONS**

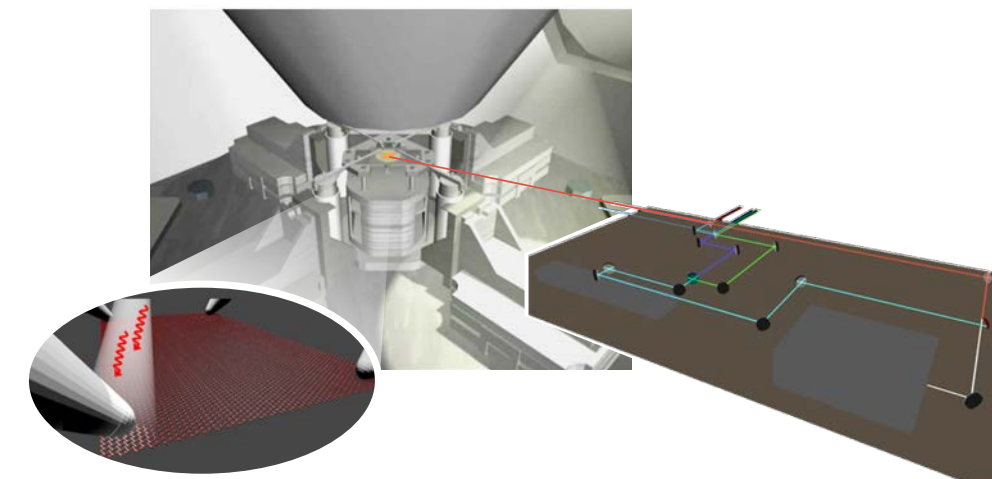
- Transport properties of surfaces and nanostructures. Complementarity with MBE, STM, tunneling-induced light-emission spectroscopy.
- Mapping of transport properties combined with STM. Complimentary with STM and electronics processing.

→ **ADVANTAGES & LIMITATIONS**

- Nanoscale imaging and manipulation with SEM monitoring
- Electronic transport measurements from nanometer to millimeter scale
- Limited STM resolution (nanometer) and stability



Top: SEM image of GaAs/LT-GaAs junction with one STM probe scanning across the junction.
Bottom: Simultaneous acquisition through STM probe of (i) Topographic STM image and (ii) Lock-in-demodulated ultrafast optical signal.



CHOP

The **CHOP service** covers 900m², in a ISO8-certified environnement, of the IEMN's common resources enabling the characterization of the main electrical parameters of electronic components and subsystems in a wide range of frequencies, from DC to TeraHertz. Most of the measurement benches are modular in order to best meet the needs of research. Engineers develop the test setup in a continuous improvement in order to work in line with technological innovations. Some experiments have been designed to electrically test components under «hard» conditions such as low temperature (5.5 K) or high voltage (10 kV). The expertise in characterizing ultra-fast devices is internationally recognized and allows the CHOP to also play a very important role in the joint laboratory created between the IEMN and French manufacturer ST Microelectronics or foreign research centers. The CHOP hosts 22 research groups, several innovation projects and start-ups (Vmicro, Zymoptiq).

Head of CHOP
S. Eliet Barois



- **Nano-characterization** II. 1-2
SNOM MIR-THz: Scanning Near-Field Optical Microscopy
Scanning Microwave Microscope (SMM)
- **DC Low Frequency** II. 3
DC-CV-PULSE-SOLAR measurements
- **Hyper-frequency** II. 4-6
DC-110 GHz RF-Characterization
Opto-Hyper measurements
Cryogenic RF measurements
- **Millimetric & THz** II. 7-10
Millimeter waves up to 1.1THz
THz-TDS: TeraHertz Time Domain Spectroscopy
Fourier Transform Infrared Spectrometer (FTIR) coupled with Microscope
- **Noise measurement** II. 11-12
Noise measurement
- **Power Measurement** II. 13-16
40 & 94 GHz Load-Pull characterization
I/V Measurements High Voltage or High Current

chop-contact@iemn.fr





SNOM MIR-THz: SCANNING NEAR-FIELD OPTICAL MICROSCOPY

Sophie Eliet

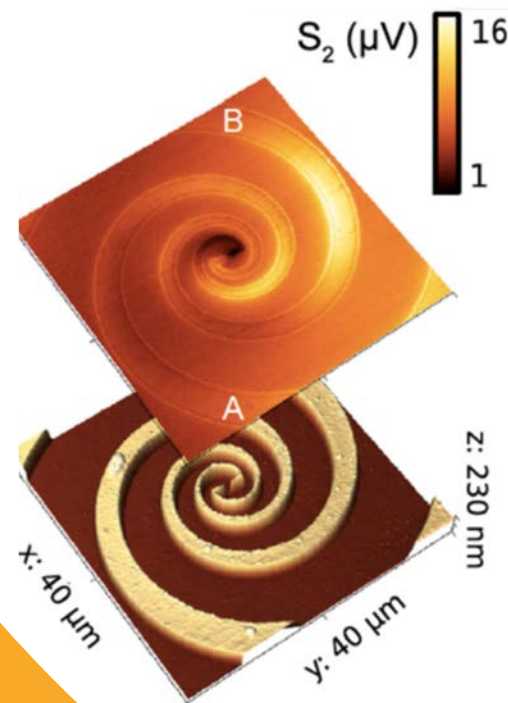
The SNOM MIR-THz is a near-field optical measurement bench allowing the acquisition of images respectively in the mid-infrared and TeraHertz range with a spatial resolution of the order of 30 nm (limitation by the size of the AFM tip). For this, two laser sources are currently available: a 10µm quantum cascade laser and a THz molecular laser pumped by a CO₂ laser.

→ EXAMPLE

- This technique is well suited for the qualitative study of 2D materials such as graphene, molecular electronic nanostructures, doped materials (even weakly) or the study of waveguides induced by laser inscription in glasses.
- It is complementary with others Scanning Probe techniques (cf PCP service)

→ ADVANTAGES & LIMITATIONS

- The spatial resolution is linked to the apex of the probe (almost few tens of nanometers).
- Materials must have a MIR or THz contrast (plasmons resonance ...)
- Sample must be relatively flat few hundreds nanometers of relief maximum



Example of SNOM-THz image of Logarithmic Spiral Antenna @ 2,5 THz (up), simultaneously recorded with AFM topography (IRMMW Conference, 2021)

SCANNING MICROWAVE MICROSCOPE (SMM)

Sophie Eliet

Scanning Microwave Microscopy is Scanning probe technique. It is based on a AFM technique coupled with VNA (Vector Network Analyzer). The probe is specially designed and integrated into a specific support and radio-frequency connectors.

At CHOP, there are 2 types of SMM:

- At air, 3600 LS Keysight, up to 12 GHz
- Under vacuum, a home-made system integrated in a Tescan SEM, up to 67 GHz

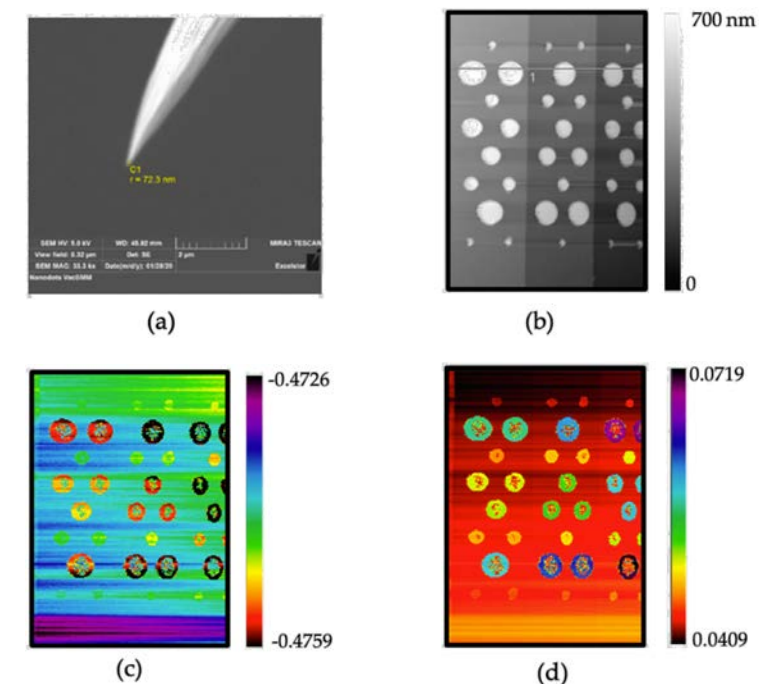
→ APPLICATIONS

The technique is based on AFM but develops a specific contact electric mode at microwave frequencies (2-67 GHz) that allows to map material or device surfaces at the nanoscale for topography and microwave reflectivity. The sample must be compatible with AFM topography measurements.



Example

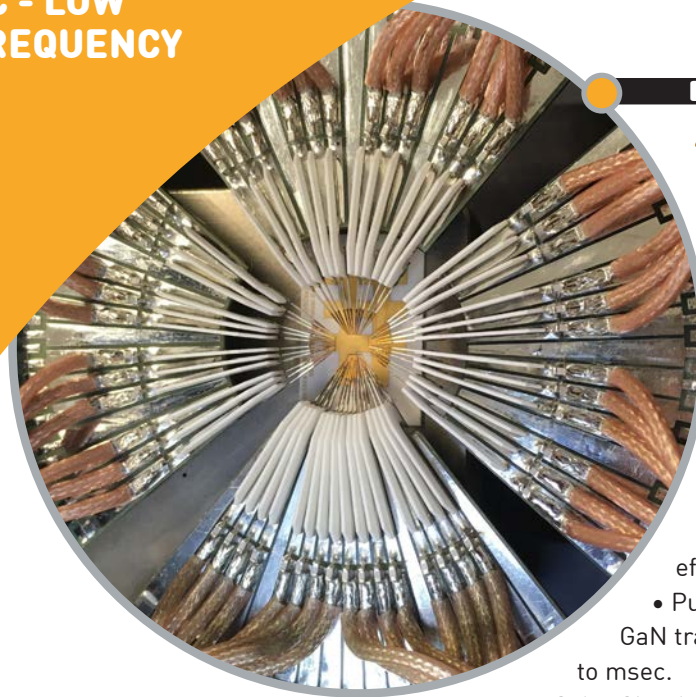
SMM in SEM illustration



Combined AFM, SMM and SEM images obtained in the home-made system (a) SEM image of the apex tip. (b) AFM topography image of a set of metallic dots deposited on a SiO₂/Si substrate to form capacitances, (c) real part and (d) imaginary part images of the complex reflection coefficient Γ_M at 30 GHz. The dots diameters range from 1 to 4 µm. From Appl. Sci. 2021, 11, 2788

→ ADVANTAGES & LIMITATIONS

- It combines topography and microwave nanoscale measurement over a large microwave range. The spatial resolution is linked to the apex of the probe (a few tens of nanometers) but also to the microwave frequency. It allows to observe surface contrasts of microwave dielectric properties. The resolution is in the aF range. It can be combined with DC biasing up to 10 V. Traceability to microwave standards is still under study. Calibration based on the probe shape is possible but indicative with several µS uncertainty. The sample must be flat within a few hundreds of nanometers maximum.



DC-CV-PULSE-SOLAR MEASUREMENTS

Etienne Okada

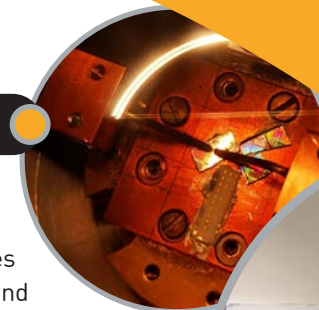
Mandatory for any electric component, DC characteristics can be provided by several equipment. To make a technological return as soon as it comes out of production.

Benches can be adapted to supply several circuits or study one device. With connector or on wafer (from 1 to 16 pins simultaneously) we can measure characteristics to identify performances, homogeneity of manufacturing and also robustness. Several environments can be used (ask for compatibility), temperature, pressure, lighting/darkness.

- DC are made from 0 to 210 V with current up to 2A.
- Impedance meter is available to highlight capacitance effect. CV from 1 kHz to 100 MHz.
- Pulsed measurements are helpful to mark trapping effect on GaN transistor or to eliminate heating effect. Pulse from 300nsec up to msec.
- Solar Simulator is used to characterize solar cells. Laser beam can be also provided on device

→ ADVANTAGES & LIMITATIONS

- ⊕ High voltage and current are available but power is limited by the setup.
- ⊕ Both can be performed on or off wafer.

CRYOGENIC DC
AND RF MEASUREMENT

Sylvie Lepilliet

CHOP has acquired and developed several test benches made up of vector network analyzers, power supplies and probe stations fitted with coplanar tips. This equipment and the know-how of CHOP allow in DC regime the establishment of current-voltage characteristics and in RF-regime, the measurement of S parameters.

It is possible to characterize components on wafer or in package (coax) according to different frequency bands. The design of the electrical accesses for placing the probes or the connectors must correspond to the available materials and physical possibilities (see "limits of the technique"). Meet the CHOP team!

To make a technological return as soon as it comes out of production or for the design of complex circuits (frequency converter, amplifier, micro processor, etc.), small signal measurements up to 110GHz are at the core of the CHOP expertise.

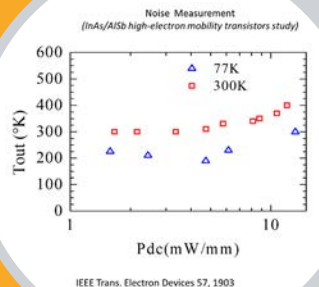
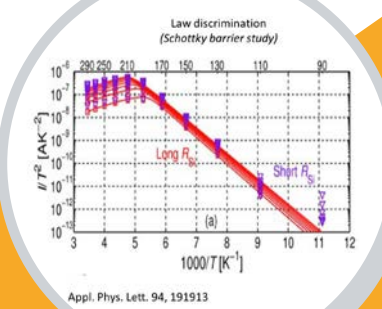
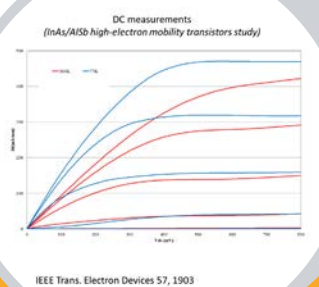
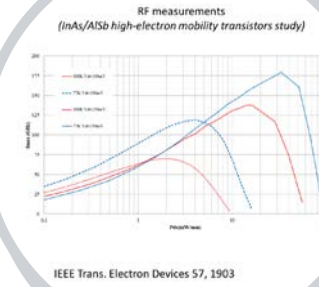
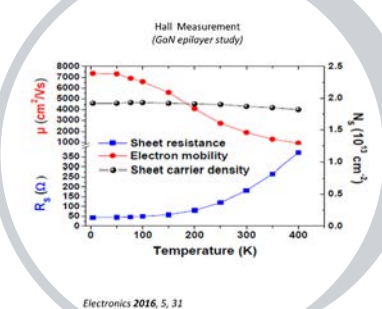
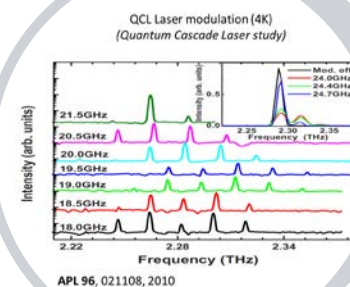
→ This can be a first step before other types of measures:

- Millimeter-waves measurements
- Noise measurements
- In power regime
- At High Voltage or High Current measurements

If microwave measurements are required (up to 67 GHz) in cryogenic mode, this is also possible in CHOP

→ ADVANTAGES & LIMITATIONS

- ⊕ Designed of electrical access must be taken into account, come in CHOP for more details!
- ⊕ Coaxial available up to 67GHz versus 110GHz under probing method.





DC-110GHz - RF-CHARACTERIZATION

Sylvie Lepilliet

CHOP has acquired and developed several test benches made up of vector network analyzers, power supplies and marble stations fitted with coplanar tips. This equipment and the know-how of CHOP allow in DC regime the establishment of current-voltage characteristics and in RF-regime, the measurement of S parameters.

It is possible to characterize components on wafer or in package (coax) according to different frequency bands. The design of the electrical accesses for placing the probes or the connectors must correspond to the available materials and physical possibilities (see "limits of the technique"). Meet the CHOP team!

To make a technological return as soon as it comes out of production or for the design of complex circuits (frequency converter, amplifier, micro processor, etc.), small signal measurements up to 110GHz are at the core of the CHOP expertise.

→ This can be a first step before other types of measures:

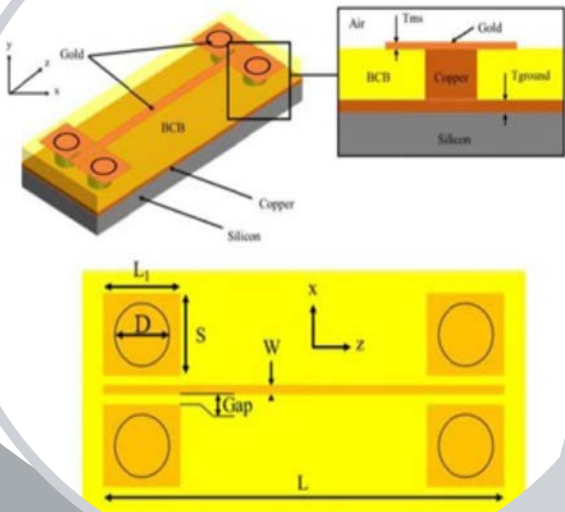
- Millimeter-waves measurements
- Noise measurements
- In power regime
- At High Voltage or High Current measurements

If microwave measurements are required (up to 67 GHz) in cryogenic mode, this is also possible in CHOP

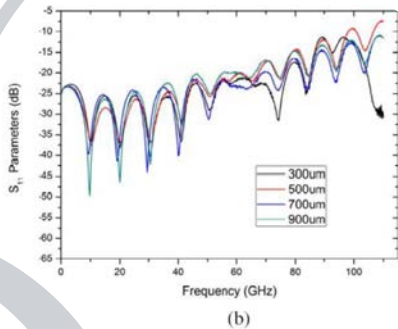
→ ADVANTAGES & LIMITATIONS

- Designed of electrical access must be taken into account, come in CHOP for more details!
- Coaxial available up to 67GHz versus 110GHz under probing method.

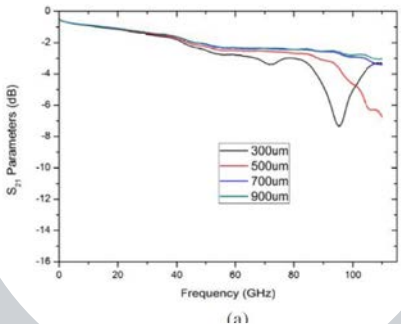
Modelled GCPW-MS-GCPW transition including input and output coplanar-microstrip transitions with grounding via-holes and a microstrip transmission line in between



Example of measurements up to 110GHz



Measured S-parameter as function of the via-hole diameter: (a) S_{21} and S_{11}



OPTO-HYPER MEASUREMENTS

Sophie Eliet Emilien Peytavit

Objectif: établissement of electrical model for material and knowledge of performances

Technical Specifications:

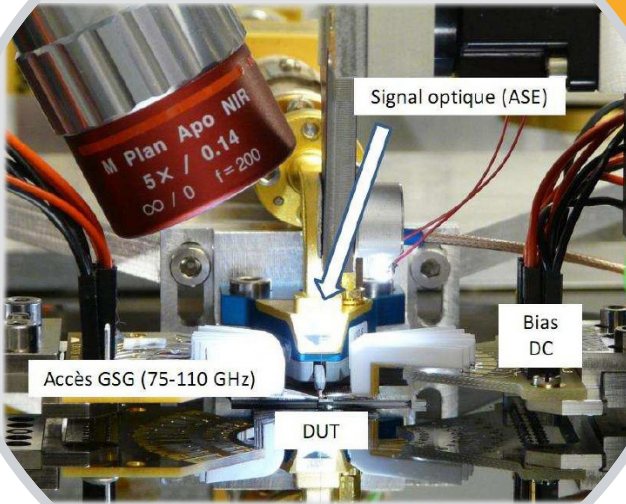
- Lasers: 780 nm/1064 nm/1300nm/1550 nm. Output power :<10 mW
- Optical Amplifier: 780 nm/1550 nm. Output power: <500 mW
- Near diffraction limit optical focusing capabilities (free space and fiber coupled)
- Optical beam characterization (powermeter / optical spectra analyzer)

Expertise:

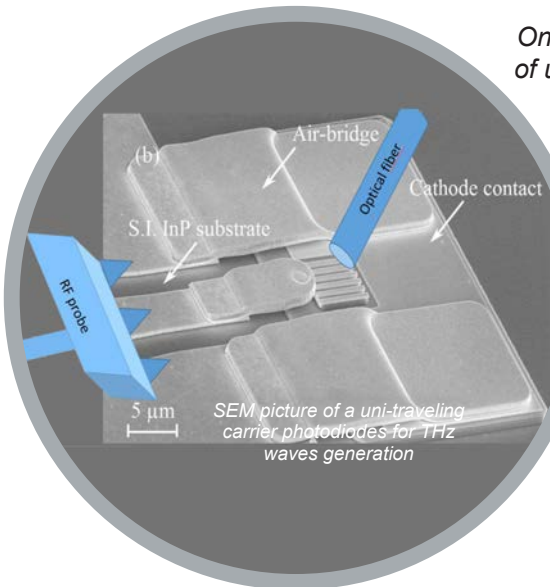
- On-wafer S parameter characterization of device under CW illumination up to 320 GHz (limited by RF probes)
- Frequency response (up to 320 GHz) and noise characterisation (up to 50 GHz) of photodetectors
- Optical waveguide and grating coupler characterization

→ ADVANTAGES & LIMITATIONS

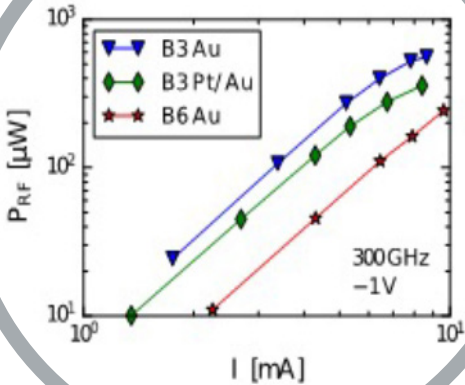
- Probing on wafer with several type of wavelength, come in CHOP for more details!



Characterization (S parameter/ Frequency response) of ultrafast photoconductors up to 320 GHz



On wafer characterization of ultrafast photodetectors beyond 320 GHz



MILLIMETER WAVES UP TO 1.1THz

Sylvie Lepilliet

Thanks to technological advances in the field of micro and nano electronics, more and more applications are emerging and are being considered in the millimeter frequency band (mmW) above 100 GHz. The millimeter frequency band is defined between 30 GHz and 300 GHz, corresponding to wavelengths between 10 mm and 1 mm respectively. Beyond 100 GHz, the millimeter frequency band intersects with the Terahertz (THz) spectrum up to 300 GHz. This frequency band (100 GHz - 300 GHz) commonly known as Sub-THz offers an important lever for increasing the performance of existing systems and opens up prospects for new applications. This part of the millimeter band is of interest mainly in the fields of spectroscopy, imaging and telecommunications.

→ Vectorial measurement capabilities

3 VNAs with 6 converters :

- 75-110GHz – WR10
- 140-220GHz – WR05
- 220-325GHz – WR03
- 325-500GHz – WR2.2
- 500-750GHz – WR1.5
- 750-1100GHz – WR1.0

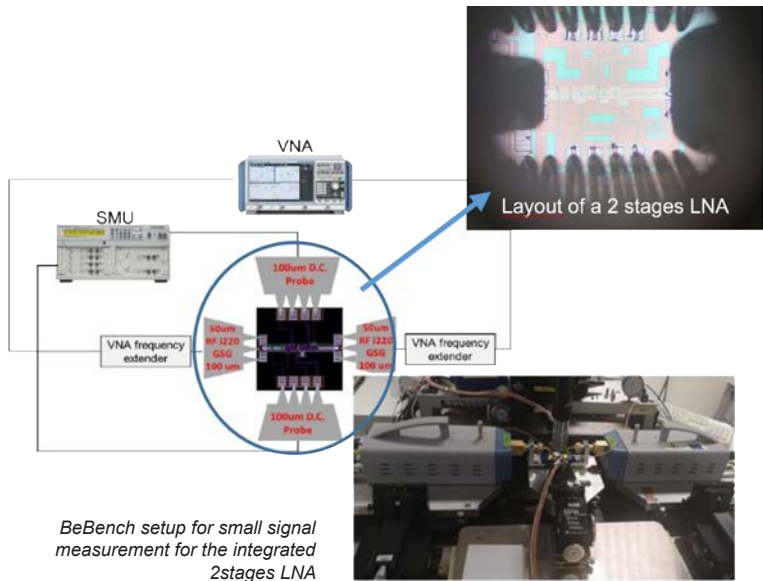
- On wafer
- In waveguide
- In free space

→ Scalar measurements capabilities:

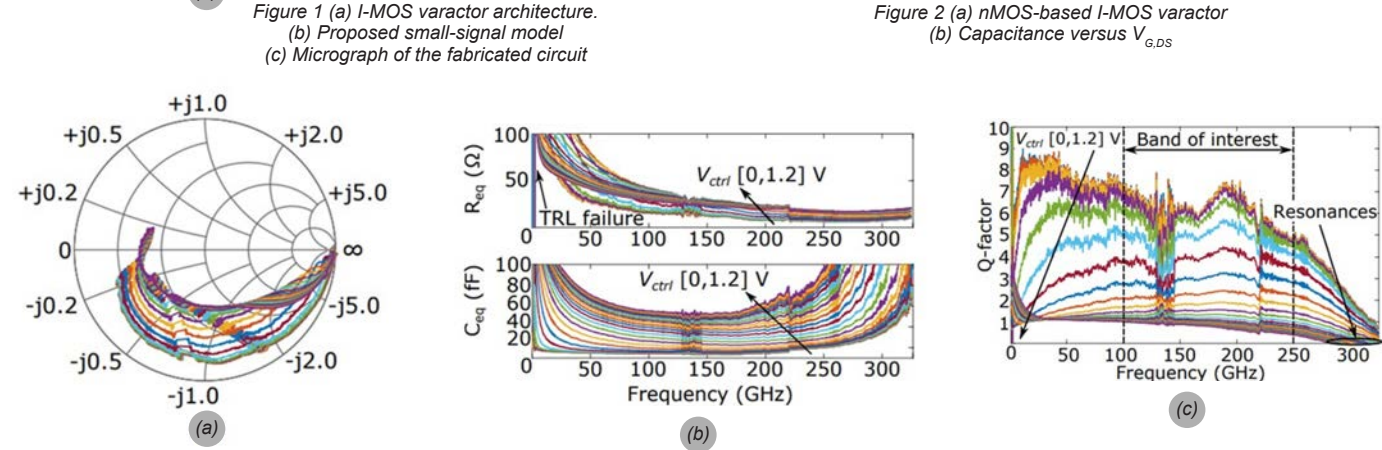
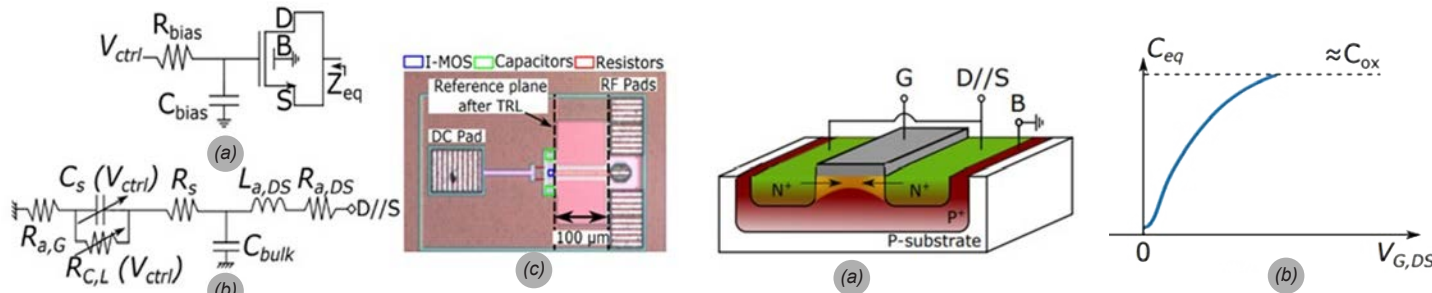
- Spectrum analyzer mixers up to 1 THz
- Absolute power (PM5 Erickson) 60GHz – 2THz, 1μW – 200mW
- Multiplication chains (80-360, 580-720 GHz)
- Pyroelectric detector: 100GHz – 30THz, 100nW – 100mW free space
- Waveguide integrated zero-bias detectors (Schottky): WR 3.4 (220-325 GHz), WR 1.5 (500-750 GHz) 100GHz, 140-220GHz, 750-1100GHz

→ Photonics-based sources/receivers for THz communications & instrumentation, 200-340 GHz:

- Sources for amplitude modulation and I/Q measurements, in THz range (up to 340 GHz)
- Receivers for wideband signal reception (60-340 GHz)
- Bit error testers (realtime, 2 channels 25 GBit/s)
- Generation & Analysis of I/Q signals (developed with PhLAM, Lille)
- IP3 bench of scalar evaluation of active devices intermodulations based on photonics techniques (up to 330 GHz)

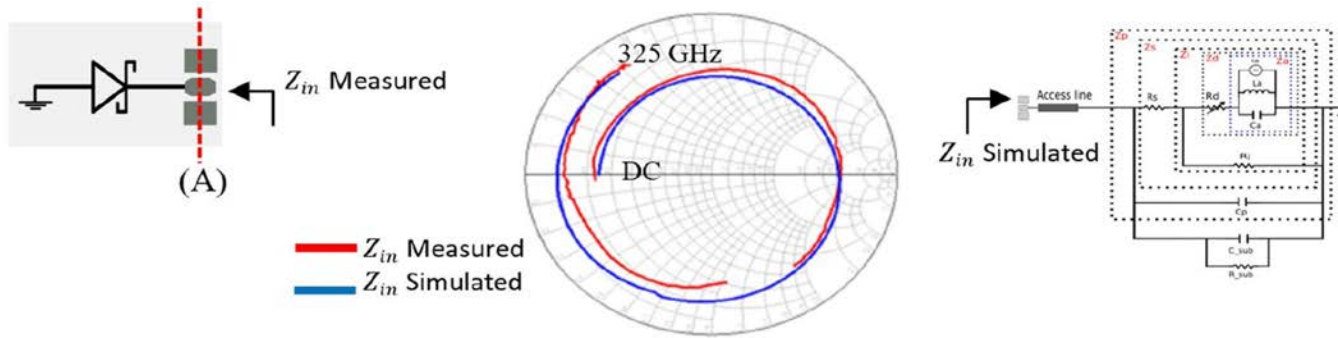


Example 1 Highly Tunable High-Q Inversion-Mode MOS Varactor in the 1–325-GHz Band

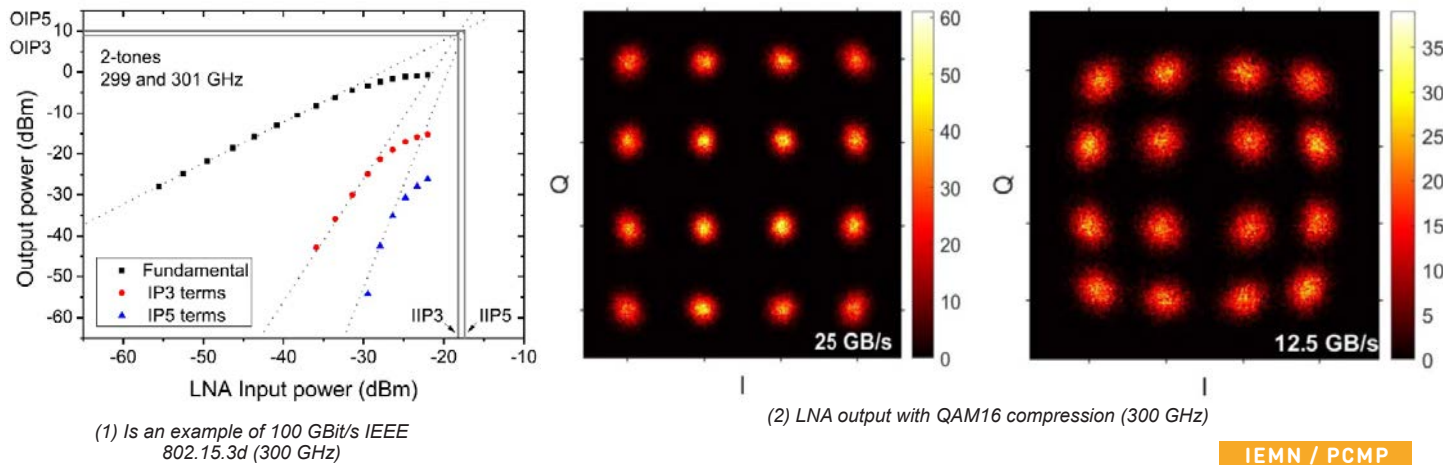


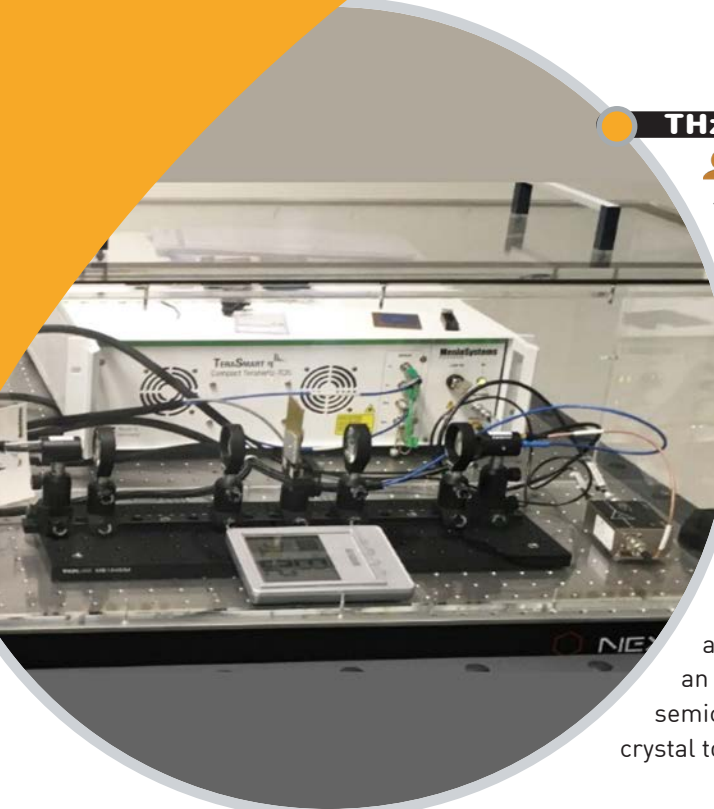
«Highly Tunable High-Q Inversion-Mode MOS Varactor in the 1–325-GHz Band,» in IEEE Transactions on Electron Devices, vol. 67, no. 6, pp. 2263–2269, June 2020, doi: 10.1109/TED.2020.2989726.

Example 2 To validate the extraction methodology, the unput impedance of this simulated electrical model id compared to the impedance extracted from the S-parameters , in the range DC-325GHz



Example datacom IP3 and I/Q analysis of the compression curve of LNA: IP3 measurement of 300 GHz LNA





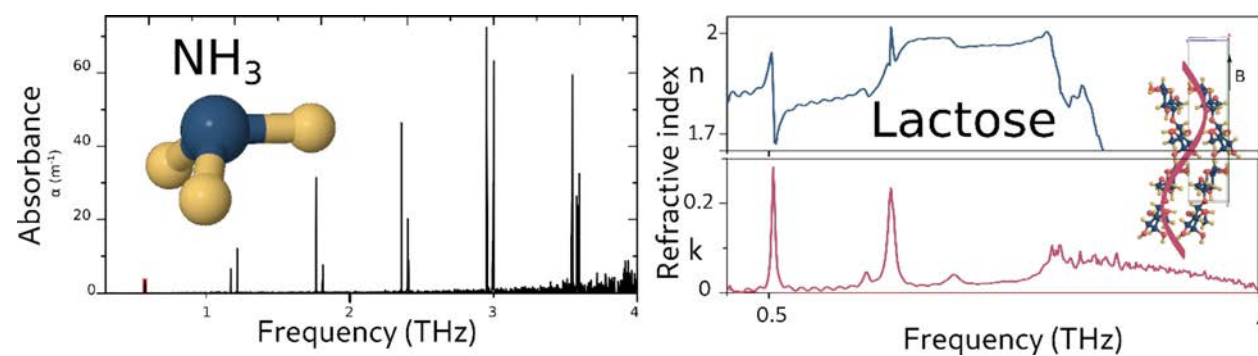
THz-TDS: TERAHERTZ TIME DOMAIN SPECTROSCOPY

Sophie Eliet

Terahertz Time-domain-spectroscopy is the most spread THz spectroscopy setup for broadband THz spectral measurements. It is based on a femtosecond laser of which pulse is transferred in the THz spectral range thanks to a photoconductive antenna (in our case). The resulting THz pulse is, then, time sampled using another photoconductive antenna triggered by the femtosecond laser after a controlled delay. It leads to time traces that a Fourier transform transfers in the spectral domain.

→ APPLICATIONS

TDS spectroscopy is used on all kinds of samples: gaseous, liquid solid and even plasma. It is used to probe the rovibrational lines of gas with a very good specificity when molecules have from ~3 to ~10 atoms. It is very sensitive to polar liquid such as water and thus plays an important role in biology. THz broadband spectroscopy is used on semiconductor sample to probe very low level of doping and on molecular crystal to study their conformation.



→ ADVANTAGES & LIMITATIONS

- ✦ Spectral range: 0,2 - 5 THz
- ✦ Total scan range: 850 ps
- ✦ Spectral resolution limited by the Fast Fourier Transform : <1,2 GHz
- ✦ Dynamic range : 100 dB
- ✦ Better resolution possible by temporal signal processing
- ✦ Type of sample: Solids (wafers, powder, pellets...) , gases or suspended particles

FTIR: FOURIER TRANSFORM INFRARED SPECTROMETER, COUPLED WITH MICROSCOPE

Sophie Eliet

This N₂-purged FTIR allows spectral acquisition from the mid-IR to the THz spectral range

Total Spectral range: 8 000 – 50 cm⁻¹ (1,25μm- 200μm) (240 THz- 1,5 THz)

Spectral resolution: = 0,4 cm⁻¹

Detectors: Internal DLATGS 8000-350cm⁻¹; Internal DTGS/PE 680-50cm⁻¹

External MCT (cooled 77K): 12000-600cm⁻¹

Internal source: Blackbody

Coupled to a MIR microscope and internal MCT detector (cooled 77K): 12000-600cm⁻¹

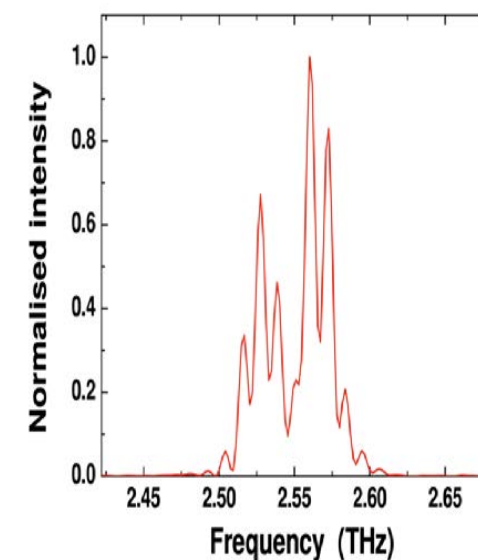
Microscope mapping:

- Precision of step: 0.1μm
- Repeatability: 1μm
- Positioning precision: +/-3μm



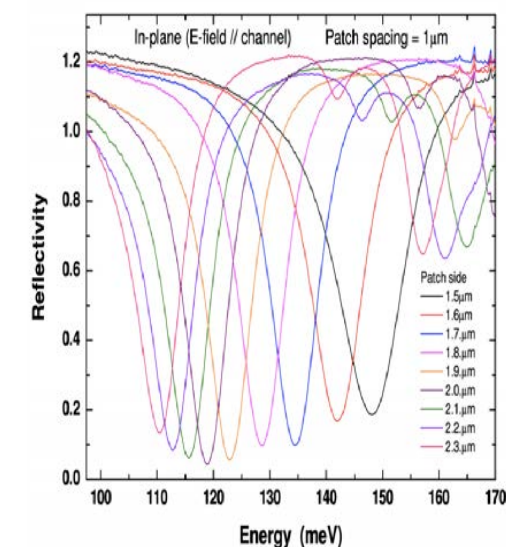
Example 1

Emission spectrum of a THz quantum cascade laser



Example 2

Reflectivity spectra of 2D periodic array (1μm period) of square metallic patch cavities of different side

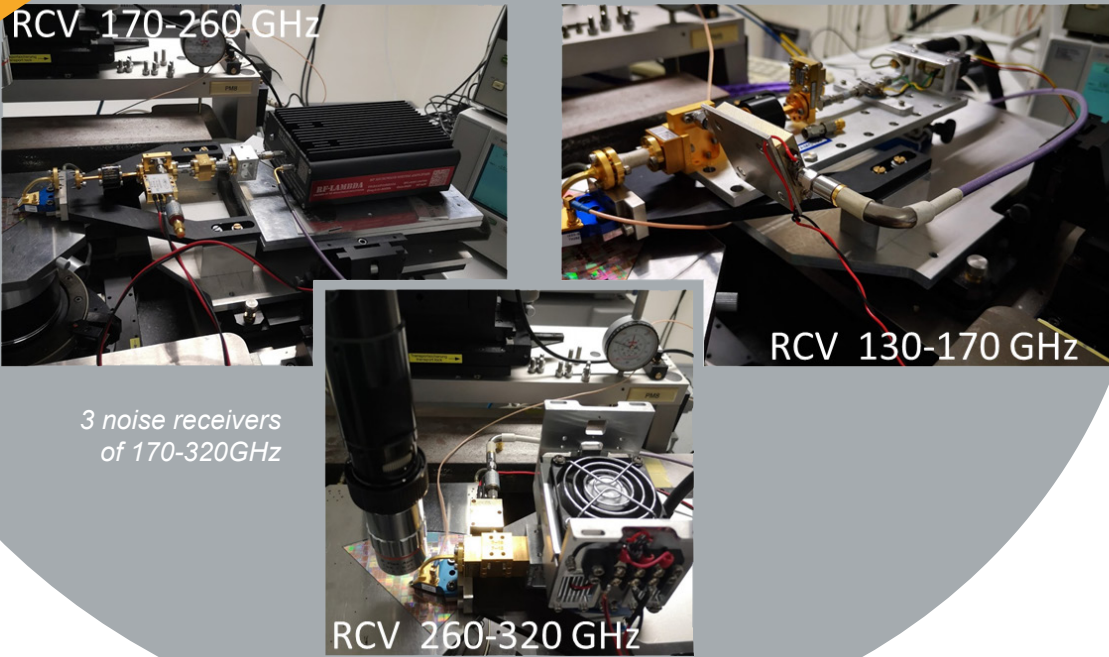


The cavities consist of a GaAs/AlGaAs heterostructure sandwiched between metallic top contact and ground plane. Spectra are measured in reflection geometry with the mid-infrared microscope.

ACS Photonics 8. 464 [2021]

→ ADVANTAGES & LIMITATIONS

- ✦ Spectral range depend of the couple beamsplitter / detector
- ✦ Type and dimensions of sample for Hyperion module: flat sample of maximum dimensions ~5x7cm



For the extraction of the four noise parameters [γ_{opt} , N_{fmin} and R_n] of semiconductor devices studied, several automated measurement benches make it possible to measure the available gain and the noise figure (Noise Figure) of microwave components. according to the following frequency ranges:

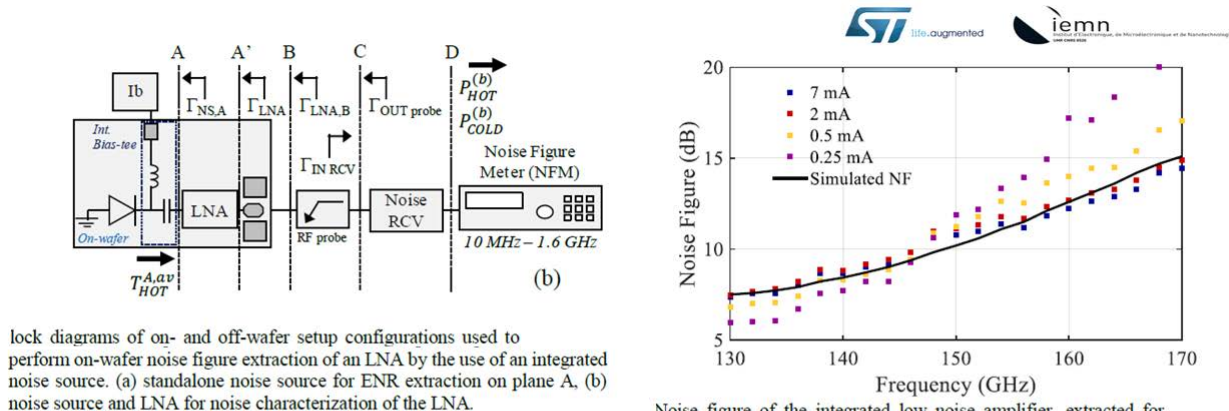
6 noise receivers:

- 6-20GHz
- 20-40GHz
- 75-110GHz
- 110-170GHz
- 170-260GHz
- 260-325GHz

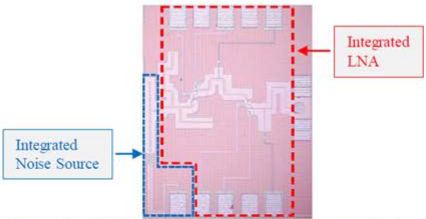
On wafer
In waveguide

Example 1

Noise Measurements (LNA integrated 130-170GHz)



Block diagrams of on- and off-wafer setup configurations used to perform on-wafer noise figure extraction of an LNA by the use of an integrated noise source. (a) standalone noise source for ENR extraction on plane A, (b) noise source and LNA for noise characterization of the LNA.



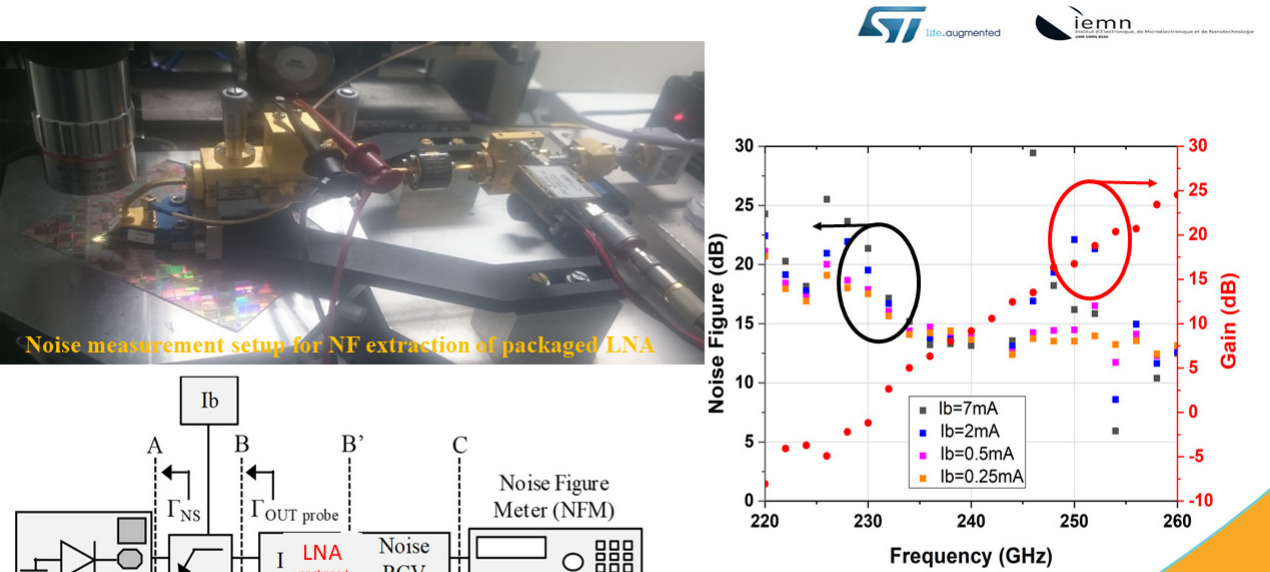
Chip photograph of the BiCMOS 55 nm test structure, composed of the integrated noise source and the LNA.

Noise figure of the integrated low noise amplifier, extracted for variable diode noise source bias currents and simulated on noise source impedance.

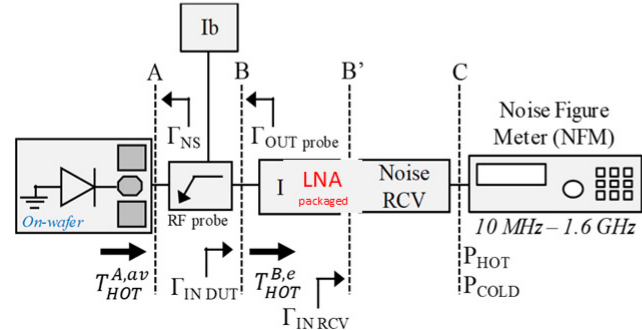
IEEE Transactions on Microwave Theory and Techniques (MTT), vol.67, Issue 9.

Example 2

Noise Measurements (LNA packaged 220-260GHz)



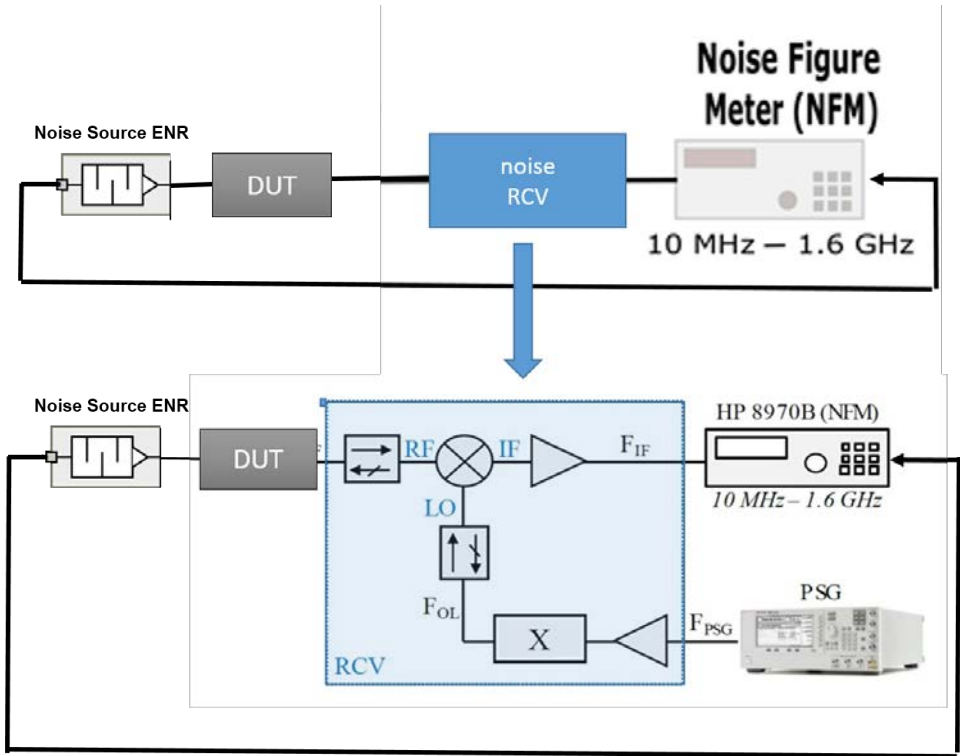
Noise measurement setup for NF extraction of packaged LNA



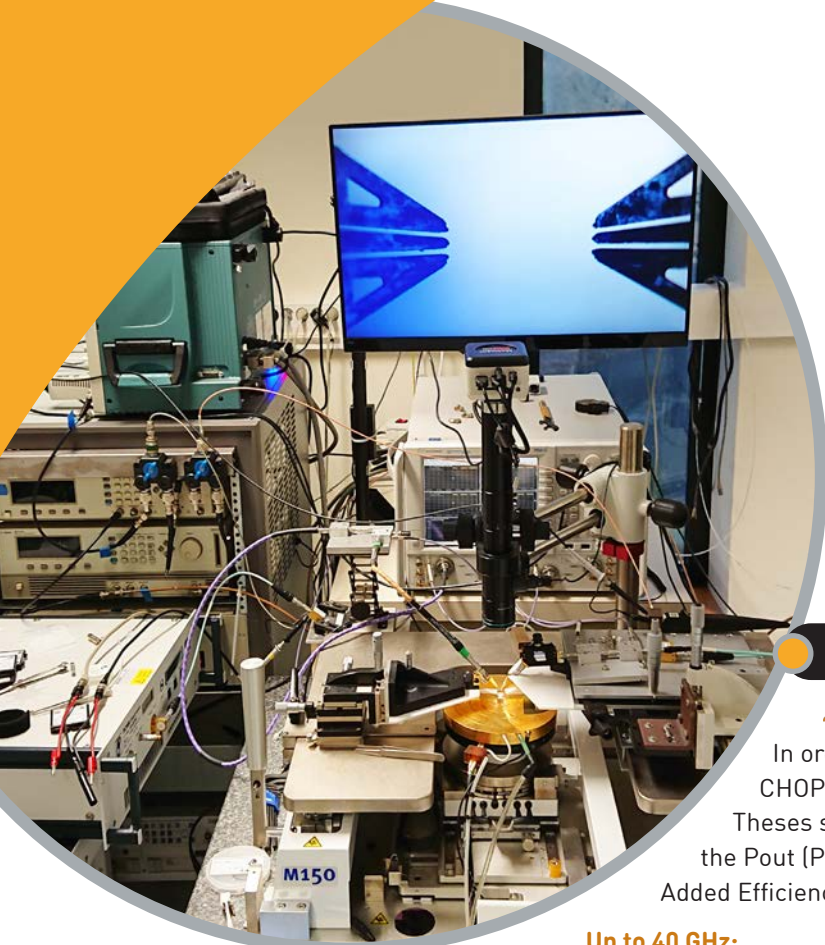
NOISE MEASUREMENTS

Sylvie Lepilliet

The term "Noise" is normally used to express the unwanted fluctuations that may disturb the information propagation within the signal, or reduce the quality of its contents. Noise figure (NF) is measures of degradation of the signal-to-noise ratio (SNR), caused by components in a signal chain. It is a number by which the performance of an amplifier or a radio receiver can be specified, with lower values indicating better performance.



Block diagram of noise measurement



40 & 94 GHz LOAD-PULL CHARACTERIZATION

Etienne Okada

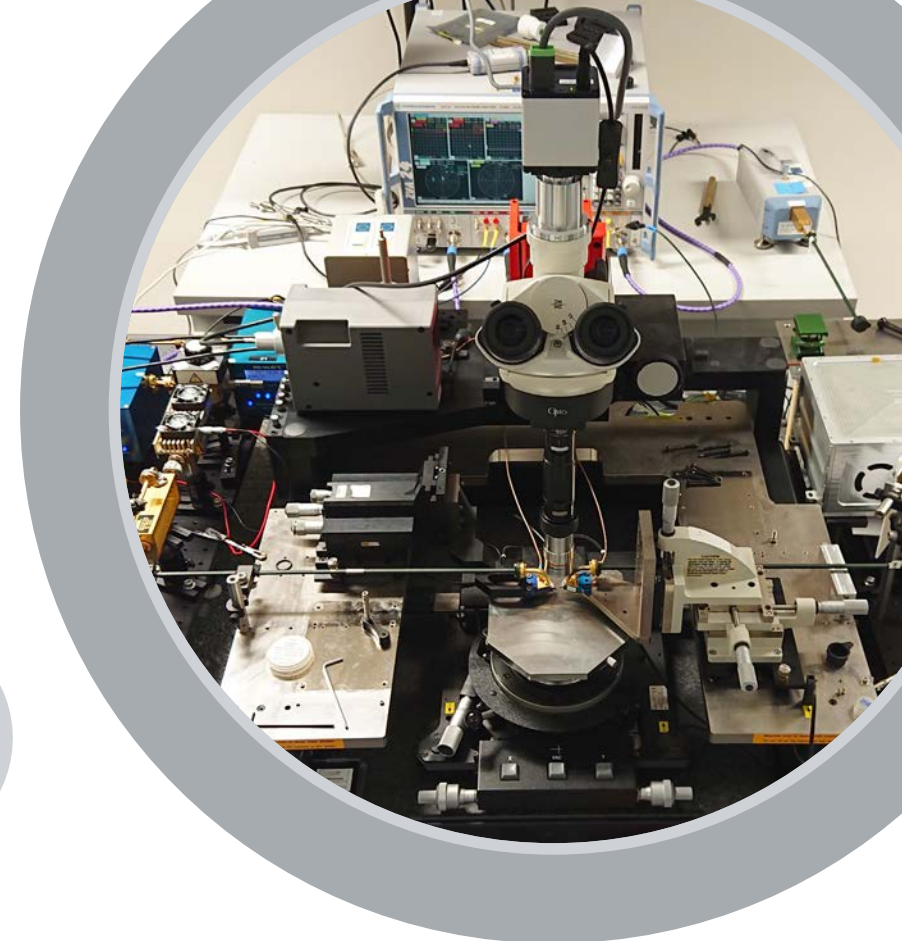
In order to measure the power performance of transistors, the CHOP developed specific "Load-Pull" measurement benches. These system make it possible to determine the G_p (Power Gain), the P_{out} (Power available at the Output) as well as the P_{ae} (Power Added Efficiency) of transistors and amplifiers.

Up to 40 GHz:

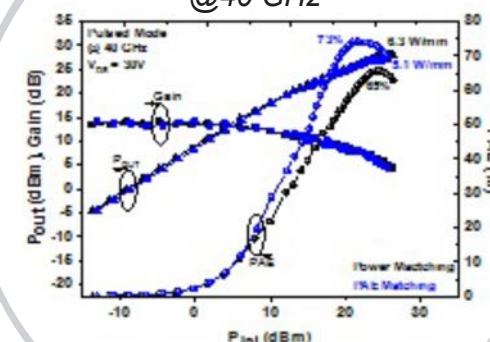
Since these parameters can only be determined under saturated conditions, a high power level is required to energize the device under test. For this, several power amplifiers are available and the bench have been optimized to carry the measurement up to the saturation of the DUT at 6, 10, 18 and 40GHz. At these frequencies, we can apply up to +30dBm at wafer level. Devices under test can be bias up to 50V. These measurements can be made in «load-pull» mode to modify the impedance presented at the output of the device under test. For this, we developed an active Load-Pull setup to reach high magnitude reflection coefficients. This helps determine the optimal impedance to maximize G_p , P_{out} or P_{ae} . All these measurements are possible in CW condition (continuous) or pulsed condition (pulsed bias + pulse RF) with a pulse width of 1 μ s and a duty cycle of 1%. Pulse measurements make it possible to overcome trap and thermal phenomena, thus maximizing the performance of the components under test. Large signal reliability test can also be made with this bench. We apply a large signal to the DUT and we measure its performance versus time for hours.

@94 GHz:

The 94GHz Load-Pull measurement bench is based on an active Load-Pull technique also. It is quite similar to the 40GHz bench with specific modification due to the high frequency. Big improvements are underway on this bench to reach higher power. Only CW measurement are available for now, pulsed measurements are in development.

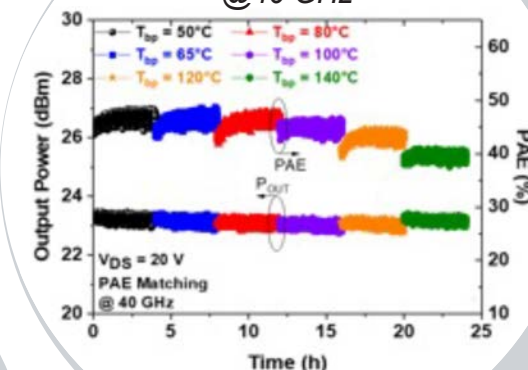


Large signal measurements @40 GHz



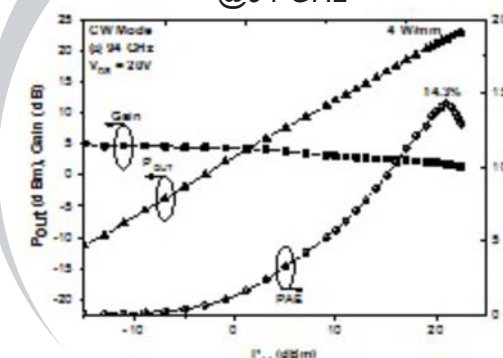
IEEE J. Electron Devices Soc.,
vol. 7, 2019

Large signal reliability @40 GHz



2020 IEEE IRPS

Large signal measurements @94 GHz



2020 IEEE IMS



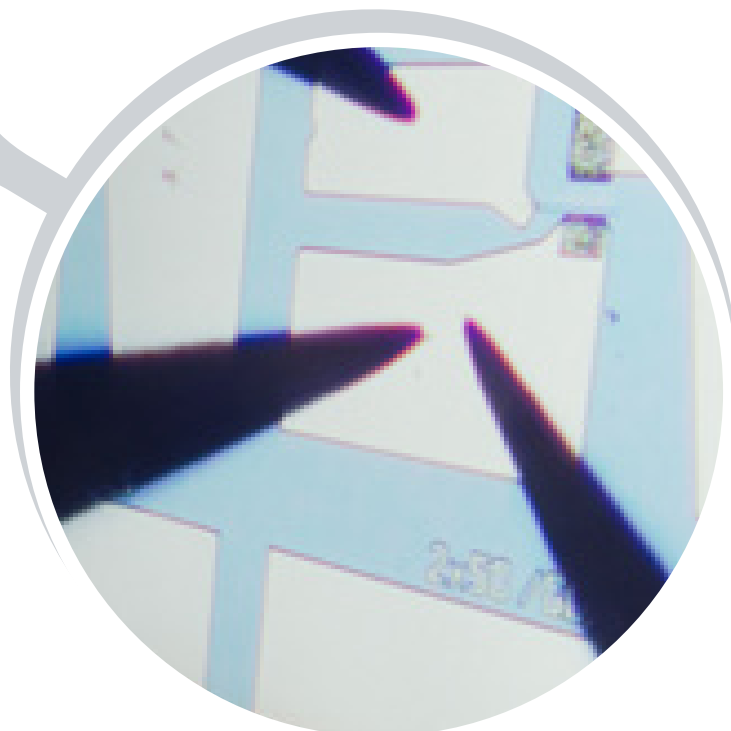
I/V MEASUREMENTS HIGH VOLTAGE OR HIGH CURRENT

Etienne Okada

Based on a Keysight B1505A device analyzer coupled with a MPI TS150-HP probe station, this system allows on-wafer measurement up to 10kV DC for breakdown characterization. It also permit high current measurements: 20A @ 20V (Pulsed).
We can also extract Dynamic RDS-ON of transistors by switching the device OFF to ON in just 50µs and monitoring the evolution of the current versus time.
Coupled with our HP-4294A Impedance Analyzer we are able to carry capacitance measurement from 1kHz up to 1MHz under bias voltage up to 3kV.
• This equipment can test components or materials up to voltages of 10 kV for breakdown measurements or 20 A @ 20 V.

→ ADVANTAGES & LIMITATIONS

- High voltage and current are available but power is limited by the setup.



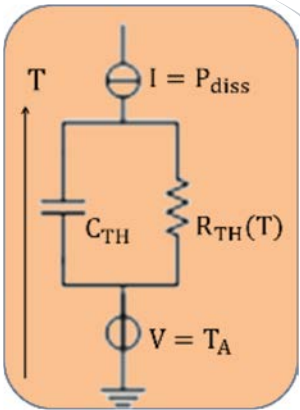
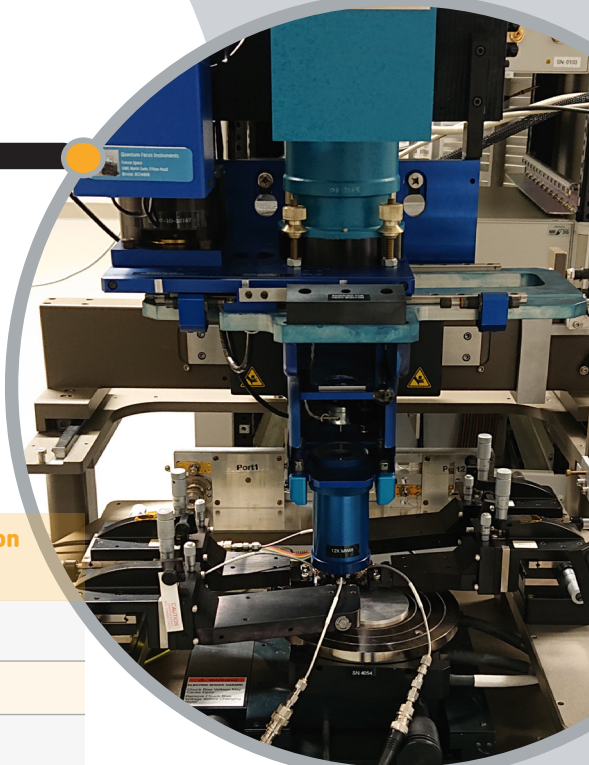
INFRARED MICROSCOPY

Etienne Okada

- MW InfraRed Camera (InSb / 3-5µm) for microscopic temperature measurement
- Measurement range: from room temperature up to 500°C with 0.1°C resolution
- Thermal mapping or transient IR measurement with 3-microseconds rise time resolution
- 3 magnifications:

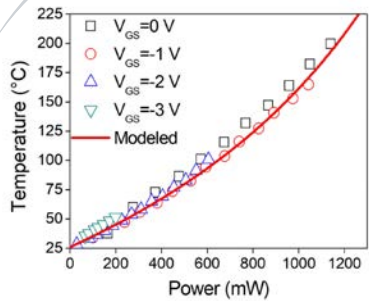
Objectif	Résolution spatiale minimum	Champ de vision (mm²)
*1	36 µm	12.3
*4	10 µm	3.07
*12	3 µm	1.02

- On-wafer measurement available under DC bias and/or RF power

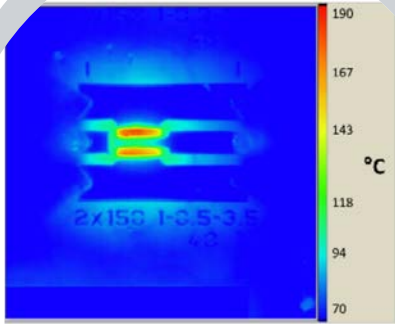


Modeling

Examples



Validation



Measurement

**SIG
MAC
COM**

The SIGMACOM service offers a large set of advanced scientific equipment's for the conception and test of new radio modules communicationsystems, (up to the millimeter wave range) and sensors. We can address wide area single hop or multi-hop networks as well as mixed radio-fiber connectivity for smart devices, implementing edge and near sensor computing to optimize rate, power consumption, reliability and/or latency. This service offers both software and hardware facilities to design, program and test both the analog and digital parts of smart and connected devices, up to 110 GHz. We can for example address the challenges related to IOT, 5G and beyond.

Head of SigmaCom
R. Kassi



- **Analog and digital communication systems** **III. 1-6**
 - Telecom test bench
 - Software-defined radio
 - Multifunctional analog and digital I/O devices
 - Energy efficiency test bench
- **Optical communication systems** **III. 7-8**
 - Optical telecom testbed
 - Optical measurement bench
- **Prototyping** **III. 9-10**
 - Design Modelling
 - Realisations
 - Programmation
 - Tests Mesures

sigmacom-contact@iemn.fr





Real-Time Open Multi user RF communication Test-Bench with Controlled Channel

TELECOM TEST BENCH

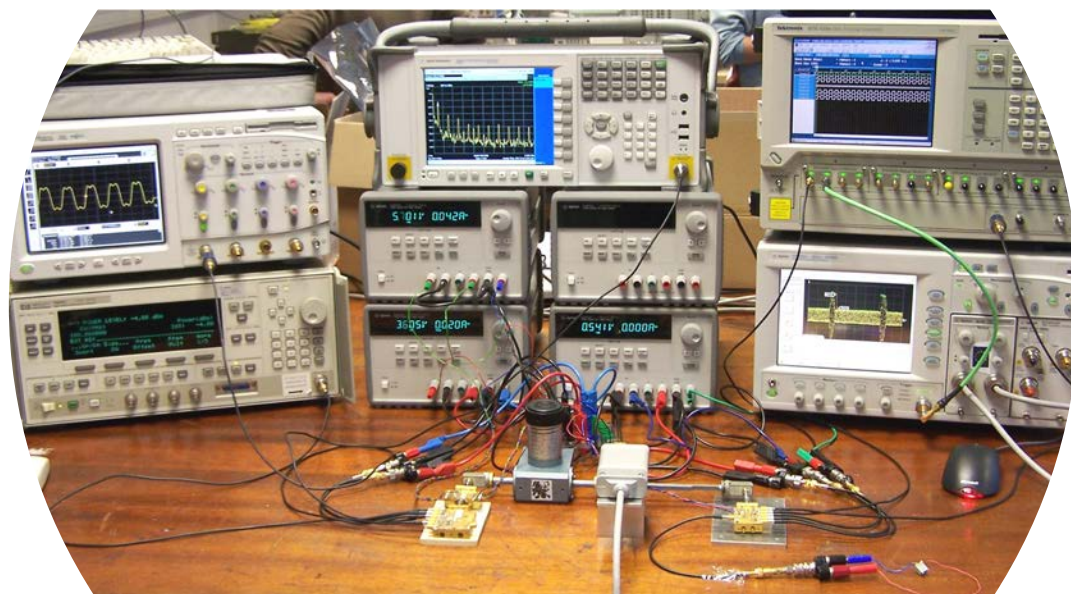
👤 Rédha Kassi

This telecom test bench offers a wide range of state-of-the-art scientific equipment for the characterization of new radio modules and communication systems, covering frequencies up to the millimeter wave range.

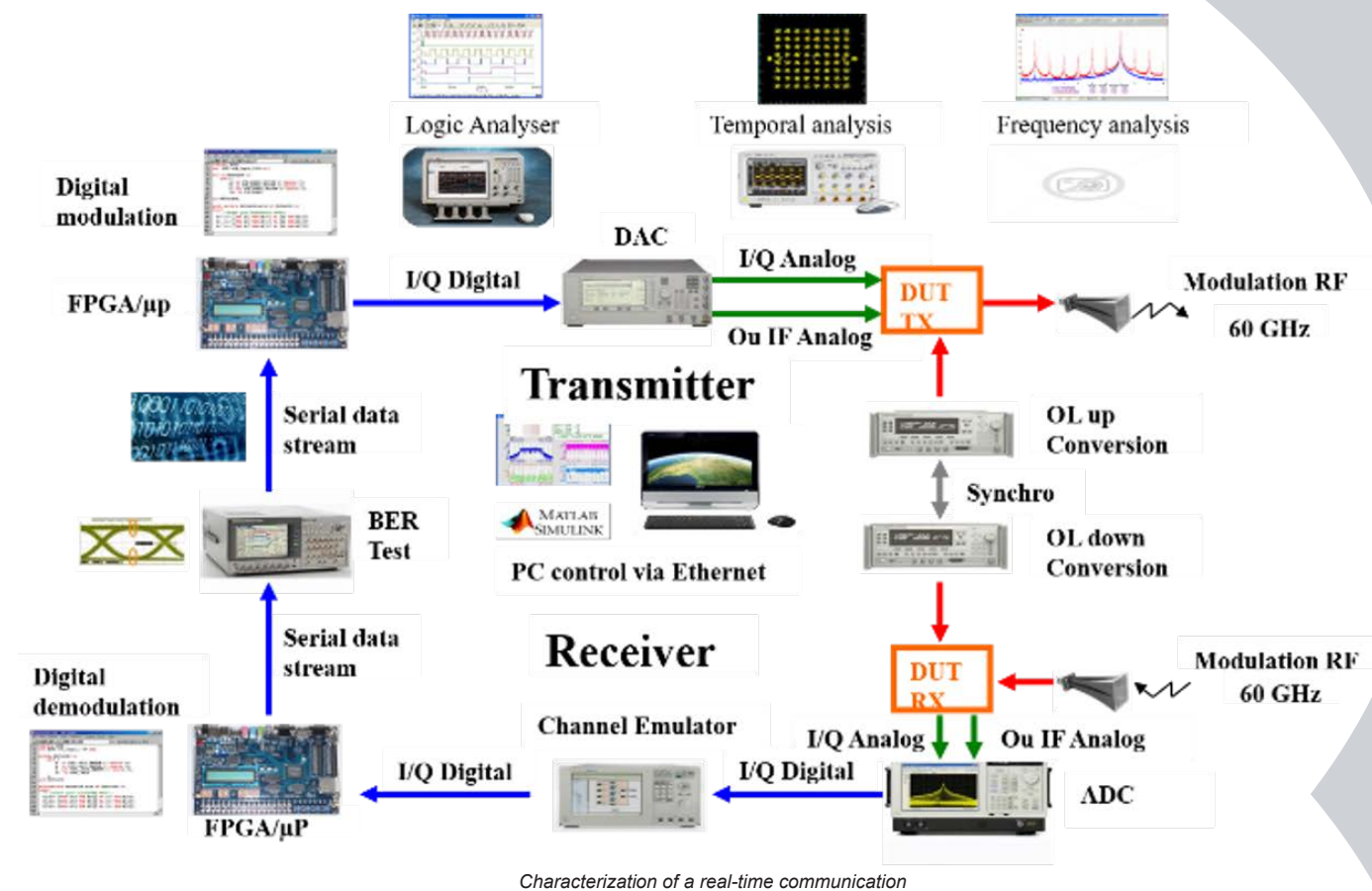
→ APPLICATIONS

- Real-time characterization of a complex transmission and/or reception system, from baseband generation to RF transmission.
- Real-time characterization of a transmission/reception system from demodulation to data recovery with options to analyze RF signal integrity at each channel stage (EVM, channel power measurements, Occupied bandwidth, Modulation accuracy...), digital signal (BERT, PER, eye diagrams, jitter measurements), and mixed signals.
- Characterization of link robustness against real-time RF channel emulation, interference analysis.
- Physical testing of interoperability in heterogeneous sensor networks
- Testing the non-linearity of an amplifier on the communication channel and hard/soft correction.
- Testing frequency and phase synchronization.
- Testing clock accuracy and stability.
- Optimizing transmission packet size and the size of the synchronization preamble.
- Measure component temperature drift and impact on transmission.

Some measurement techniques can be used by the CHOP service for THz communications.



Mixed signal test bench for an UWB-IR communication system operating at 60 GHz



Characterization of a real-time communication

✦ Generation of complex analog, digital or mixed signals:

- Vectorial signals up to 20 GHz with a 1 GHz analog bandwidth
- Arbitrary wave form signals up to 1.25 Gs/s with a 15 bits resolution.
- Arbitrary wave form signals up to 20 Gs/s with a 10 bits resolution.
- Pulse and data up to 3.35 Gb/s
- Frequency synthesizers up to 75 GHz

✦ Time and frequency domain analysis of analog, digital or mixed signals:

- Automatic phase noise test set up (10 KHz - 110 GHz), baseband noise, AM, FM measurement, variance, frequency meter.
- Vectorial signal analyzers up to 50 GHz with a potential 160 MHz analog bandwidth
- Sampling oscilloscopes up to 75 GHz
- Single shot oscilloscopes up to 12 GHz
- Spectrum analyzers up to 110 GHz
- Real time spectrum analyzer up to 14 GHz and 14 bits resolution
- Power meters up to 110 GHz
- Differential vectorial network analyzer (100 MHz- 26.5 GHz) for RF circuits or radio
- Electrical Clock Recovery Module up to 2.5 Gb/s
- Logic analyzers up to 800 Mb/s for each of the 34 channels
- Bit Error Rate Test bench up to 13 Gb/s

✦ Real time modelling for the channel propagation:

Baseband generator and channel emulator (4*2 or 2*4 MIMO Max, 24 multi-paths per channel, Channel BW 120 MHz, Sample rate 150 Msa/s Max)

✦ Real time telecom signal generation and analysis

- modulation and demodulation for cellular (LTE/LTE-Advanced/LTE-A Pro FDD, GSM, GPRS, W-CDMA...) and non-cellular technologies (Wifi, Bluetooth, ZigBee, LoRa, SigFox, RFID...)

✦ Software suite:

- Labview
- signal studio
- 89600 vsa

SOFTWARE-DEFINED RADIO

👤 Rédha Kassi

We offer a range of NI Universal Software Radio Peripherals (USRP) to define Software Defined Radios (SDRs) used for RF applications. These integrated hardware and software solutions enable rapid prototyping of wireless communication systems. NI USRP transceivers can transmit and receive RF signals in multiple bands. The USRP hardware architecture integrates RF analog front-ends (high-low conversion, filters, amplifiers), RF I/Q modulation-demodulation stage, ADCs and DACs, a processor or FPGA connected by wire to a host computer (PC or PXI chassis) for sending, and receiving properly formatted baseband I/Q data. The USRPs are programmed using the LabVIEW development environment. This solution offers great flexibility for software radio prototyping and communications research.

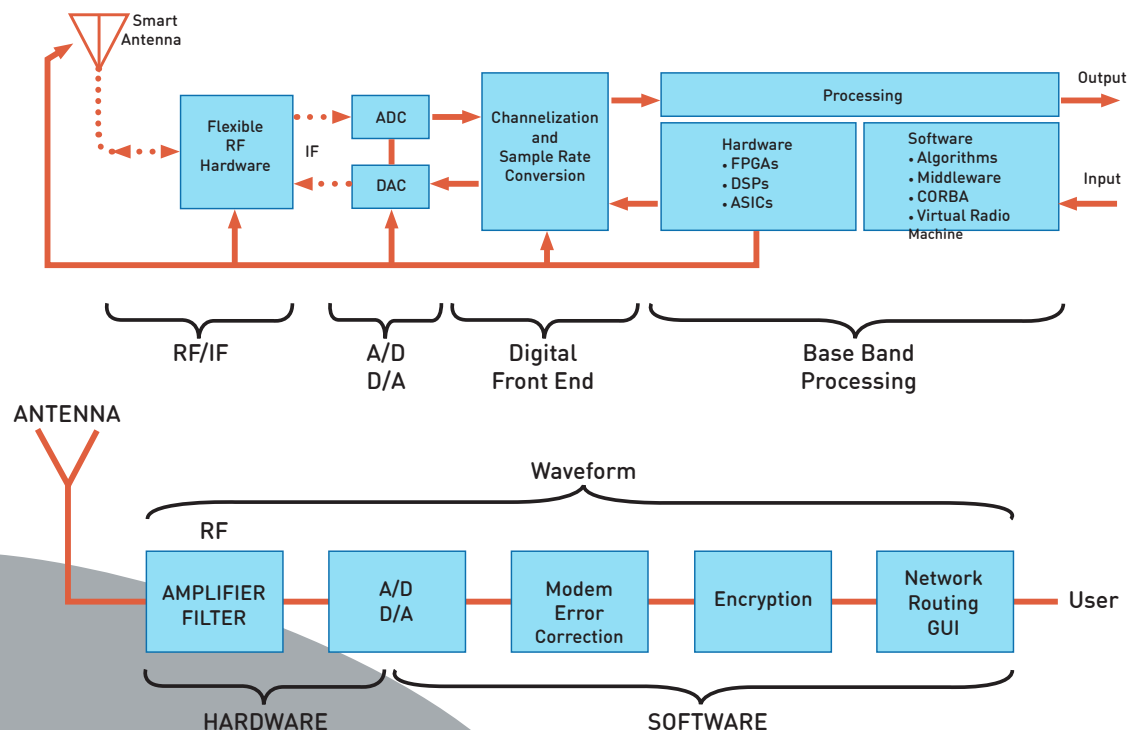
→ APPLICATIONS

The USRP hardware allows a wide range of applications.

- Dynamic access to the RF spectrum and real-time recording of signals over a long period of time.
- PHY and MAC layer research for robustness of radio links.
- Build custom transmission or reception protocols.
- Build multi-standard communication gateways
- Integrate USRP into a standard radio communication network to test new wireless algorithms (TDD, FDD) to improve communications.
- Test channel coding or source coding blocks
- Simulate channel degradation and verify the impact on transmissions.
- Implementing of MIMO technology

Multi-standard communication Gateway

USRP-2954



MULTIFUNCTIONAL ANALOG AND DIGITAL I/O DEVICES

👤 Rédha Kassi

We offer several PXI chassis integrating a controller and different multi-channel I/O modules (analog, digital or mixed) allowing to realize several instruments adaptable for multiple test and measurement applications. The originality of this modular, synchronous, standardized solution is to quickly offer several specific instruments to generate, acquire, store and analyze different signals in a single chassis. The National Instrument programming environment is used to create or use software applications to drive the hardware, process, analyze stored data and/or visualize it in continuous time.

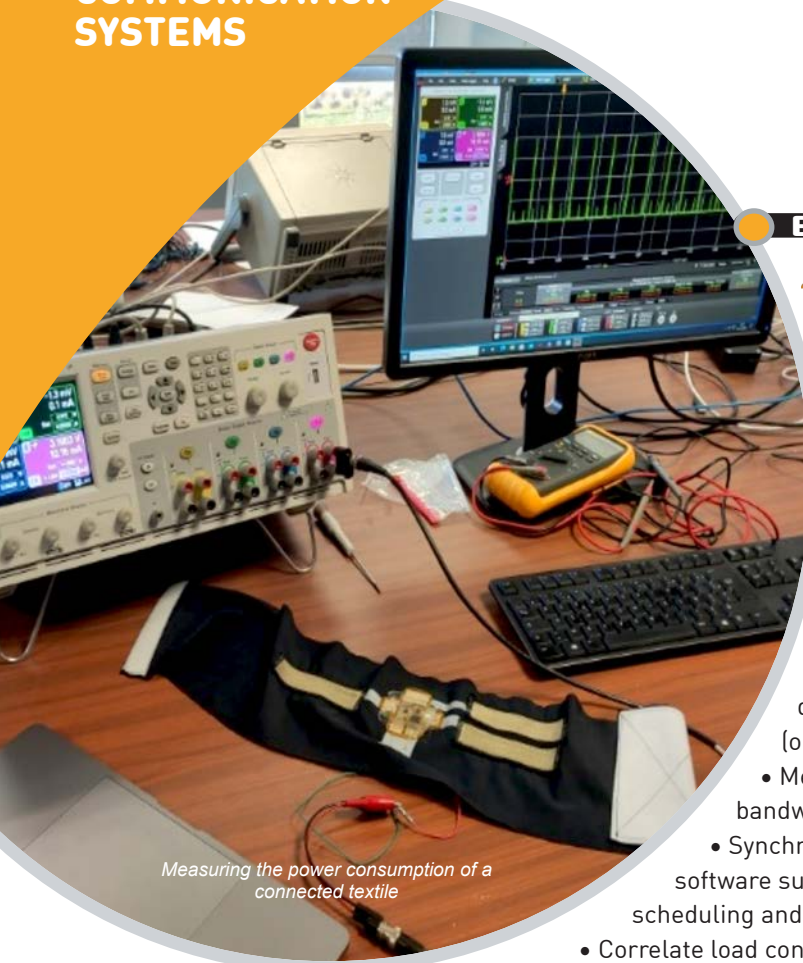
→ APPLICATIONS

- Generation (DAC) and acquisition (ADC) of data and control
- Instrumentation (function generator, AWG, digital signals, oscilloscope, spectrum analyser, ...)
- Wireless communication test (acquisition and real time generation of baseband or IF)

RF test bench

- 16-bit PXI analog output module, 8 channels, 1 MS/s (8 TTL/CMOS 5V digital I/O lines)
- 16 simultaneous 24-bit PXI analog inputs module (204.8 kS/s sampling rate, 114 dB, 4 gains, AC/DC coupled)
- PXIe, 16 AI (16 bits, 1,25 MS/s/ch), 4 AO, 48 DIO, module I/O multifunction
- 100 MHz Bandwidth Transceiver Adapter Module (this module must be combined with a PXI FPGA)
- 200 MHz digital I/O adapter module, 32 LVDS channels (this module must be combined with a PXI FPGA)
- Digitizer adapter module 50 MS/s, 14 bit, 16 channels (digitizer must be combined with a PXI FPGA)

RF Signal Analysis



Measuring the power consumption of a connected textile

ENERGY EFFICIENCY TEST BENCH

 **Rédha Kassi**

This energy efficiency test bench offers the possibility of optimising the energy consumption of communicating objects for IOT, 5G and beyond, by enabling the energy impact of electronic systems to be measured precisely in a controlled environment through the choice of low-power hardware and software architectures.

→ APPLICATIONS

Measure and analyse the power consumed by a system or the sub-systems of a complex object.

- To measure the current and voltage accurately over a wide dynamic range depending on the operating state of the object (on, standby, communication, ...)
- Measure the exact power consumption with sufficient bandwidth not to miss fast digital events.
- Synchronize the power consumption measurement with the software subroutines of the powered object to optimize processor scheduling and maximize the object's battery life.
- Correlate load consumption with RF events and events in the object's sub-circuits.
- Consider the impact of power consumption as a function of RF interference with other wireless devices in a real or controlled environment by combining it with the telecom test bench (influence of channel model, RF disturbance, interferer, electromagnetic pulse, ...).
- Test in difficult electromagnetic environments (C2EM: anechoic chamber, reverberation chamber)

Evaluating the battery characteristics of a device

- Visualize the evolution of the power consumed by an object according to its use and record it over a long period of time in a point file.
- Replay a stored point file to check the performance of a battery and estimate its lifetime.
- Characterize the charge and discharge of a battery over time.
- Analyze statistically (CCDF) the power consumed



Analysis of the energy consumption of a device under test

✚ Device current waveform analyzers

- Widest current measurement range: 100 pA to 10 A
- Capture fast transient effects of spikes with bandwidth up to 200 MHz
- Max sampling rate: 1GSa/s
- Purpose-built low power IoT chip or device characterization

✚ DC power Analyzer and source measure unit

- 20W and 80W power generators
- Measure wide range of current from sub μ A to 8 A and voltage in one pass
- Function as current / voltage source and e-load
- Purpose-built for battery drain analysis
- Long term data logging (up to 200 KSa/s, log current drain up to 1000 h, energy consumption measurements [Ah, Wh, Joules, Coulombs])
- Battery emulation mode
- Meter view (output voltage, current and power)
- Scope view (displays output voltage and current as a function of time)
- Data logger view (hours of measurements with a maximum time resolution of 20 μ s can be logged internal memory or an external USB)
- CCDF (complementary cumulative distribution function) view (quantify the impact of design changes – hardware, firmware or software- on current flows in your design.
- ARB capability (step, ramp, staircase, sine, pulse, trapezoid, exponential, sequence, user defined; max size of 64000 waveform points, max bandwidth of 100 KHz, two quadrant operation)

OPTICAL TELECOM TESTBED

👤 Rédha Kassi



Measurements of an optical transmission

This optical telecom testbed allows the exploration of technologies such as photonic space division multiplexing while combining coherent optical technology with wireless transmissions up to THz to support the insatiable demand for ever increasing data transmission capacity worldwide. This instrumentation test bench is a complex chain of very high speed coherent optical transmission systems that can generate, acquire and analyze the data transmission quality of optical communications systems that allow the

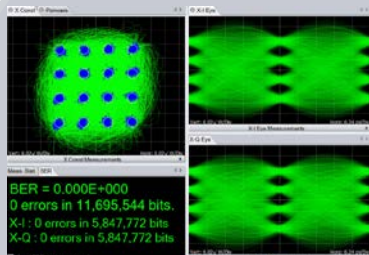
combination of THz radio technologies. A software suite allows the instrumentation to be controlled and the transmission quality to be quantified in terms of BER, EVM and eye diagrams for different modulation standards at data rates up to 512 Gb/s. This bench, located at the IRCICA, is managed by the PHLAM and shared with the IEMN.

The instruments constituting the telecom testbed may also be used individually in experiments with high requirements, such as synchronized acquisition of fast electrical or optical signals (group of sampling oscilloscopes with 4 ATI ports at 70 GHz or 8 ports at 33 GHz); or the generation of complex electrical or optical signals (group of arbitrary function generators with 8 ports at 22 GHz).

→ APPLICATIONS

- Transmission quality (EVM, Q, BER) in optical fiber on optical carrier ;
- In free-space on THz carrier ;
- Coherent modulation formats (N-QAM, 32 Gbaud) ;
- Digital signal processing (DSP, MIMO 4x4) ;
- Shaping and detection of fast optical signals (33 GHz) ;
- Spatial and modal multiplexing.
- Space-time coding
- Implementation of very high speed transmissions on new generation slightly multimode optical fibres using spatial multiplexing such as modal multiplexing to characterise crosstalk.
- Coupling coherent optics technology to wireless transceiver technology in the terahertz range.

• 32 Gbaud 16-QAM optical signal
• EVM = 6.5%

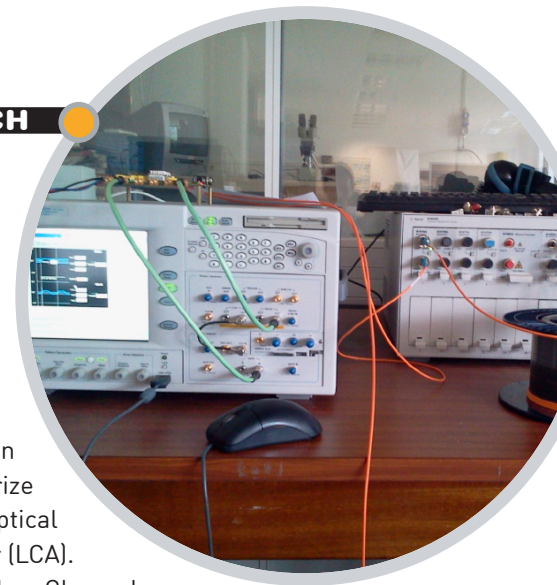


⊕ This transceiver test bench has several instruments:

- Arbitrary Wave Generator (BW up to 15 GHz, 10 bit vertical resolution, DAC 50 Gs/s)
- Instruments for AWG synchronisation (random jitter 315 fs)
- Multi-format coherent optical transmitter and receiver (46 Gbaud BPSK, PM-16 QAM, C or L band lasers or external, Ix, Qx, Iy and Qy base band signals)
- Real time oscilloscope (70 GHz, <7 ps rise time, 200 GS/s sample rate, 100fs jitter noise floor, single-ended 62,5 mv to 300 mv)
- Software generation of RF communication standards
- Display constellation diagrams, EVM, phase eye diagrams, Q-factor, Q-plot, BER,...
- Measures Polarization Mode Dispersion (PMD)
- Coherent lightwave signal analyzer software

OPTICAL MEASUREMENT BENCH

👤 Rédha Kassi



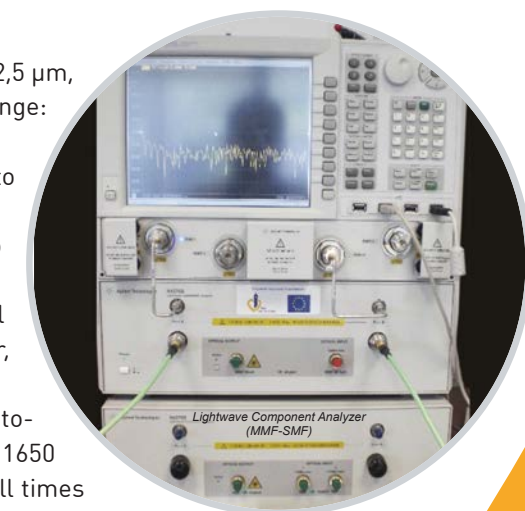
We can generate and analyze optical signals to verify the optical performance of fibers, photodiodes and electro-optical components. S-parameter, optical power and reflectometry measurements can be performed. These instruments are complementary to the optical telecom test bench for radio over fiber or the telecom test bench for communications over fiber.

→ APPLICATIONS

- Fiber radio requires an RF frequency response (from 10 MHz to 26.5 GHz) around an optical wavelength (850 nm, 1550 nm or 1310 nm) in order to accurately characterize an optical transmission chain by measuring the S parameters of electro-optical components (detector diodes, modulators) using a Lightwave Component Analyzer (LCA).
- Basic platform for testing 10 GbE optical and electro-optical components, Fiber Channel FC*8, FC*10, FC*16
- Qualitative analysis of modulated signals with an electrical spectrum analyzer or oscilloscope.

⊕ Lightwave Measurement System:

- Variable Optical Attenuator Module for Multimode Fiber Applications (50 μm and 62,5 μm, input power level up to 27 dBm, at-tenuation range: 0dB to 60 dB, wide wavelength range: 700 nm to 1400 nm)
- Variable Optical Attenuator Module with Angled Interface (attenuation Range: 0dB to 60dB, High Input Power Level: 2W, Wavelength Flatness: < 0.05dB, High Attenuation Accuracy < 0.1dB, Wide Wavelength Range: 1200nm to 1700nm (SMF))
- Reference transmitter for Optical Receiver Stress Test (10MHz to 33 GHz typical electro-optical bandwidth, Optical wavelength 1310 nm & 1550 nm Single Mode Fiber, Operational data rate 622 Mb/s to 14.2 Gb/s, Rise and fall times < 15 ps)
- Reference Receiver is an O/E converter optimized for transceiver loop-back test (Opto-electrical modulation bandwidth DC to 9.3 GHz (typical), Wavelength range 750 nm to 1650 nm, MMF 62.5 μm/125 μm, Operational data rate 622 Mb/s to 12.5 Gb/s, Rise and fall times < 35 ps)
- General Purpose Optical Power Head (Wavelength range 800 nm to 1700 nm, power range 40 dBm to -90 dBm, Low polarization dependence)



⊕ Lightwave Component Analyzer:

- Operation frequency range 10 MHz to 26.5 GHz
- Transmitter and receiver specifications MMF
- Optical input 62.5 μm
- Optical output 50 μm
- Input wavelength range 750 nm to 1650 nm
- Output wavelength 850 nm
- Transmitter and receiver specifications SMF
- Optical input/output 9 μm single mode angled
- Input wavelength range 1250 nm to 1640 nm
- Output wavelength 1310 nm and 1550 nm

PROTOTYPING WORKSHOP

👤 Rédha KASSI 👤 David DELCROIX

Our expertise in prototyping include :

DESIGN: (design new advanced systems)

Systems simulations

- ADS and CADENCE
- Matlab-Simulink- Spice
- TINA
- VHDL

3D electromagnetic simulations

- HFSS
- CST

Data storage and visualization

- InfluxDB
- Grafana

PROGRAMMING: (digital components and systems)

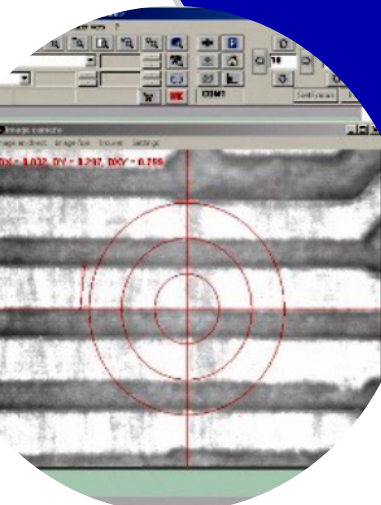
- FPGA (Altera, Xilinx, Actel)
- Microcontroller (AVR, Arduino, ESP32,...), microprocessor (ARM,...)
- Specific Radio (BT, Lora, Zigbee, Wifi , 802.15.4,...)

REALIZATION:

- PCB Design Package TINA
- LDKF PCB ProtoMat H100 fully Automated
Mat. Size 400x360 mm – Resolution 0.25µm – Minimum isolation 0.1mm – Minimum width 0.1mm – Minimum hole diameter 0.15 mm – Automatic 30 position tool changer – Optical fiducial recognition
- Semi-automatic station for SMD assembly
- SMD soldering by reflow furnace

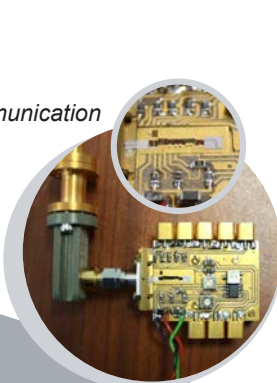
TEST & MEASUREMENT: (functional validation and commissioning, intra and ex-tramural measurement campaign)

- Logical analyzer up to 68 ways 600MHz 4Gs/s (Agilent 16950A)
- Network analyzer 4 ports up to 26.5GHz (Agilent PNAx N5242A)
- Signal analyzer up to 50GHz, Bp real time 160 MHz (Agilent PXA N9030A)
- Vector signal generator, up to 2 GHz, I/Q modulation 1 GHz (Agilent PSG E8267D)
- Data Timing Generator up to 3,35 Gb/s Data rate (Tektronix DTG 5334)
- Arbitrary Waveform Generator up to 20 Gs/s (Tektronix AWG 7102)

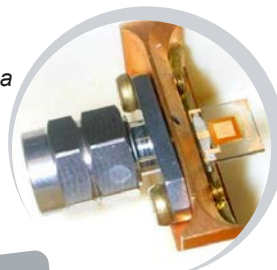


Mechanical engraver for the realization of high frequency circuit boards

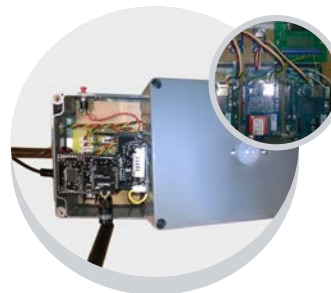
Receiver for an UWB-IR communication system operating at 60 GHz



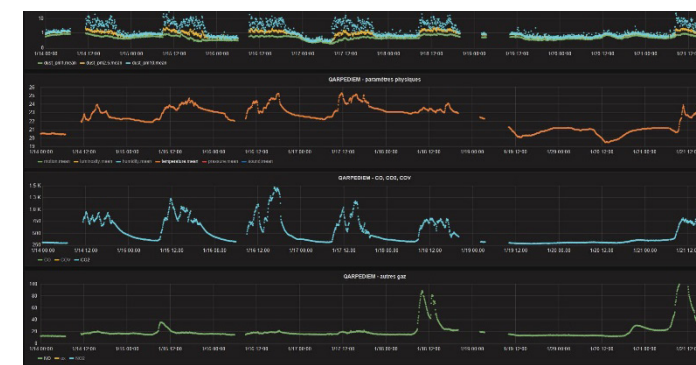
60 GHz Patch antenna



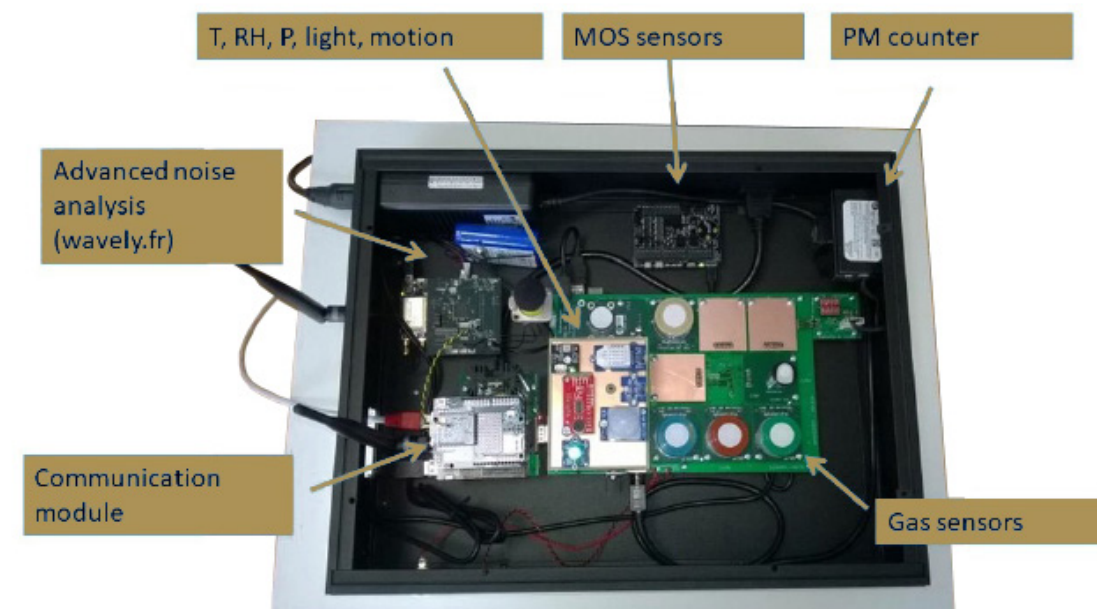
PROTOTYPING
WORKSHOP



Multi-standard IoT gateway



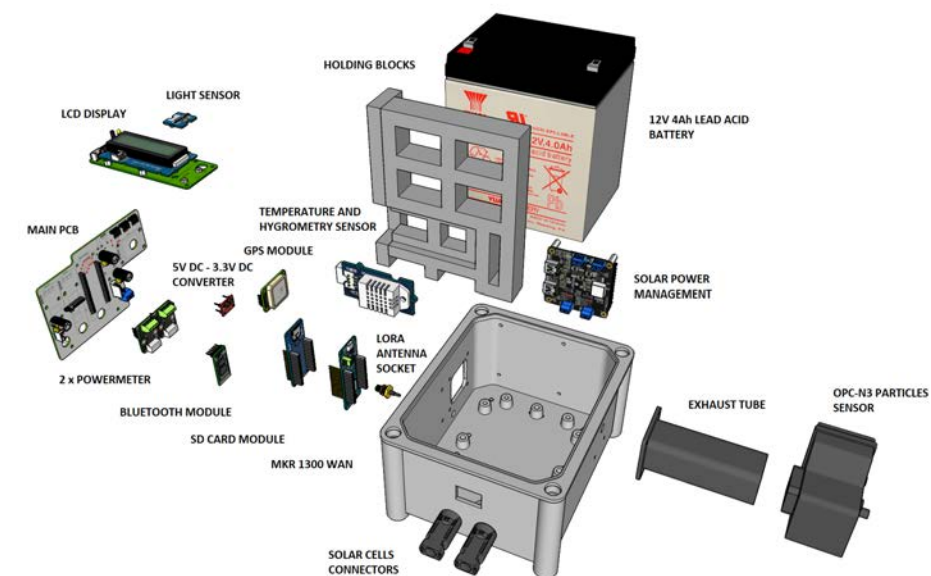
Temporal visualization of data from a sensor node



Embedded instrumentation

→ APPLICATIONS

- Connected objects for IOT
- Embedded instrumentation
- Circuit design, electronic systems for instrumentation
- localization people in the engine rooms of a freight freighter in particularly difficult measurement conditions



Exploded view of a connected object

C 2 E M

The C2EM service is devoted to both Electromagnetic Compatibility (EMC) measurements and, in generic words, to Electromagnetic (EM) characterization in a wide frequency range (few Hz to 20 GHz) with dedicated equipments and instrumentation.

EMC studies / EM interactions between electronic/electrical equipments and their functioning environment. The aim is to ensure that such equipments will operate correctly both with a sufficient level of EM immunity against external sources and without generating EM emissions susceptible to disturb communication systems.

EM characterization concerns all EM measurements (e.g antennas characterization) requiring a standard 'quite' site and the on-site measurements such as the telecom propagation channels characterization.

The service gathers in a same area of 180 m² various measurement's chambers and cells, each of them attempting to represent a certain EM environment required for research and EMC testings.

1. Radio Frequency Anechoic Chamber (RF-AC): 6m x 6m x 2.8 m
2. Transverse ElectroMagnetic Cell (TEM-cell) : 2m x 1m x 0.6 m
3. Mode Stirrer Reverberation Chamber (MSRC), 5.6m x .4m x 2.8 m

Head of C2EM
P. Laly



- **EMC chambers and cells** IV. 1-2
 - Radio frequency anechoic chamber (RF-AC)
 - Transverse electromagnetic cell (TEM-cell)
- **EM site characterization** IV. 3-4
 - Mode stirrer reverberation chamber (MSRC)
 - Transfer impedance (ZT) bench test
- **Massive multiple input multiple output system acquisition (MaMIMOSA)** IV. 5-6
- **Electronic prototyping and realisation Lab**
 - Realisations
 - Programmation
 - Tests Mesures V. 7-8

c2em-contact@iemn.fr



RADIO FREQUENCY ANECHOIC CHAMBER (RFAC)

Pierre Laly

The actual RFAC consists in a 137m³ shielded room whose internal walls are covered with radio-frequency (RF) absorbing foams. It is intended to represent a standard free space propagation environment with known properties. The geometrical dimensions and the electromagnetic characteristics of the absorbing materials limit the bandwidth of the chamber, in particular in the lower frequency range. This chamber is devoted to ElectroMagnetic Compatibility (EMC) testing

and to all electromagnetic (EM) characterization requiring quiet EM environment (e.g. for antennas radiation pattern and gain assessments). According to the application, the frequency range is from 30 MHz up to 18 GHz. For EMC purpose, the chamber meets the basic EMC requirements in terms of field uniformity and site attenuation for a 3 meters testing. Therefore, it is quite usable for EMC pre-compliance testing according to European and to some military and aeronautic EMC standards, for radiated immunity and emission.

To ensure its functioning, the following instrumentation is available:

- Spectrum Analyzer RS FSV30 (10 Hz -30 GHz)
- VNA RS ZVA 24 (10 MHz -24 GHz)
- Synthesized RF generator (10 MHz -20 GHz, 10 dBm)
- Turntable table
- Broad band antennas (30MHz -18 GHz) : bi-conical, log-periodic, double ridge
- Broad band amplifiers: 30W (1 MHz-1 GHz), 25W (800MHz-4 GHz)
- Broad band Electric field probe (100 kHz-6 GHz), E-field max 200V/m

→ ADVANTAGES & LIMITATIONS

- ⊕ High EM isolation against EM disturbances (90 dB min @1GHz),
- ⊕ Standard plane waves environment
- ⊖ Low frequency limitation for antennas characterization (Fmin=200 MHz),
 - ⊖ Size limitation, e.g. 5 m distance max available for RFID tags characterization
 - ⊖ Height scanning limited (1.2m to 1.80m) for EMC testing

→ MAIN EMC APPLICATIONS

- Radiated emissions and radiated immunity characterisation of electronic/electric equipments,
- Shielding effectiveness measurement of flat materials,
- Experimental validation of EMC numerical models

→ OTHER APPLICATIONS

- Characterisation of RFID (Radio Frequency Identification) tags performance (860 -950 MHz),
- Characterisation of antennas arrays (radiation pattern, gain, antenna factor),
- Experimental validation of antennas numerical models



TRANSVERSE ELECTROMAGNETIC CELL (TEM CELL)

Pierre Laly

The TEM cell is a shielded strip line like a tapered transmission line (TL) of rectangular cross-section with a flat inner conductor (septum). It is intended for establishing standard uniform EM field in the low frequency range ($f < 30$ MHz) where RF-AC and MSRC are not functioning. The cell geometry is designed to give a 50 Ω characteristic impedance for the TL. Within the working volume (under the septum), the fields are those of a plane wave as far as the fundamental TEM mode remains dominant. The cell operates from DC to an upper frequency such that high order modes excited in the cell remain negligible compared to the TEM mode. Therefore, the maximum frequency of measurement depends on the dimensions of the cross-section of the cell and of the size of the device under test (DUT).

The TEM cell constitutes a powerful experimental tool which enables various experiments in EMC domain for the study of EM fields coupling phenomenon to cables and PCB traces.

To ensure its functioning, the following instrumentation is available:

- Spectrum Analyzer RS FSV30 (10 Hz -30 GHz)
- VNA Agilent E8733 (30 kHz-6GHz)
- Synthesized RF generator (10 kHz -1 GHz, 13 dBm)

→ MAIN EMC APPLICATIONS

- Measurement of radiated emissions and susceptibility of embedded electronic devices,
- Characterisation of the EMC behaviour of partially shielded cables for aeronautic applications,
- Calibration of electrically small size E and H-field probes,
- Study and validation of numerical models of the EM coupling to cables

→ Complementary with other techniques present at IEMN : Pole SigmaCom for HF RFID tags characterization

→ ADVANTAGES & LIMITATIONS

- ⊕ Standard plane wave environment at low frequency
- ⊖ High frequency limitation (e.g. 100 MHz for our TEM-c)



MODE STIRRER REVERBERATION CHAMBER (MSRC)

Pierre Laly

In contrast with the RFAC (Radio Frequency Anechoic Chamber), the MSRC is a very complex of high Q-factor measurement tool intended to simulate realistic EM environments such as that encountered by electronic devices in large screened boxes, aircrafts, automotive vehicles, etc.

The MSRC consists in an electrically large chamber with highly conducting walls. The lowest working frequency (LWF) of a MSRC is such that its wavelength is smaller than the smallest dimension of the chamber. A MSRC is equipped with a metallic paddle (the stirrer) which can be moved by means of a continuous or stepped motor. Physically, a MSRC acts as an oversized cavity in which a high number of resonant modes can be excited around any

frequency higher than the LWF. Thus, the rotation of the stirrer allows achieving different boundary conditions, and consequently, it generates a complex EM environment with randomly distributed field in amplitude, phase and polarisation. However, far from the wall > than a quarter of wave length, the fields remain in average, statistically uniform and isotropic within the chamber. Consequently, all the physical quantities (e.g. E-field, power, etc) are measured as averaged values of sets of data collected when the stirrer is moving. Uniformity and isotropy properties are checked through a normalized calibration procedure based on the standard deviation (STD) of E field samples acquired at different locations in the chamber. Due to the high Q-factor, high field level can be achieved with low input power

To ensure its functioning, the following instrumentation is available:

- Spectrum Analyzer RS FSV30 (10 Hz -30 GHz)
- VNA RS ZVA 24 (10 MHz -24 GHz)
- Synthesized RF generator (10 MHz -20 GHz, 10 dBm)
- Broad band antennas (30MHz -18 GHz) : log-periodic, double ridge
- Broad band electric field probe (100kHz – 6 GHz)

→ MAIN EMC APPLICATIONS

- Measurement of radiated emissions and susceptibility of electric/electronic equipments
- Characterisation of the shielding effectiveness of flat materials, shielded cables and connectors

→ OTHER APPLICATIONS

- Characterisation of RFID (Radio Frequency Identification) tags radiation efficiency
 - Emulation of telecom multipath propagation channel
 - Emulation of diffuse environment for assessing human body specific absorption rate

→ Complementary with other techniques present at IEMN : Pole SigmaCom, CHOPE

→ MSRC is an alternative EMC testing site to RFAC

→ ADVANTAGES & LIMITATIONS

- Low cost equipment v.s RFAC
- High Q (quality) factor environment enabling high level of E- field inside the chamber with low power amplifier.
- Low insertion losses v.s free space and RFAC
- Spatial homogeneity of the field over the working volume
- No need of changing antennas polarization and using turntable table when performing EMC testing.
- Capability for measuring the total isotropic power radiated by an equipment
- Loss of antennas directivity,
- Need of rotating the stirrer during any measurement



TRANSFER IMPEDANCE (ZT) BENCH TEST

Pierre Laly

In EMC problems, cables play an important role both in the radiation and in the susceptibility phenomenon of the equipments they interconnect. When the cables are shielded, their EMC performance is generally evaluated, (depending on the field of application), either by a measure of the shielding effectiveness or by measuring a well-known parameter: the transfer impedance denoted Z_t .

The IEMN staff TELICE is pioneer in studying Z_t measurement's methods. The Z_t bench test used in C2EM service as been studied and constructed according to IEC (International Electrotechnic Commission) requirements.

→ APPLICATIONS

- Transfer impedance and shielding effectiveness measurement of shielded cables and connectors

→ ADVANTAGES & LIMITATIONS

- Wide frequency range (few kHz to 2 GHz),
- High sensitivity (e.g. $0.1 \mu\Omega/m$) in low frequency range (few kHz to 30 MHz)
- Low frequency sampling above 100 MHz





MASSIVE MULTIPLE INPUT MULTIPLE OUTPUT
SYSTEM ACQUISITION (MAMIMOSA)

Pierre Laly

Channel sounder MIMOSA (Multiple Input Multiple Output System Acquisition) real-time MIMO (16Tx, 16Rx) and Massive MIMO (64Tx, 16Rx) channel analyzer. The actual model can operate from 1.3 GHz until 10 GHz. Two frequencies are available for now, 1.35GHz and 5.89GHz with 80MHz bandwidth. The sounder is based on numerical processing by FPGA coupled at a computer for data recording.

MaMIMOSA is based on space-frequency division multiplexing, giving a large possibility of tone and antenna allocation. This channel sounder belongs to the new generation of software radio design based systems. The architecture of proposed approach was designed with the highest flexibility thus opening a wide range of applications. In addition, the channel sounder has been built to avoid heavy post-processing: i) the Tx signal is pre-processed to include the non-linearity of the Tx and Rx chain, ii) Thanks to the high sampling frequency of the FPGA, a real digital baseband signal is transmitted to the RF chain avoiding I/Q impairment, iii) the output file gives the 4.Ntx.Nrx transfer function in a versatile binary format. Finally, the power consumption of the sounder is low and can be powered with a 24 V battery with a 8 hours autonomous.

→ MAIN APPLICATIONS

- Real-time propagation channels characterization in indoor,
- Real-time propagation channels characterization in mobility context (such as vehicular, aerial, ship, etc.),

→ OTHER APPLICATIONS

- Cybersecurity,
- Staff fall detection in a confined environment (e.g. ship)
- Localization in a complex environment (e.g. forest)
- Test of new communications techniques (5G, 6G, etc

→ Complementary with other techniques present at IEMN : Pole SigmaCom

→ ADVANTAGES & LIMITATIONS

- ✦ Real Time
- ✦ Flexibility
- ✦ Low post-processing
- ✦ “Mobile”
- ✦ New filters for new frequencies,
- ✦ Mobile but need to adapt to the new environment.



Signal in Baseband		Radio Frequency	
• Multiplex • Used sub carrier • Outputs • N subcarrier / output • Delta frequency • Symbol duration	IFDM 6560 8 820 97.7 kHz 81.92 μs	• Frequencies • Bandwidth • NTx (switched mode) • Power / Tx • NRx • AGC Dynamic	1.35 GHz / 5,89GHz 80 MHz 8 (16 ou 64) 1 to 100 mW 16 63 dB
Sounding characteristics			
• CIR* • Max CIR*	10.24 μs 50 M	- CIR Resolution - Matrix H(16,16,1024) - Matrix H(16,64,1024)	12.5 ns 1 Mo 4 Mo

Manufacturer: IEMN/Telice/Univ. Gent

PROTOTYPING WORKSHOP

The electronic study and realization lab is equipped with all the instruments necessary for the design realization and testing of electronic prototypes. For circuit board realization, it is composed of:

Autodesk Eagle and Fusion 360

- Schematic with Electrical Rule Check
- Board with Design Rule Check
- ECAD-MCAD co-design process

LPKF PCB milling machine ProtoMat S63

- Mat. Size 229x305mm
- Resolution 0.5µm
- Automatic tool change
- Minimum isolation 0.15mm
- Minimum width 0.15mm

LPKF ProtoLaser H4

- Mat. Size 305x229x7mm
- Résolution 1µm
- Automatic tool change for drilling
- Minimum isolation 30µm
- Minimum width 50µm (tested)

LPKF Multipress-II (multi-Layer)

- Up to 6 layers

LPKF MiniContact RS

- Max. material size (X x Y) 230 mm x 330 mm (9" x 13")
- Max. layout area (X x Y) 200 mm x 300 mm (7.8" x 11.8")
- Reverse pulse plating Adjustable
- Tolerance $\pm 2 \mu\text{m}$ (0.08 Mil), copper coating
- Minimum hole diameter $\geq 0.2 \text{ mm}$ (8 mil)
- ViaCleaner Included
- Chemical tinning Included

All necessary for the placement and soldering.

Advantages :

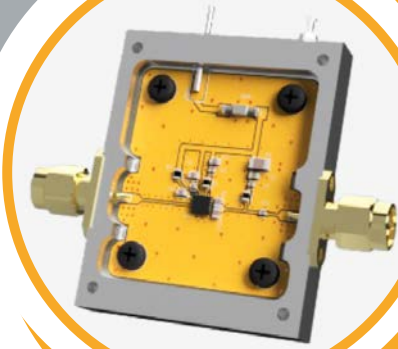
- Fast prototyping
- Metallization
- Quick test in situ
- Up to 6 layers

Disadvantages, limits :

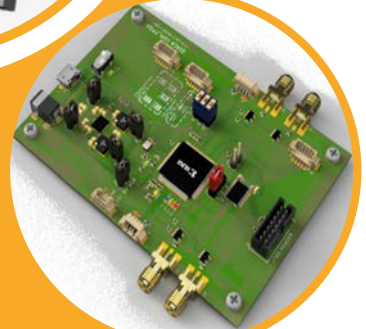
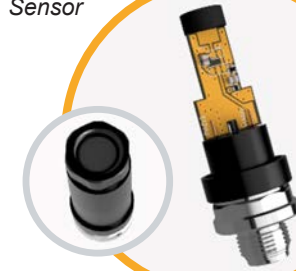
- Long time for multi-layer pcbs

PROTOTYPING WORKSHOP

RF 1W 6GHz
Power Amplifier



Embedded Sound
Sensor



FPGA Card Development
for a communication
system

For the electronic devices testing, the following instrumentation is available :

- 2GHz portable Oscilloscope (Lecroy WaveRunner 204 Xi)
- 13GHz 4 ways (40GS/s) lab Oscilloscope (Lecroy WaveMaster 813Zi)
- Logical analyzer 18 ways 500MHz 2Gs/s (Iecroy MS-500)
- Network analyzer 4 ports 8.5GHz (Agilent A5071)
- Signal analyzer 44GHz (Agilent PXA N9030A)
- Synthesizer 44GHz (Agilent E8257D)



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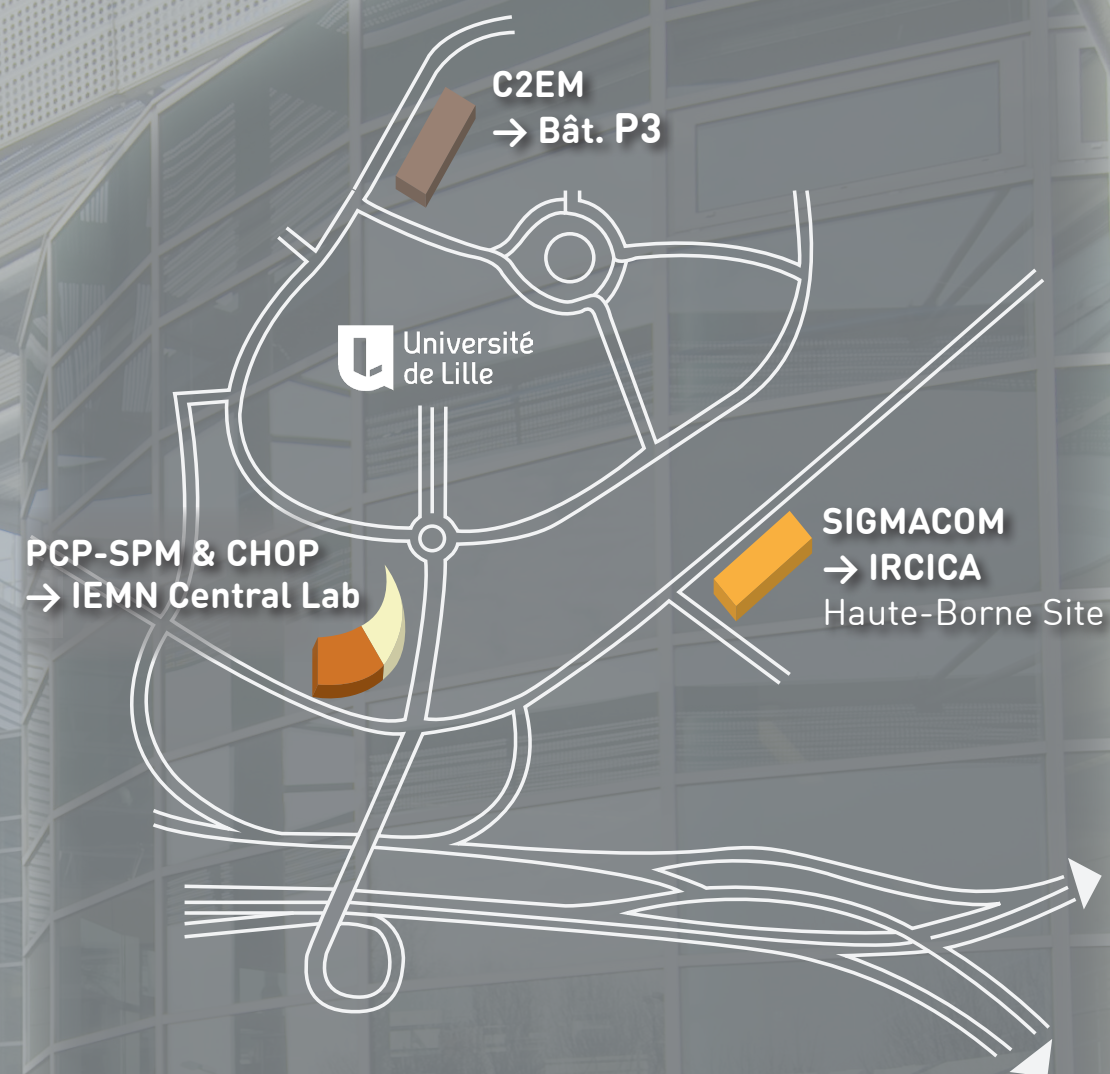
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- EQUIPEX NANOFUTUR



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